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CAD Note:
Default component footprint is
SMD 0201, X5R, 1% resistors.

Property: BUILD-OPT
DNP = Do Not Populate

DBG_S - Replace with board short for MP
DBG_R - Replace with lower cost component for MP
DBG_N - Install for Non-Debug Builds
DBG_D - Remove from BOM (Depopulate) for MP
DBG_T - Used for Telemetry in MP as needed
DBG_TS - Used for Telemetry in MP as needed. This part
needs to be replaced with a short if telemetry is not
needed.

<Variant Name>

Title: Table of Contents		
Engineer: <OrgAddr1>		
Size A3	Project Name CHARIOT	Rev 1.00
Date: Thursday, August 03, 2017		
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Schematics Change History

[illegible]

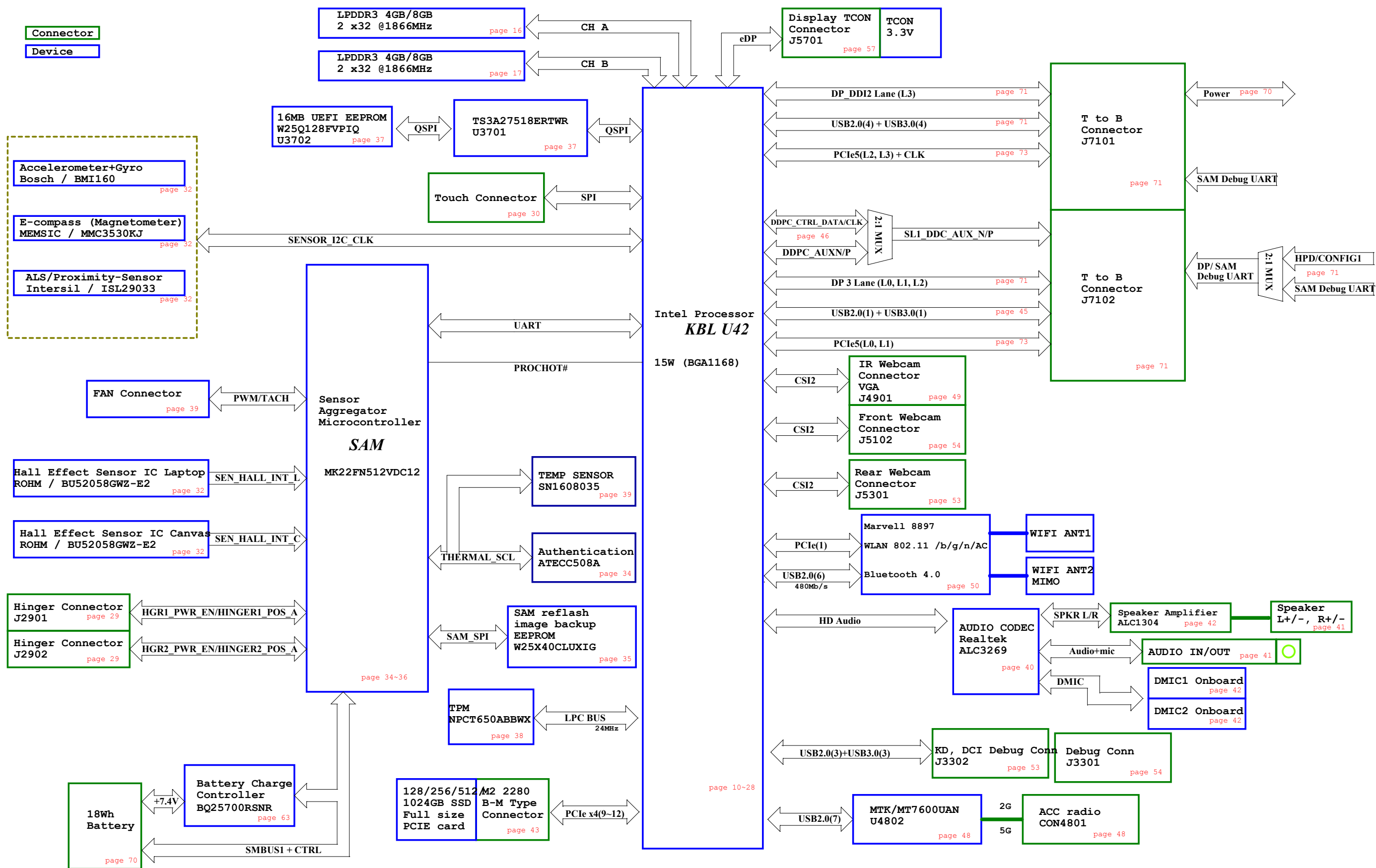
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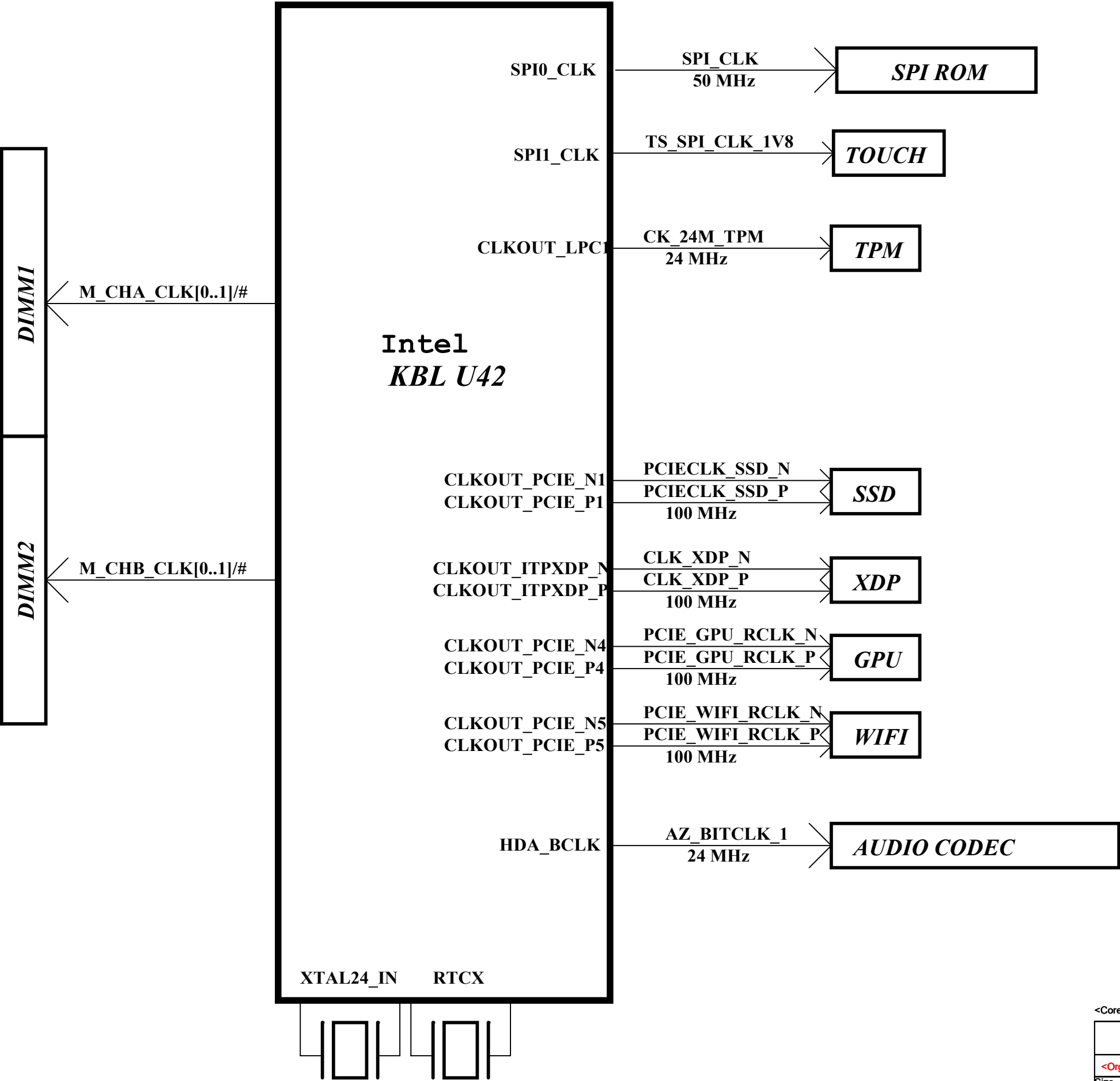
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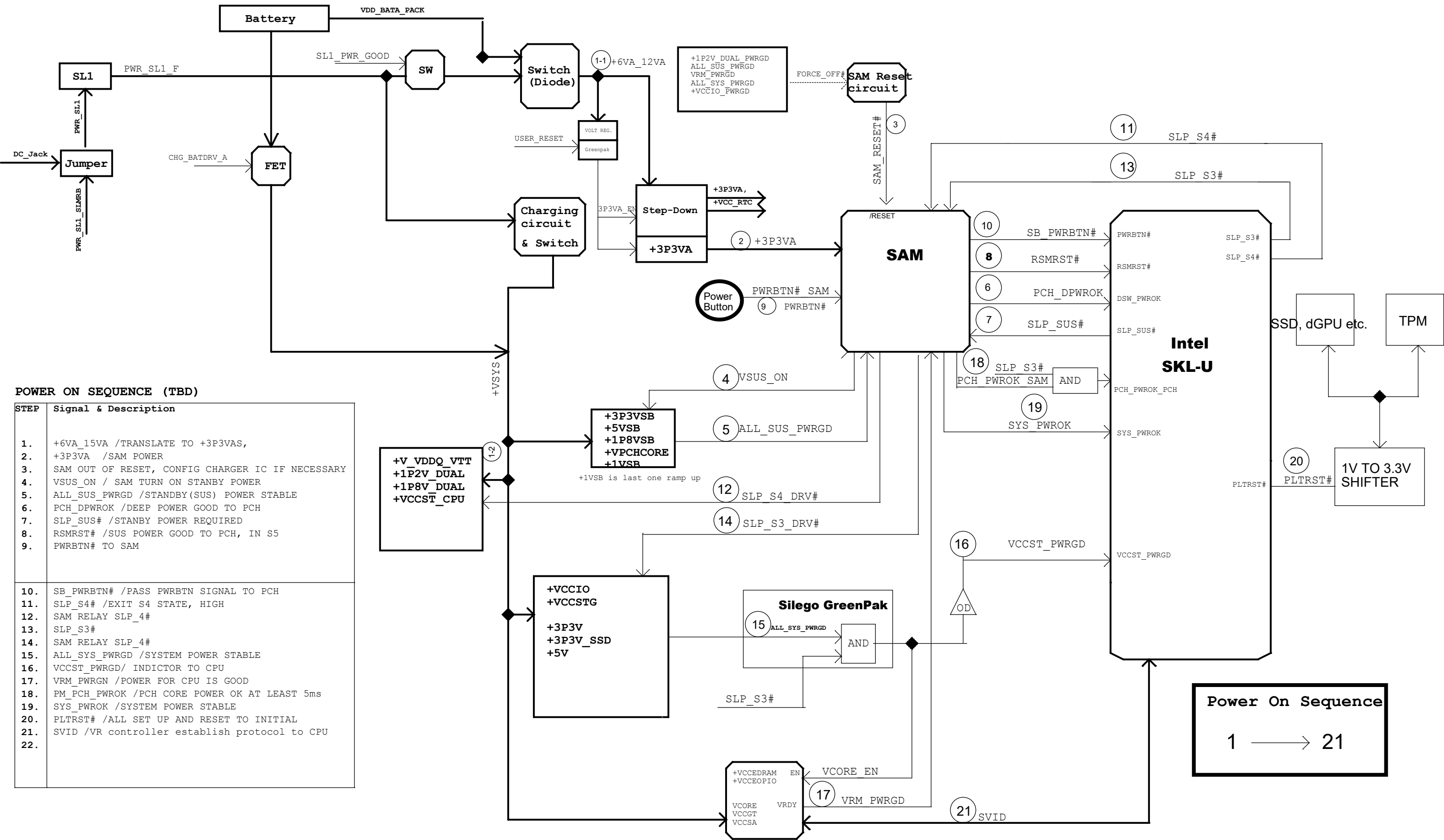
Property: BUILD-OPT
DNP = Do Not Populate

```
DBG_S - Replace with board short for MP
DBG_R - Replace with lower cost component for MP
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DBG_TS - Used for Telemetry in MP as needed. This part
needs to be replaced with a short if telemetry is not
```

<Core Design>			
		Title: CHANGE HISTORY-2	
		Engineer: <OrgAddr1>	
Size A3	Project Name CHARIOT	Rev 1.00	
Date: Thursday, August 03, 2017	Sheet 2	of 76	







POWER ON SEQUENCE (TBD)

STEP	Signal & Description
1.	+6VA_15VA /TRANSLATE TO +3P3VAS,
2.	+3P3VA /SAM POWER
3.	SAM OUT OF RESET, CONFIG CHARGER IC IF NECESSARY
4.	VSUS_ON / SAM TURN ON STANBY POWER
5.	ALL_SUS_PWRGD /STANDBY(SUS) POWER STABLE
6.	PCH_DPWROK /DEEP POWER GOOD TO PCH
7.	SLP_SUS# /STANBY POWER REQUIRED
8.	RSMRST# /SUS POWER GOOD TO PCH, IN S5
9.	PWRBTN# TO SAM
10.	SB_PWRBTN# /PASS PWRBTN SIGNAL TO PCH
11.	SLP_S4# /EXIT S4 STATE, HIGH
12.	SAM RELAY SLP_4#
13.	SLP_S3#
14.	SAM RELAY SLP_4#
15.	ALL_SYS_PWRGD /SYSTEM POWER STABLE
16.	VCCST_PWROK/ INDICTOR TO CPU
17.	VRM_PWRGN /POWER FOR CPU IS GOOD
18.	PM_PCH_PWROK /PCH CORE POWER OK AT LEAST 5ms
19.	SYS_PWROK /SYSTEM POWER STABLE
20.	PLTRST# /ALL SET UP AND RESET TO INITIAL
21.	SVID /VR controller establish protocol to CPU
22.	

Power On Sequence

1 ———> 21

	15W SOC (CPU SKYLAKE-U)
+VCORE	-> 29A
+VCCGT	-> 56A (GT2e)
	-> 62A (GT3e)
+VCCSA	-> 5. 1A
+VCCIO	-> 3. 1A
+VCCEDRAM	-> 3A (GT3e)
+VCCEOPIO	-> 3A (GT3e)
+VCCST_CPU	-> 0. 24A
+VCCPLL_OC	-> 0. 26A
+DDR_V	-> 2A
(+1P2V_DUAL)	(PCH)
+VCCST	-> 0. 04A
+VCCSTG	-> 0. 04A
+1V_MODPHY	-> 2. 766A
+1VSB	-> 0. 782A
+VPCHCORE	-> 3A
+1P8VSB	-> 0. 5A
+3P3VSB	-> 0. 6A

	LPDDR3
+1P8V_DUAL	-> 0.717A
+1P2V_DUAL	-> 3.5A
+V_VDDQ_VTT (0..6V)	-> 1A

	SSD (PCIe/mSATA)
+3P3V	-> 2.5A

	EC
+3P3V_EC	-> 0.0375A

+3P3V_EC	EC ROM
	-> 0.015A

	Temp sensor (STTS751)
+3P3V_EC	-> 0.0005A (2PCS)

	TPM(Infineon SLB9665 ESS2)
+3P3V_TPM (+3P3V)	-> 0.1A

	WiFi&BT
+3P3V_WWAN	-> 1.5A

	DMIC
DMIC_+3P3V/+3P3V_AUDIO	-> 0.02A

	FAN
+5V_FAN	-> 0.7A

	UEFI_SPI_BIOS_ROM
+3P3V	-> 0.04A

	Panel
VCC_EDP_BKLT_IN	-> 0.12A (30V)
+3P3V_PANEL	-> 1.5A

	Touch Interface
+1P8V_TS	-> 0.452A
+5V_TS	-> 0.22A

	ALC298 CODEC
+5V_AUDIO	-> 1.05A
+1P8V_AUDIO	-> 0.4A

	DSP ALC5677
+1P8V_AUDIO	-> 0.1A

	Camera REAR
+1P2V_CAM_R	-> 0.2A
+1P8V_CAM_R	-> 0.001A
+2P8V_CAM_R	-> 0.048A
+3P3V_VCM	-> 0.125A
+3P3V (LED)	-> 0.005A
	Camera FRONT
+1P8V_CAM_F	-> 0.096A
+2P8V_CAM_F	-> 0.06A
+3P3V (LED)	-> 0.008A

	Sensor uC (MKL17Z256VMP4)
+3P3VA	-> 0.001A

	SL1
+3P3V_HPD	->0.075A

	ACT_BOARD
+3P3VSB	->2A (LEFT+RIGHT)

	Hall effect sensor (BU52058GWZ-E2)
+3P3VA	->0.0028A

	Compass (MMC3416XMA)
+3P3V_SENSOR	->0.0012A

	Acceleromte&Gyro(BMI160)
+3P3V_SENSOR	-> 0.001A

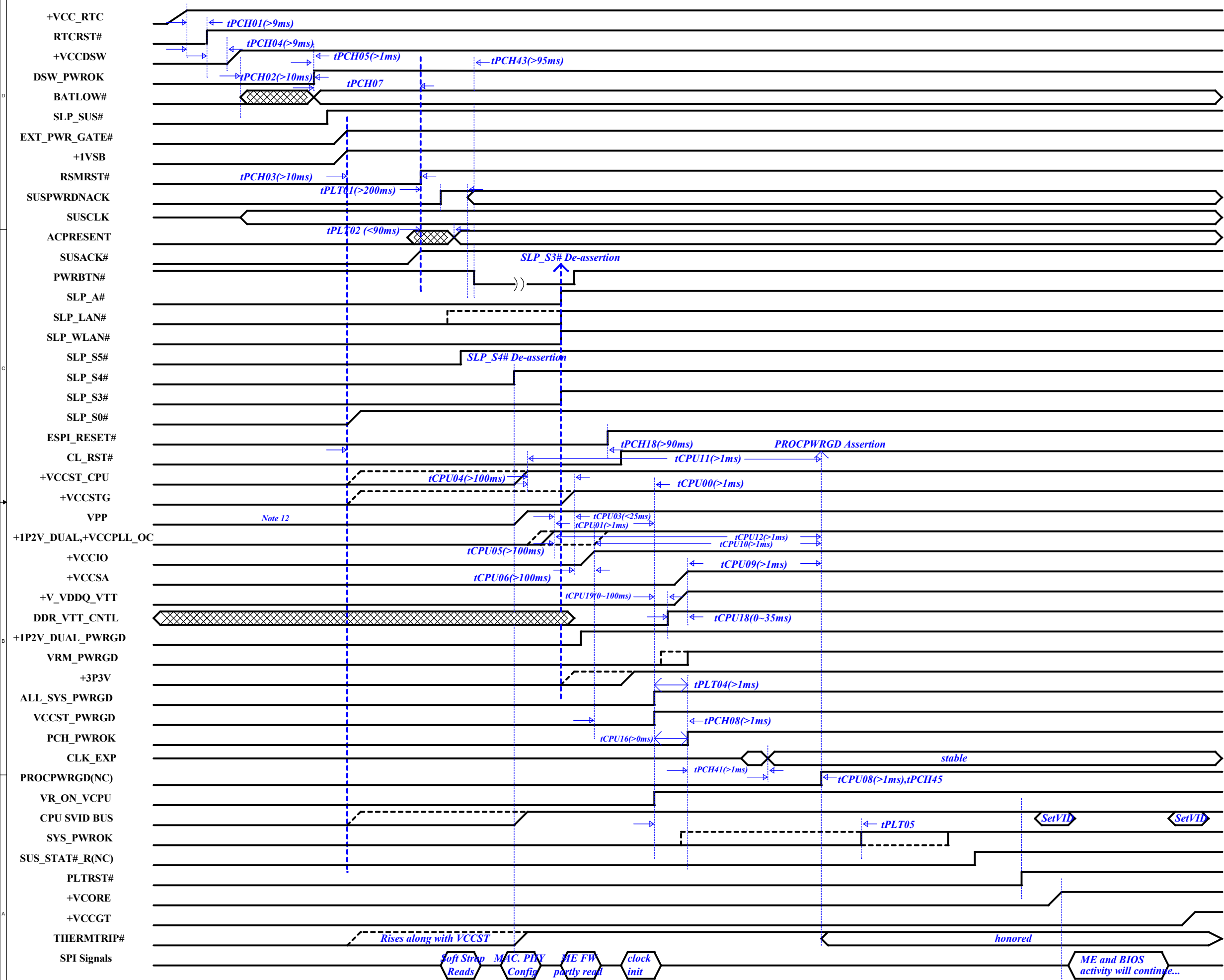
	ALS (ISL29033IROZ-T7)
+3P3V_SENSOR	-> 0.000075A

	MUX
+3P3V_MUX	-> 0.0033A

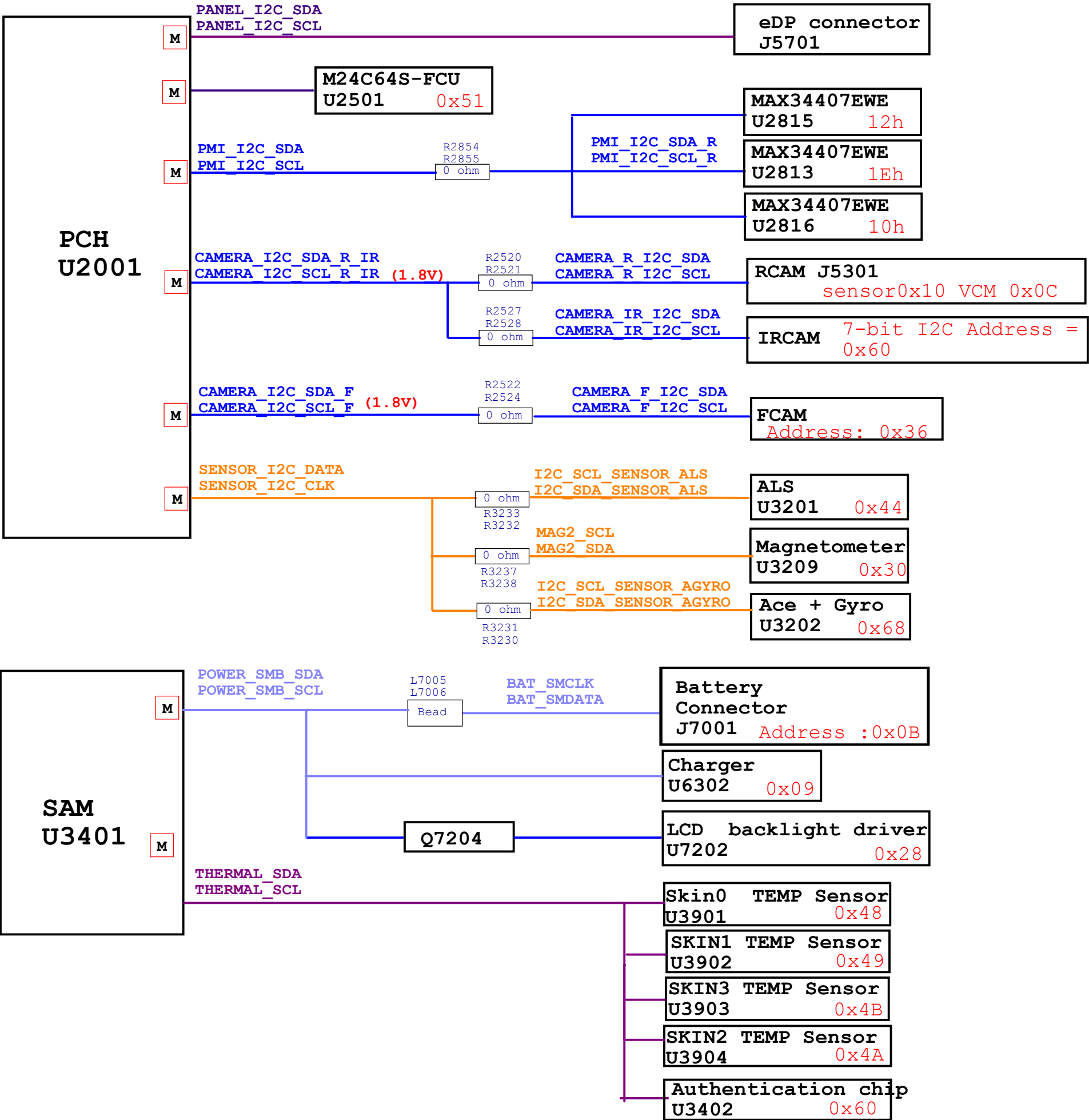
	mini DP
+3P3V	-> 0.5A

	Battery Charger BQ24735
+6VA_12VA	-> 0.003A

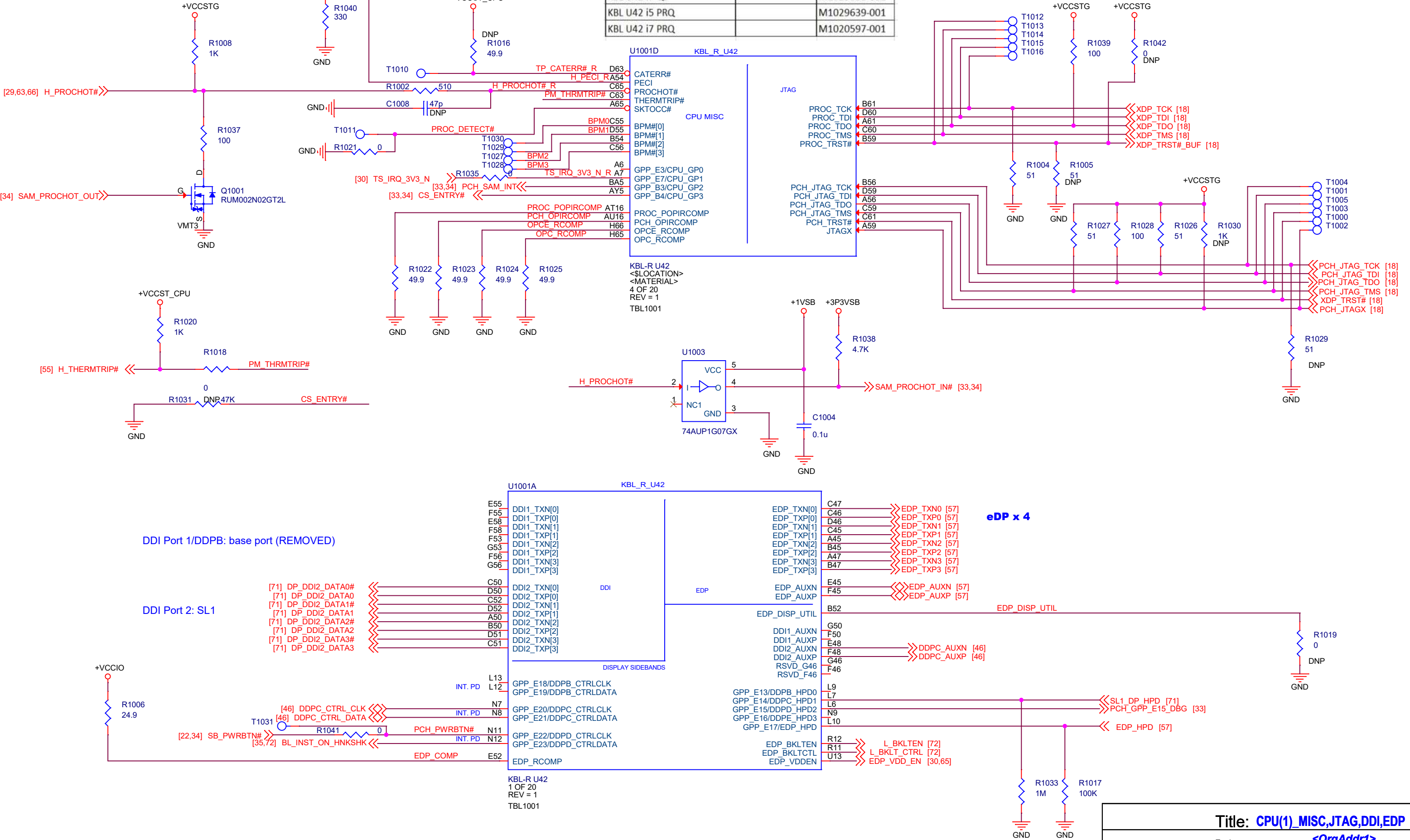
	Authentication IC (ECC108)
+3P3VA	-> 0.005A

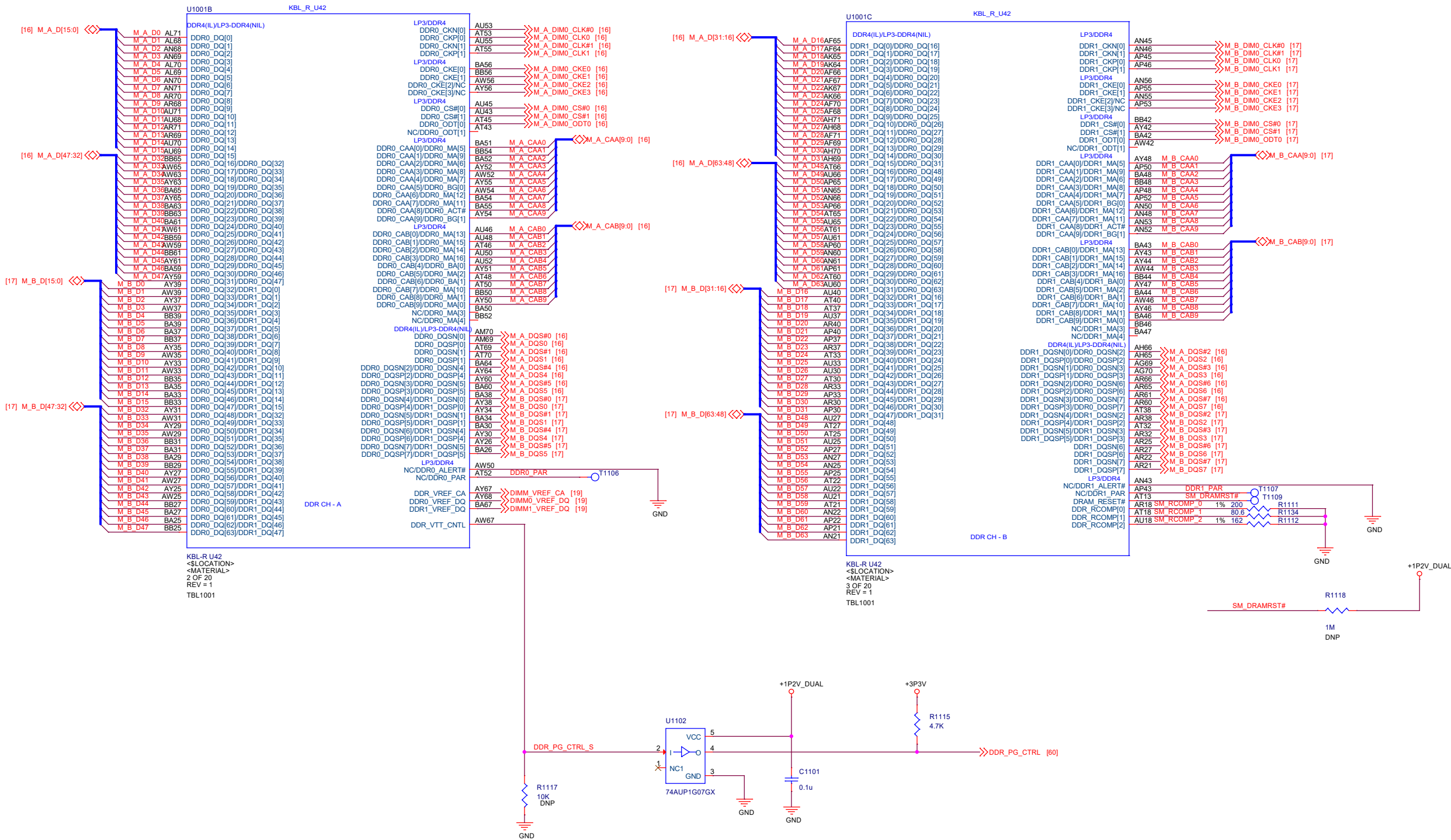


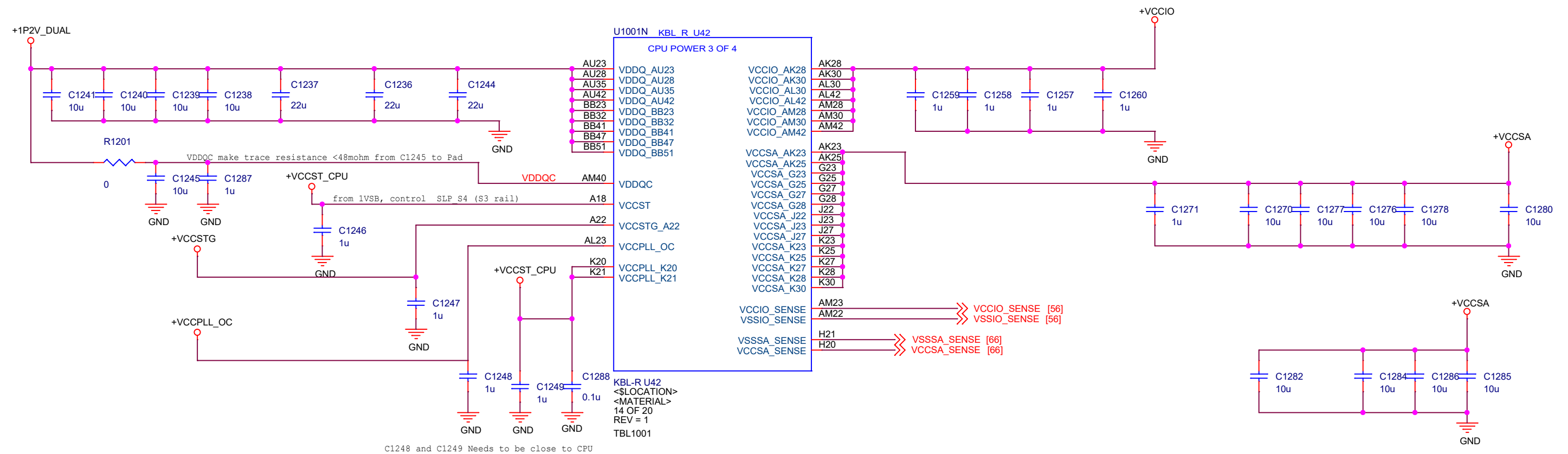
I2C & SMBUS Map



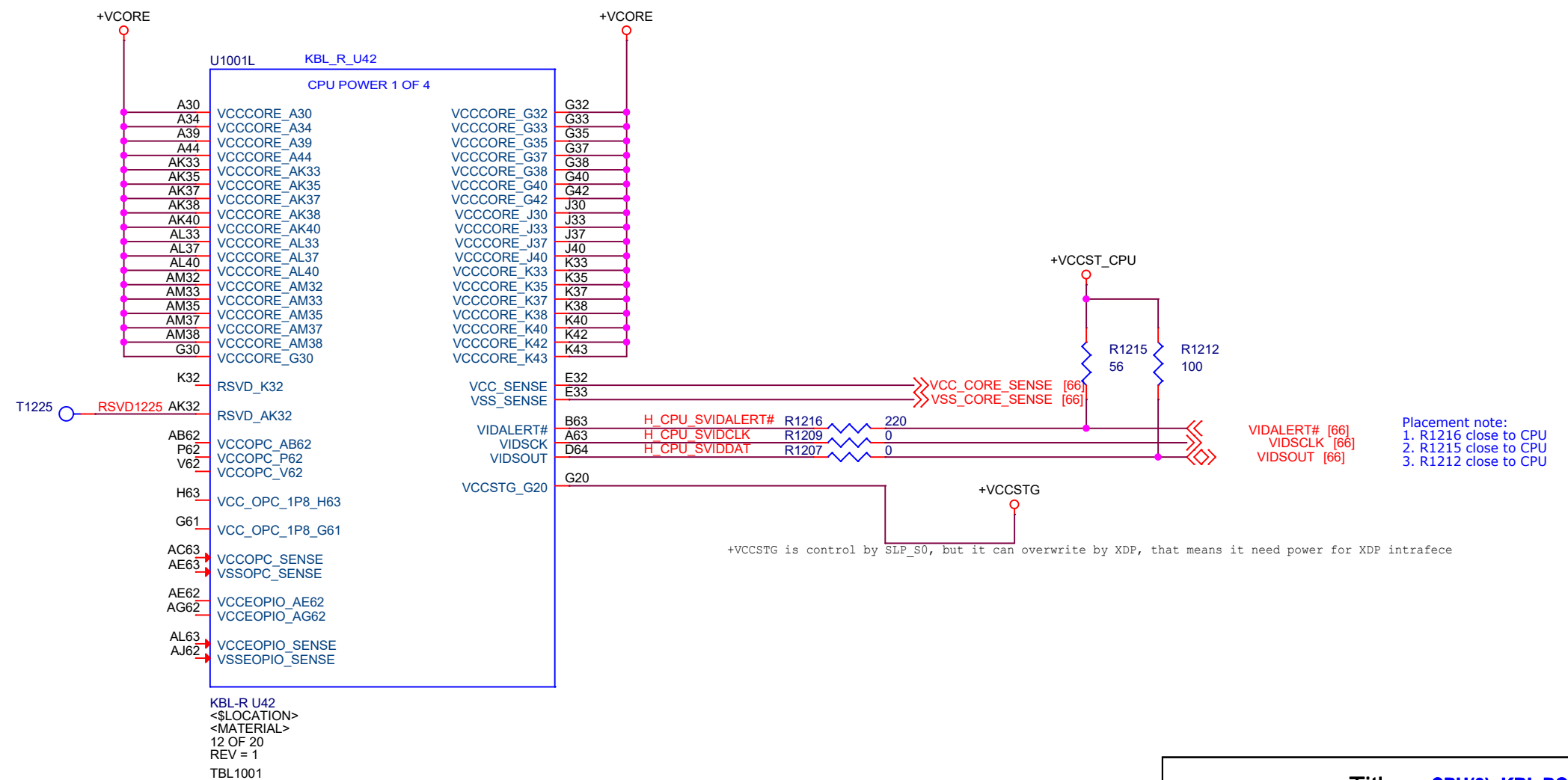
SKU	Proc #	MSPN#
KBL U42 Pre-ES		M1029632-001
KBL U42 ES High-Bin		M1029635-001
KBL U42 ES Low-Bin		M1034578-001
KBL U42 i5 QS		M1029637-001
KBL U42 i7 QS		M1029638-001
KBL U42 i5 PRQ		M1029639-001
KBL U42 i7 PRQ		M1020597-001

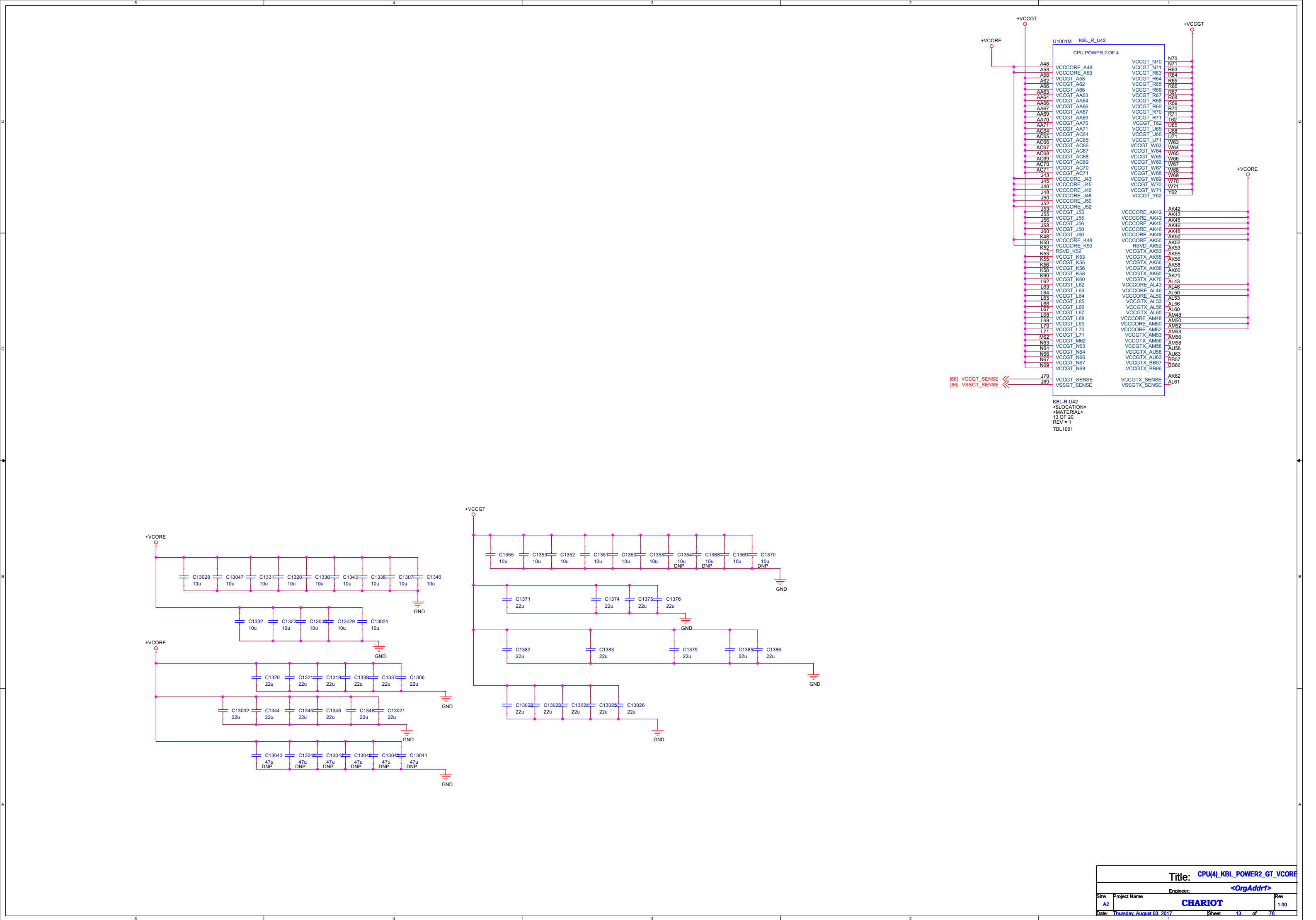


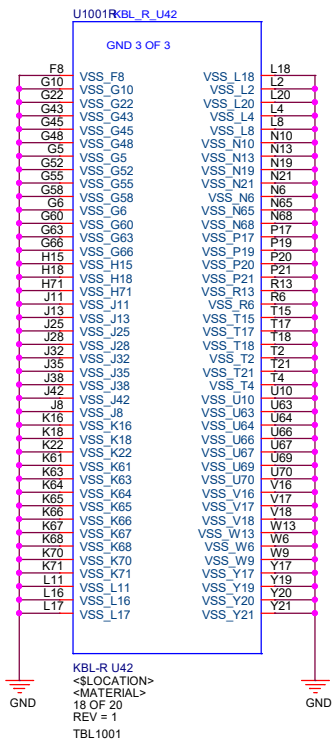
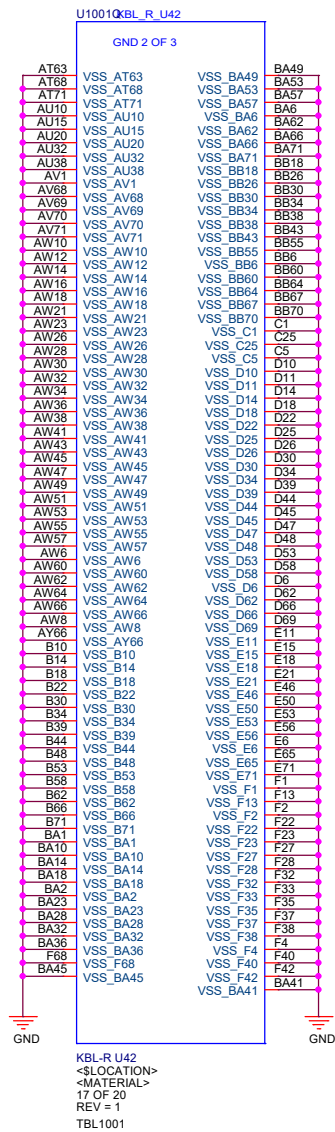
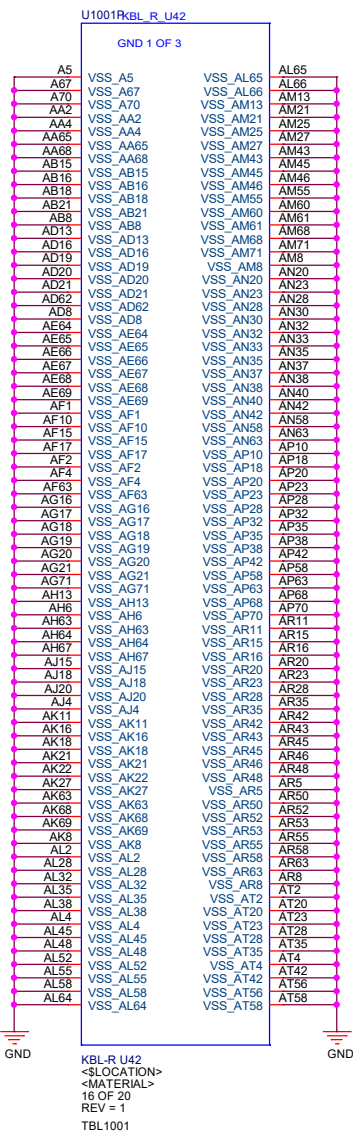


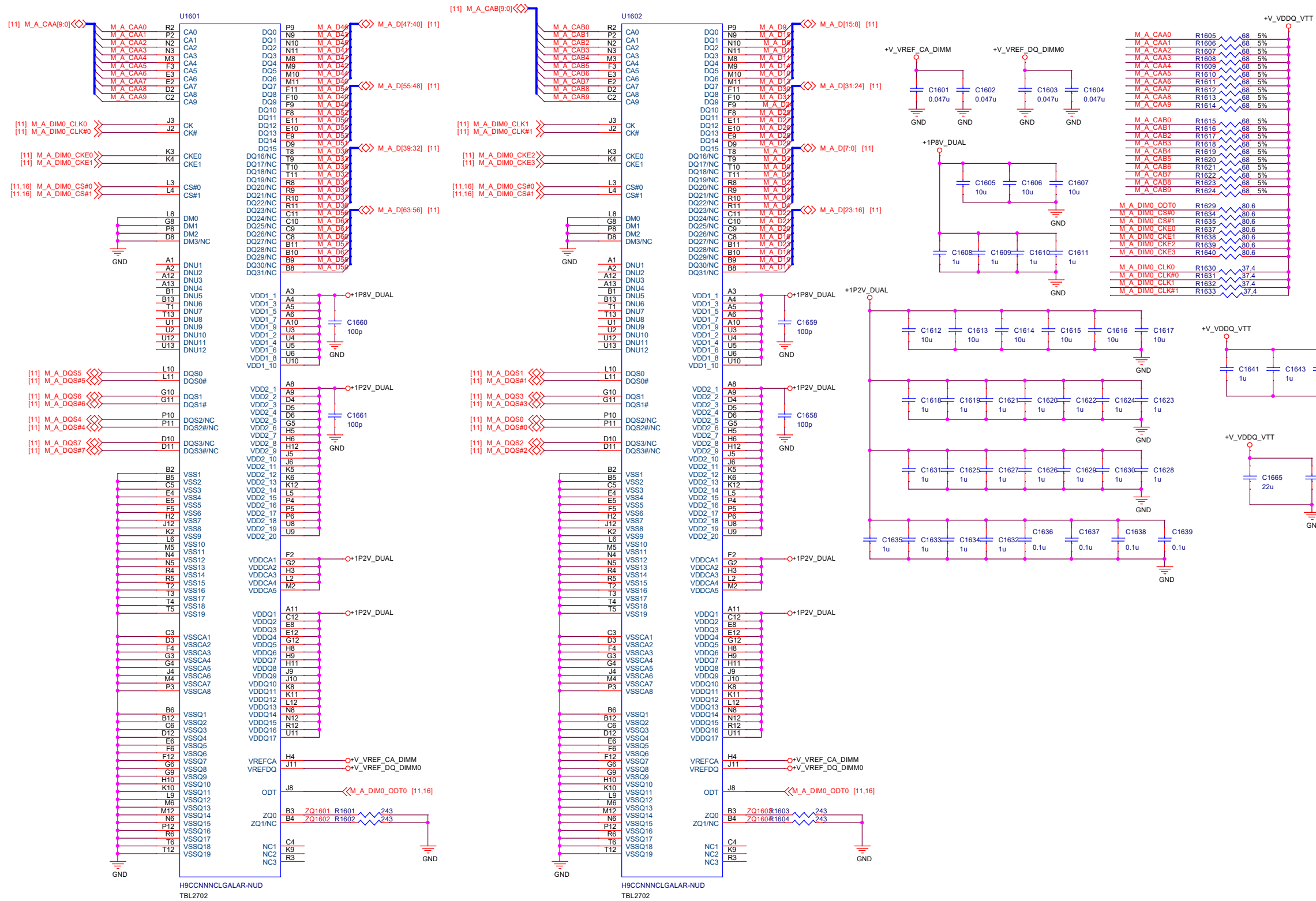


Do not route VccPLL, VccSTG, VccPLL_OC closest adjacent layer over any power net other than ground.

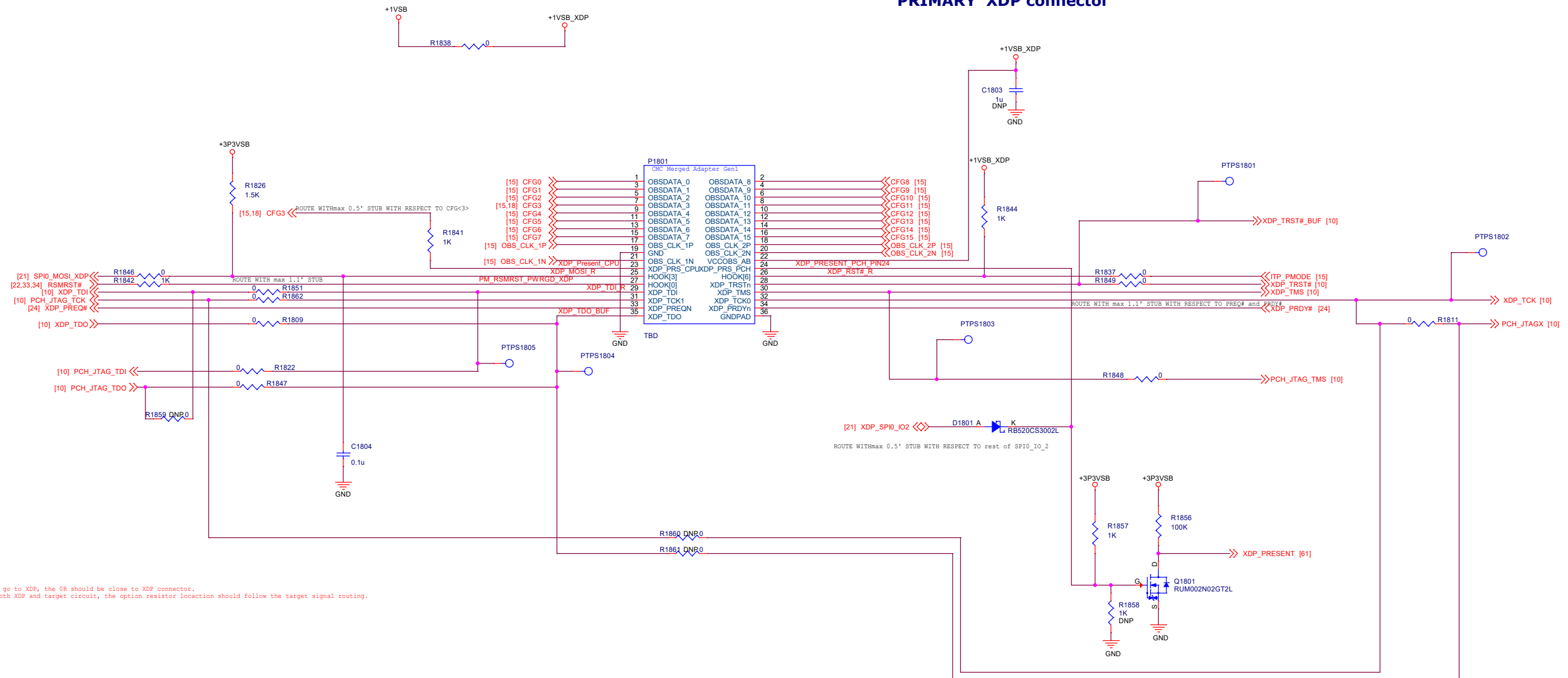








PRIMARY XDP connector



For the signals only go to XDP, the OR should be close to XDP connector.
For the signals to both XDP and target circuit, the option resistor location should follow the target signal routing.

QPS_CLK Routing

Stub length: 200ps (approx. 110mil or 28mm). The stub length should be minimized whenever possible.

Trace-to-Trace spacing: 3 x Trace Width

Maximum Via count: 4

Maximum Trace length: 2ns (roughly 1200mil or 305mm)

Length Matching: within +/- 270mil (6.85mm) of CFQ[17]

CFG Routing

Termination: None

Stub length: 200ps (approx. 110mil or 28mm). The stub length should be minimized whenever possible.

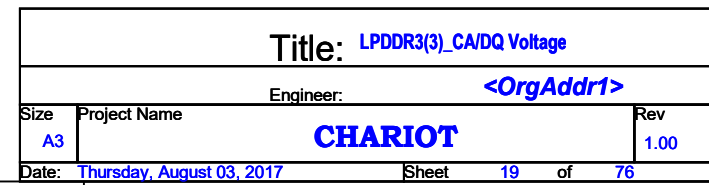
Trace-to-Trace spacing: No limit, but 2x trace width when possible

Maximum Via count: No limit, but should minimize whenever possible

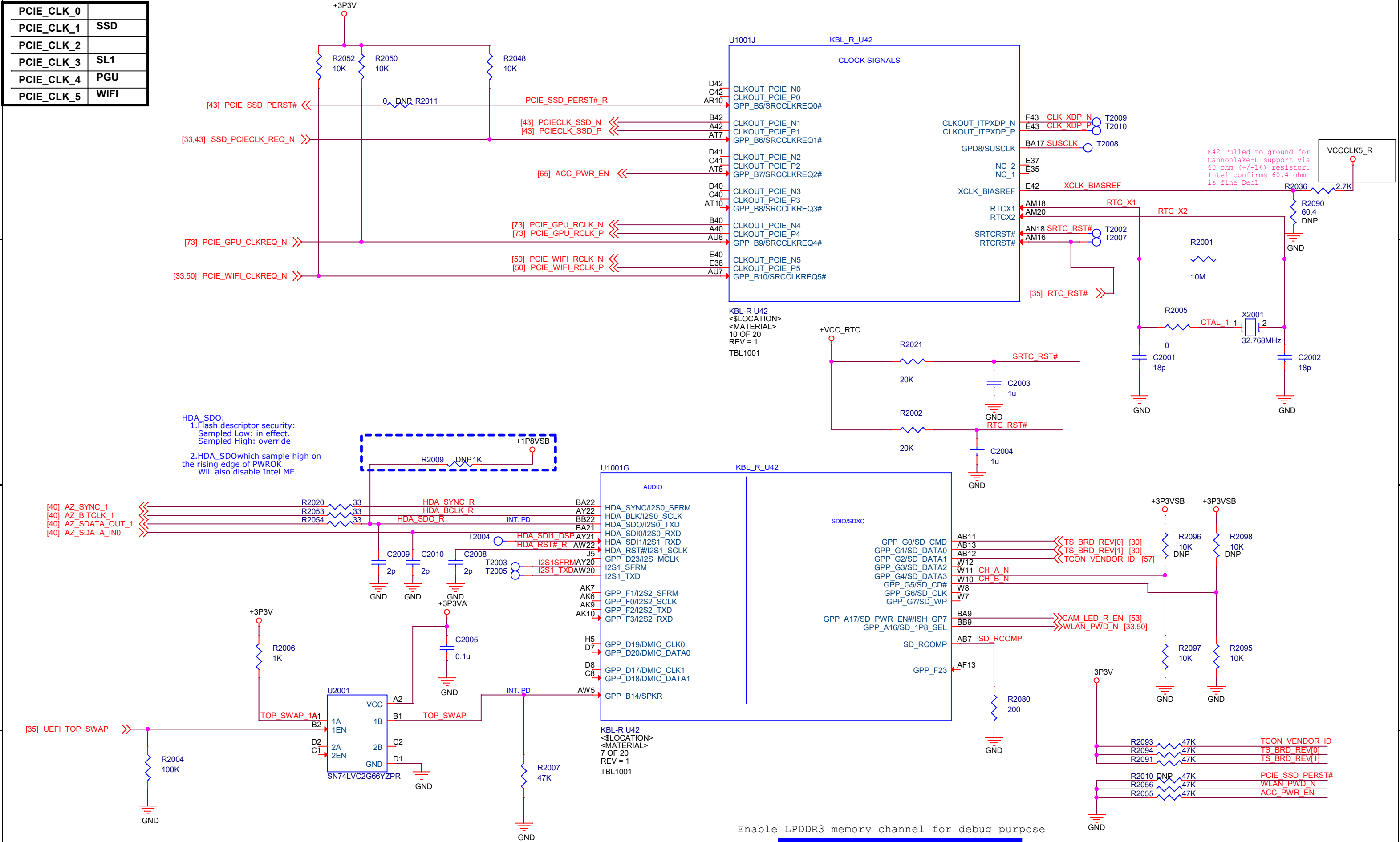
Maximum Stub length: 2ns (roughly 1200mil or 305mm) [For each segment, measured from XDP OB5 pin -> SkyVape pin]

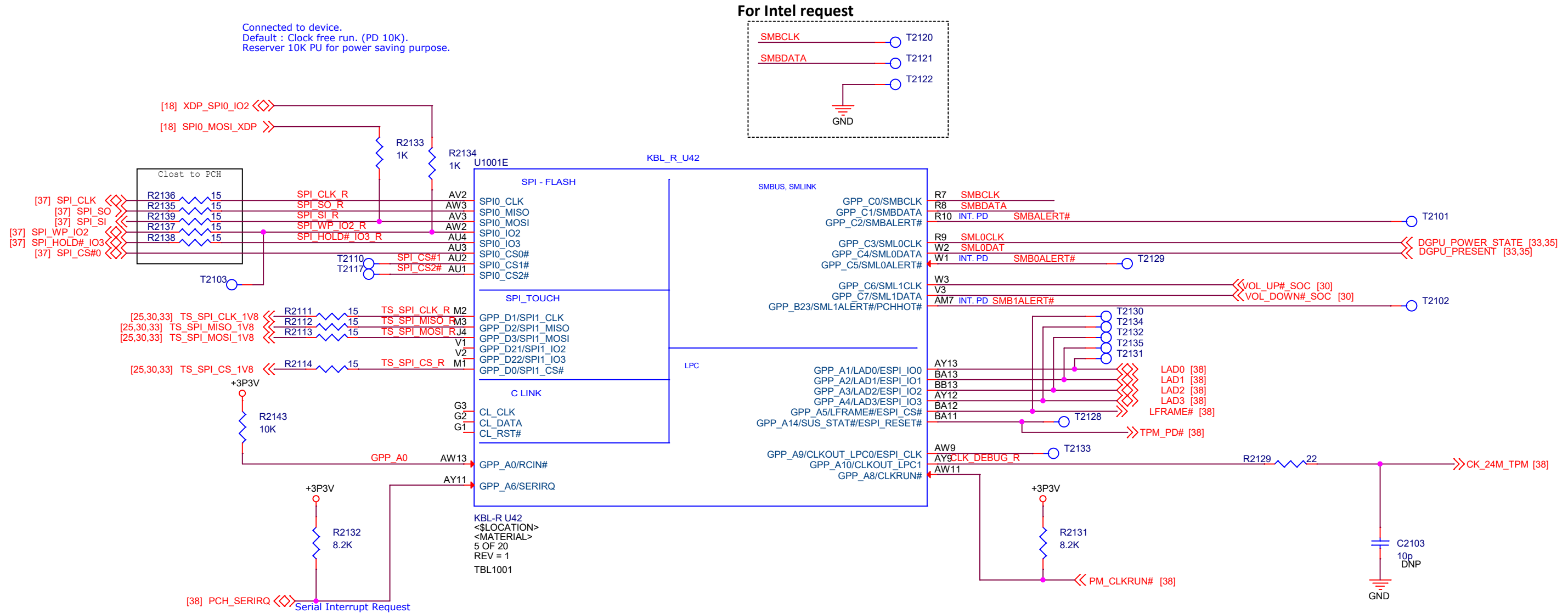
Length Matching: within +/- 270mil (6.85mm) of CFQ[1]

M3: CPU driven VREF path is stuffed by default.
M1: VREF_DQ driven by a Voltage Divider Network during Processor power-off



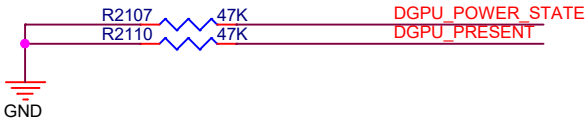
PCIE_CLK_0	
PCIE_CLK_1	SSD
PCIE_CLK_2	
PCIE_CLK_3	SL1
PCIE_CLK_4	PGU
PCIE_CLK_5	WIFI

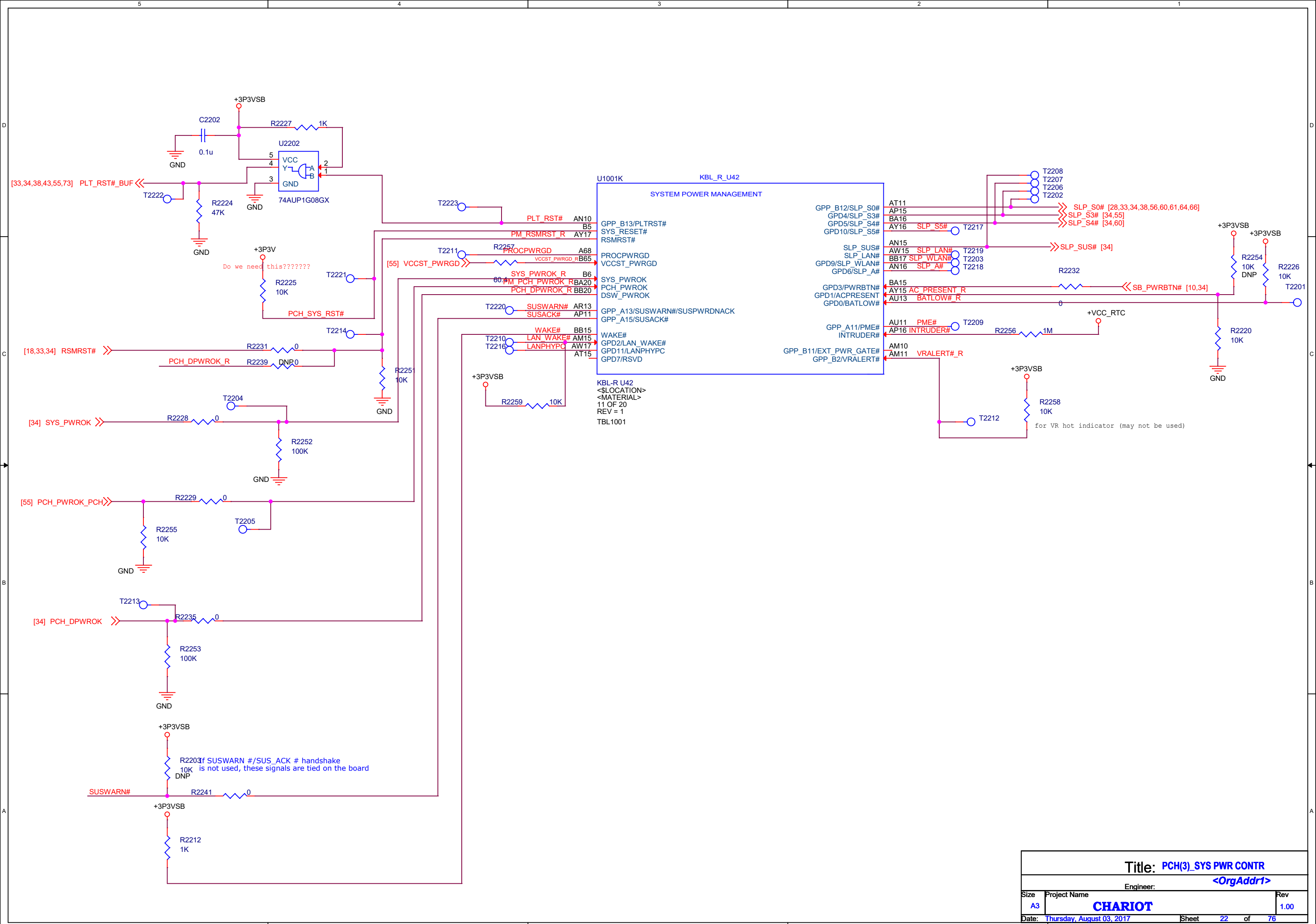




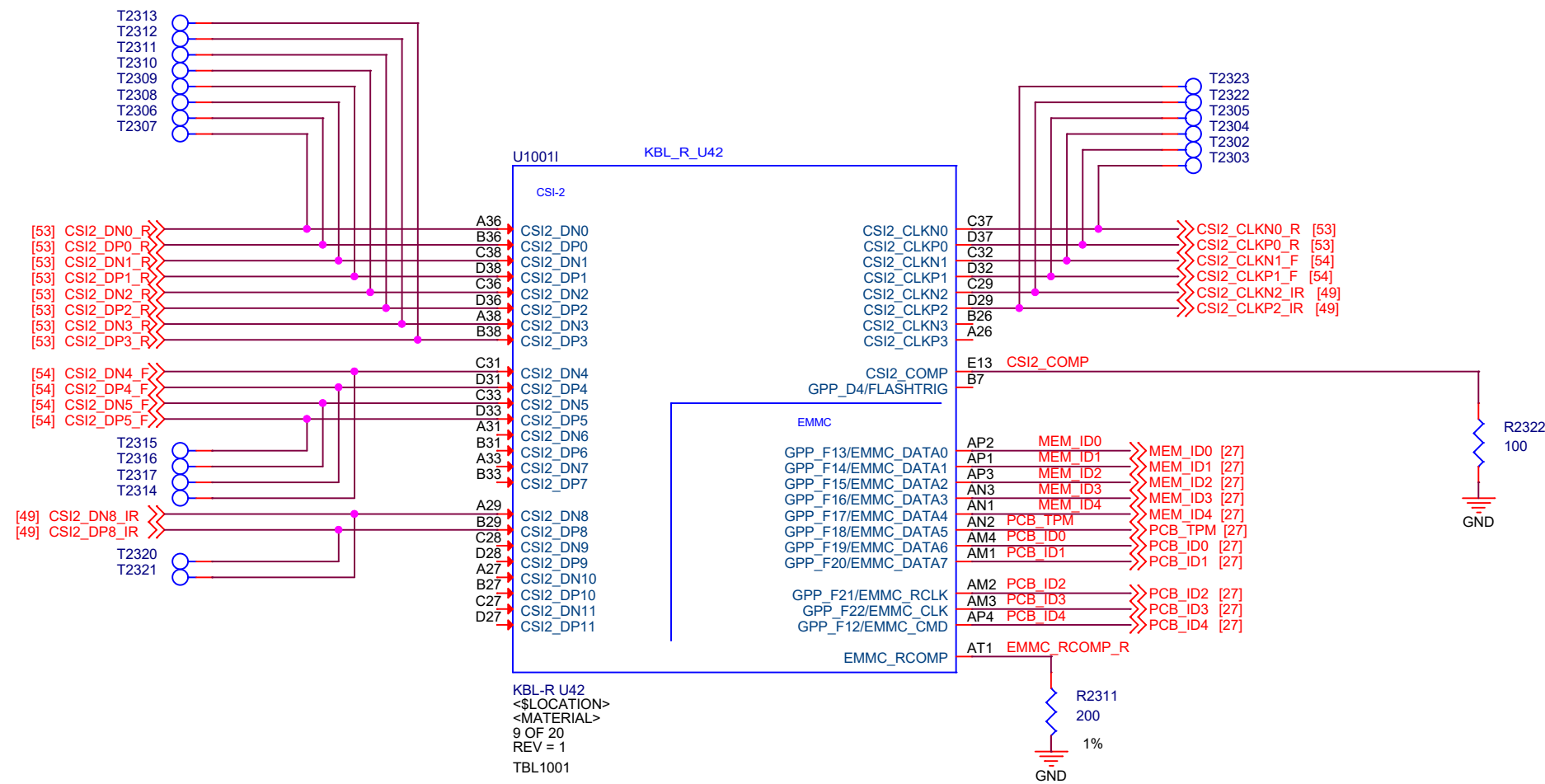
GPP_C2/SMBALERT#	
0 Default	Disable ME crypto TLS
1	Enable ME crypto TLS

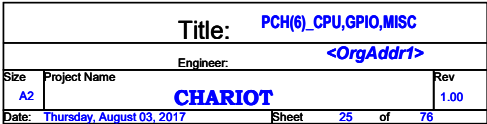
GPP_C5/SML0ALERT#	
0 Default	LPC (EC)
1	eSPI (EC)

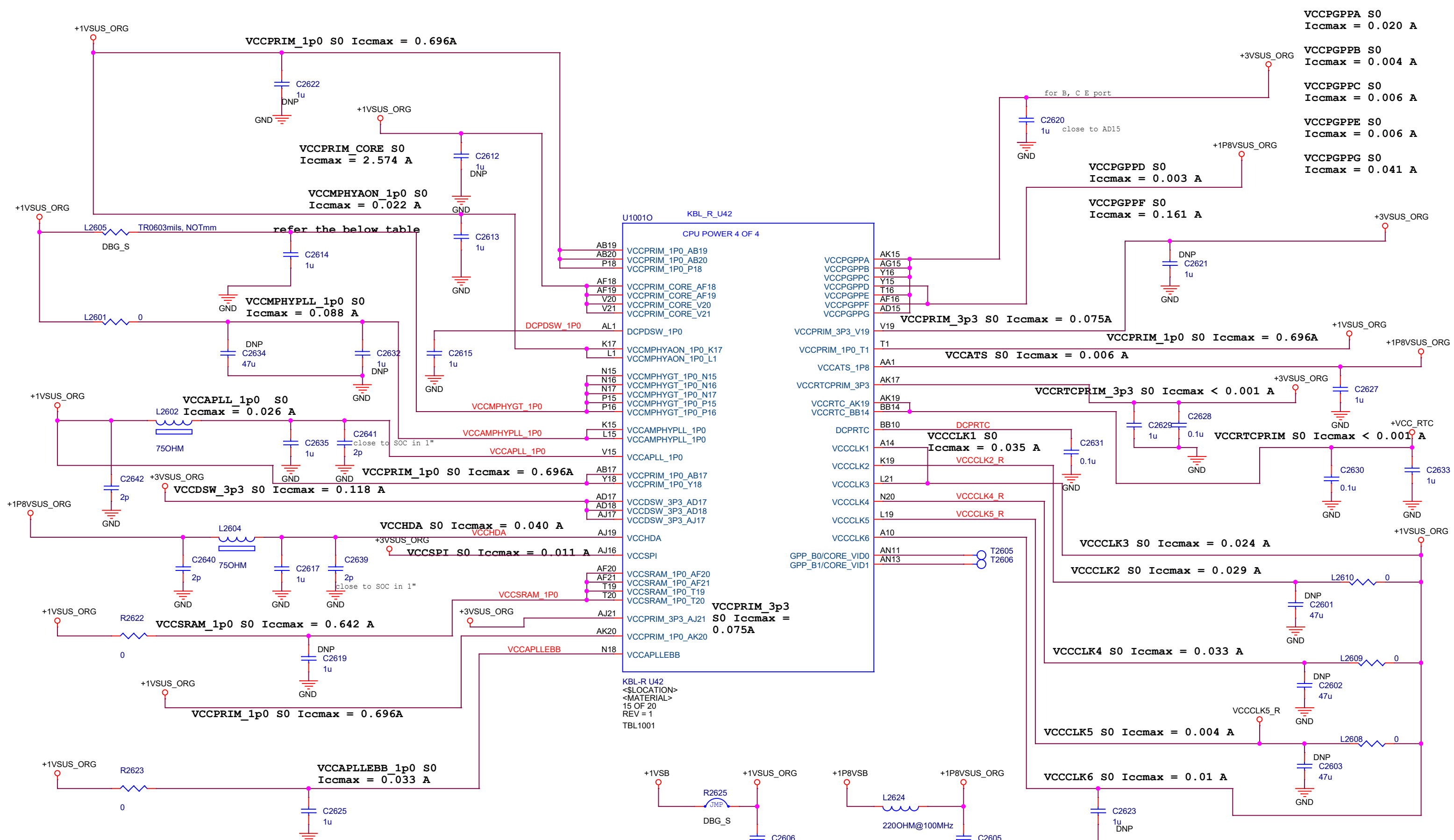




Those test point will be removed after check CSI



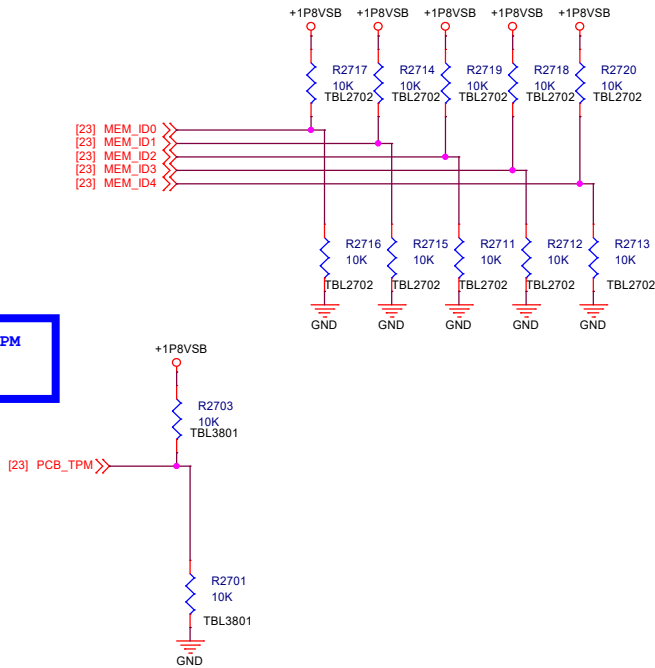




SKL U / SKL Y PCH-LP VCCMPHY_1p0 Icc Adder Per HSIO Lane

Icc (A)	Details
0.064	All HSIO disabled. Assumes DMI x4 Running 100%.
0.154	Each PCIe Gen3 Lane
0.102	Each PCIe Gen2 Lane
0.132	Each USB3 Port
0.099	SSIC
0.044	GbE Port
0.132	Each SATA Gen3 Port

Nuvoton / Infineon
Nation Z



MEM_ID4
1600 LPDDR3 0
1866 LPDDR3 1

MEM_ID1 MEM_ID0
Hynix 2znm 0 0
Samsung 20nm 0 1

32Gb * 4(pcs) = 16GB
16Gb * 4(pcs) = 8GB
8Gb * 4(pcs) = 4GB

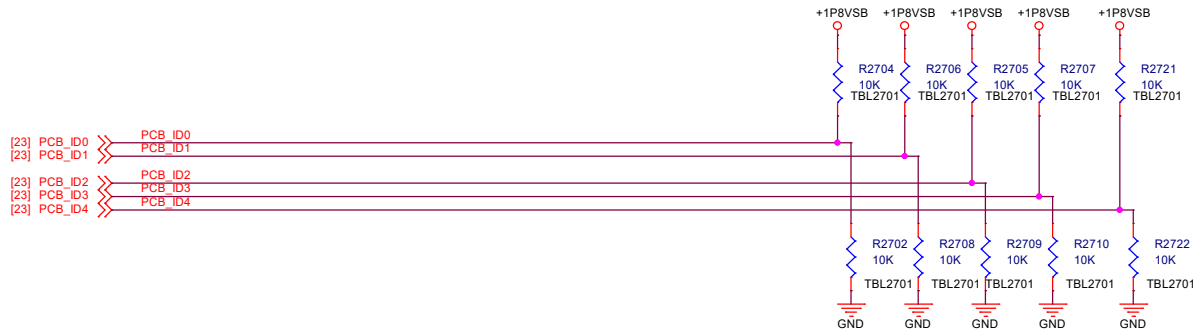
MEM_ID2 MEM_ID3
4GB 0 0
8GB 1 0
16GB 0 1

PCBID4 PCB_ID3 PCB_ID2 PCB_ID1 PCB_ID0
EV3A 1 0 0 1 1
EV3B 1 0 1 1 0
DV 1 0 1 1 1
PV 1 1 0 0 0

PCB_ID4
Gauntlet 0
Shield 1

TBL2701

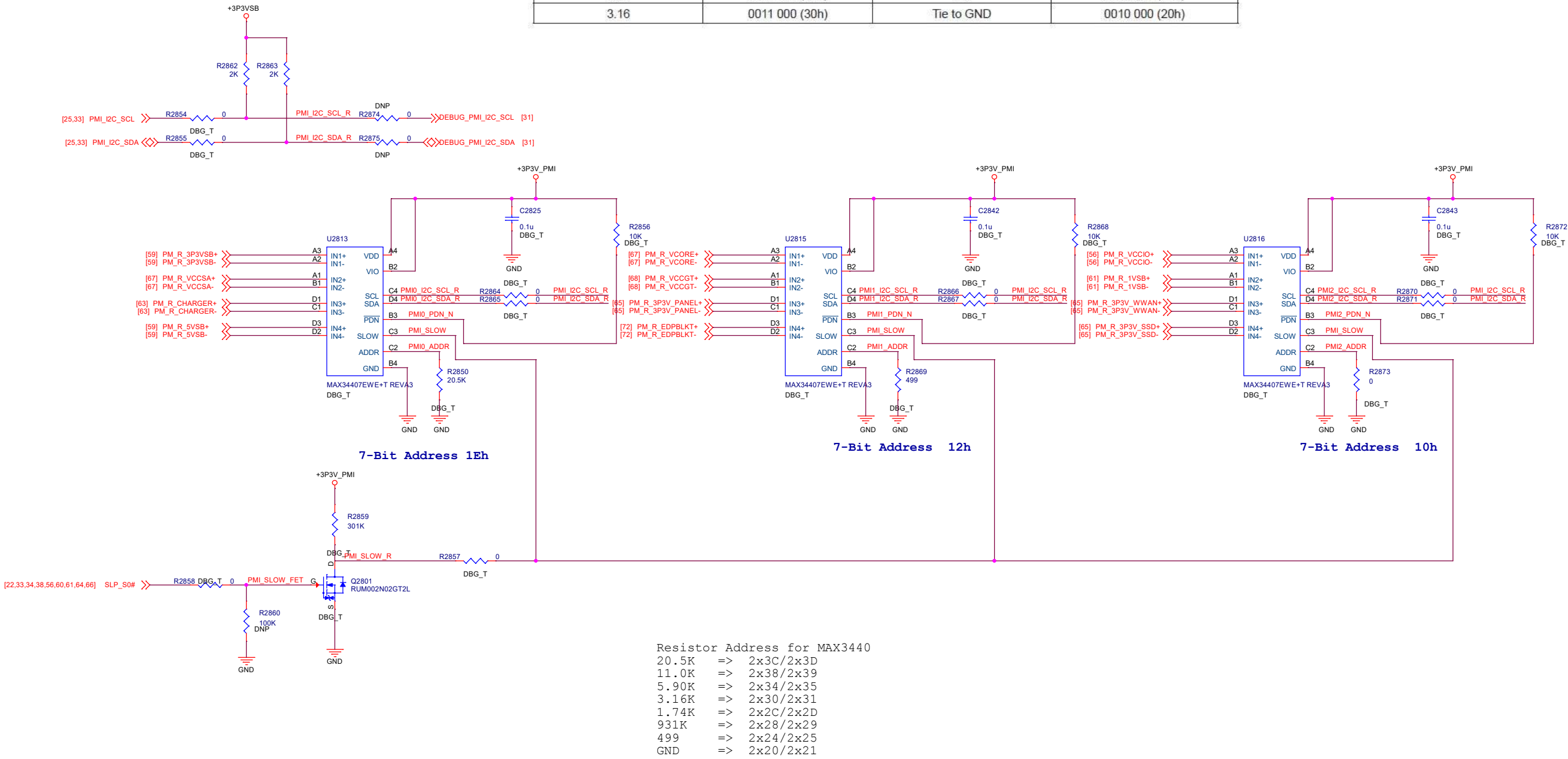
Build	X861217-001 Qty (10K 0201)	PCH_Value	PCH_10K	PCH_NOSTUFF
EV3A	5	10011	R2721, R2710, R2709, R2706, R2704	R2722, R2707, R2705, R2708, R2702
	5	10100	R2721, R2710, R2705, R2708, R2702	R2722, R2707, R2709, R2706, R2704
	5	10101	R2721, R2710, R2705, R2708, R2704	R2722, R2707, R2709, R2706, R2702
EV3B	5	10110	R2721, R2710, R2705,R2706, R2702	R2722, R2707, R2709, R2708, R2704
DV	5	10111	R2721, R2710, R2705,R2706, R2704	R2722, R2707, R2709, R2708, R2702
PV	5	11000	R2721, R2707, R2709, R2708, R2702	R2722, R2710, R2705, R2706, R2704

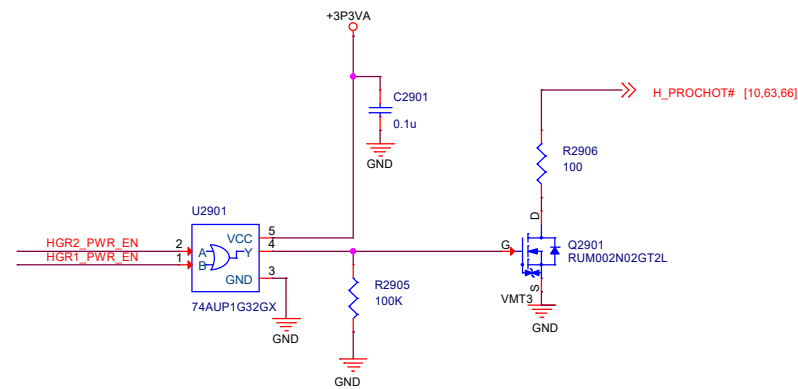


TBL2702		
H4GB 1866 2znm	Hynix 8Gb 1866	H9CCNNN8GTALAR-NUD
Mem	M1008409-001	U1601,U1602,U1701,U1702
Res	X811791-001	R2720, R2716, R2715, R2711, R2712
NI	NO-STUFF	R2713, R2717, R2714, R2719, R2718
H8GB 1866 2znm		
Mem	M1008406-001	U1601,U1602,U1701,U1702
Res	X811791-001	R2720, R2716, R2715, R2719, R2712
NI	NO-STUFF	R2713, R2717, R2714, R2711, R2718
S4GB 1866 D20		
Mem	X946149-001	U1601,U1602,U1701,U1702
Res	X811791-001	R2720, R2717, R2715, R2711, R2712
NI	NO-STUFF	R2713, R2716, R2714, R2719, R2718
S8GB 1866 D20		
Mem	X946454-001	U1601,U1602,U1701,U1702
Res	X811791-001	R2720, R2717, R2715, R2719, R2712
NI	NO-STUFF	R2713, R2716, R2714, R2711, R2718
S16GB 1866 D20		
Mem	X930118-001	U1601,U1602,U1701,U1702
Res	X811791-001	R2720, R2717, R2715, R2711, R2718
NI	NO-STUFF	R2713, R2716, R2714, R2719, R2712
H16GB 1866 2znm		
Mem	M1008421-001	U1601,U1602,U1701,U1702
Res	X811791-001	R2720, R2716, R2715, R2711, R2718
NI	NO-STUFF	R2713, R2717, R2714, R2719, R2712

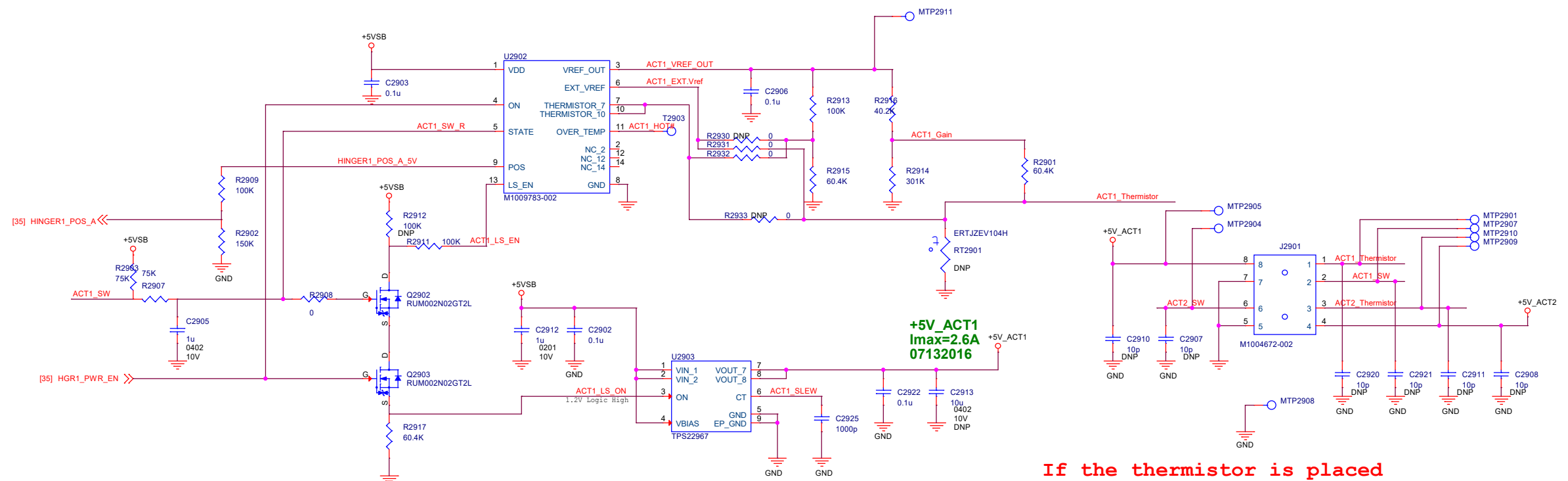
Table 5. SMBus Slave Address Select

RADDR (±1%) (kΩ)	SLAVE ADDRESS	RADDR (±1%) (Ω)	SLAVE ADDRESS
20.5	0011 110 (3Ch)	1.74k	0010 110 (2Ch)
11.0	0011 100 (38h)	931	0010 100 (28h)
5.90	0011 010 (34h)	442	0010 010 (24h)
3.16	0011 000 (30h)	Tie to GND	0010 000 (20h)





ACT1 = LEFT DM
ACT2 = RIGHT DM



If the thermistor is placed

On the FPC: Keep everything as is

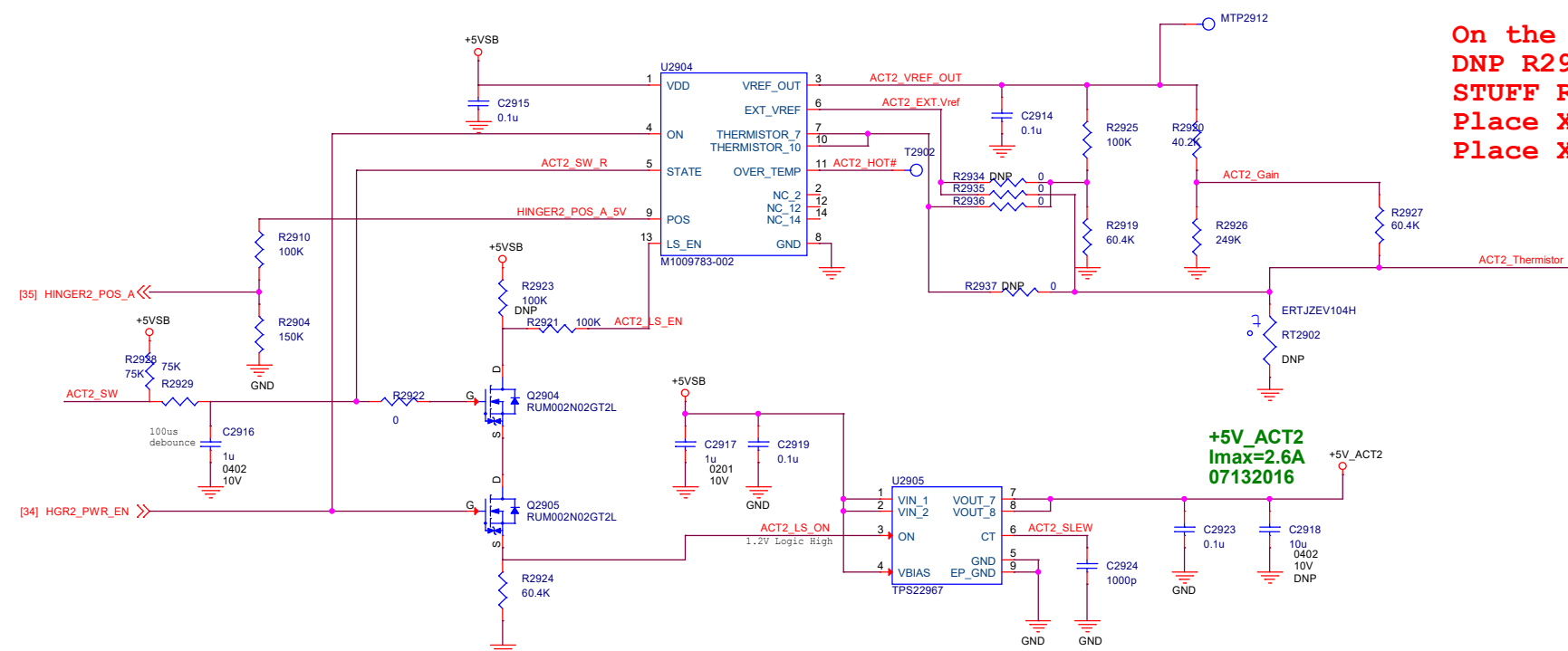
On the MB:

DNP R2931, R2932, R2935, R2936

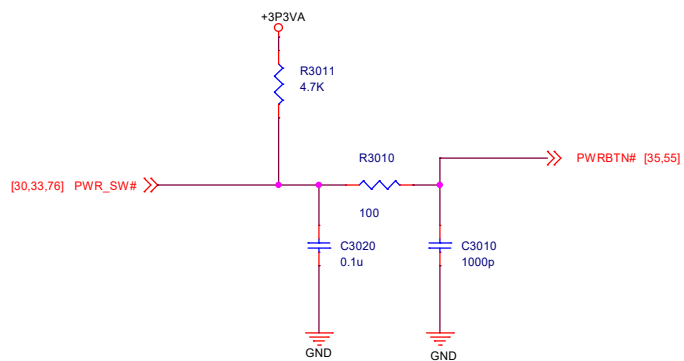
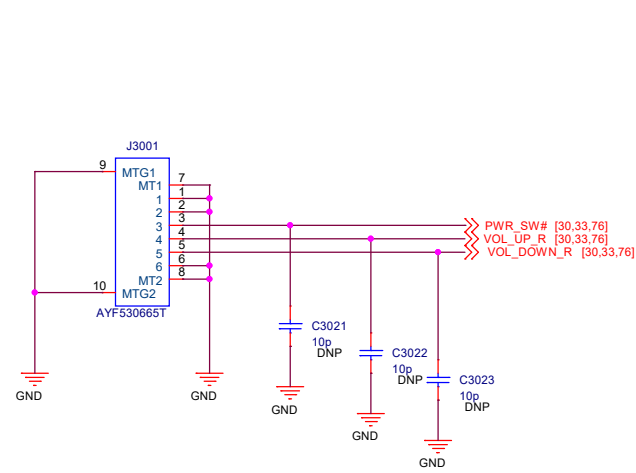
STUFF R2930, R2933, R2934, R2937

Place X930189-001 in R2901, R2927 locations

Place X801411-001 in RT2901, RT2902 locations

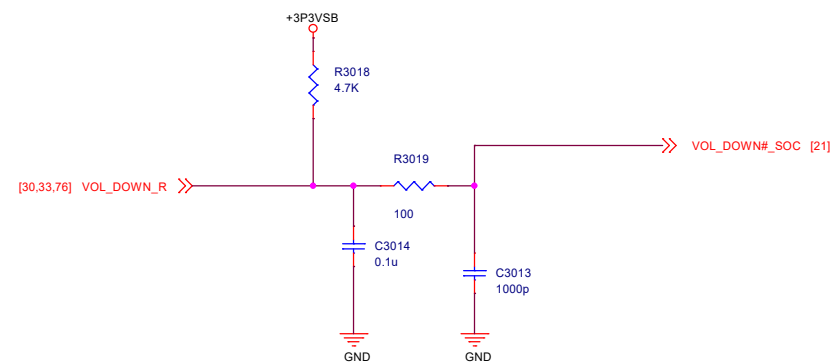


Title: Hinger connector			
Engineer: <OrgAddr1>			
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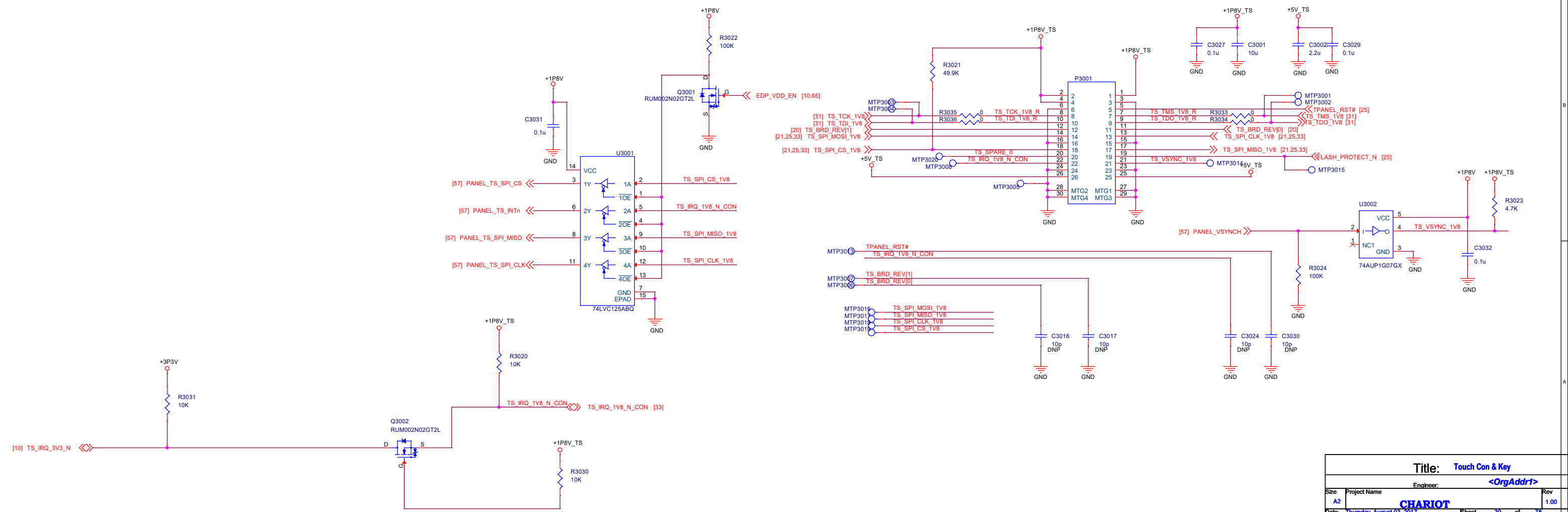
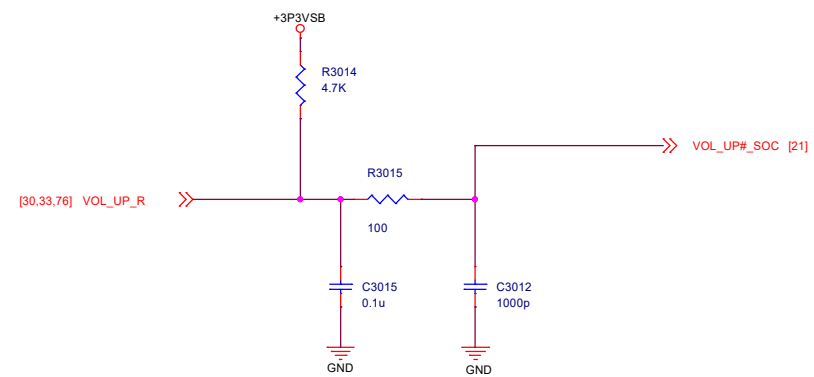


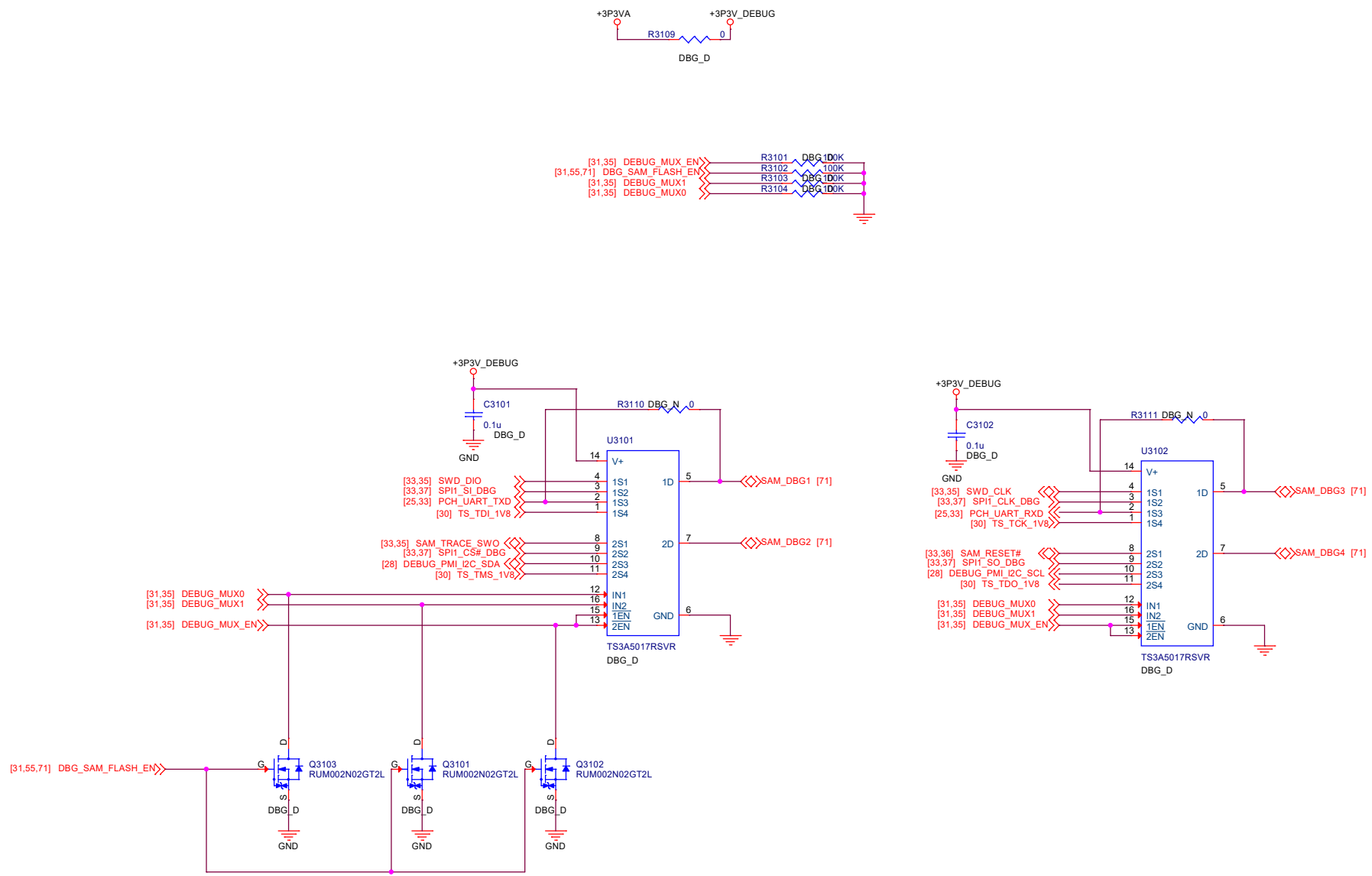
POWER BUTTON

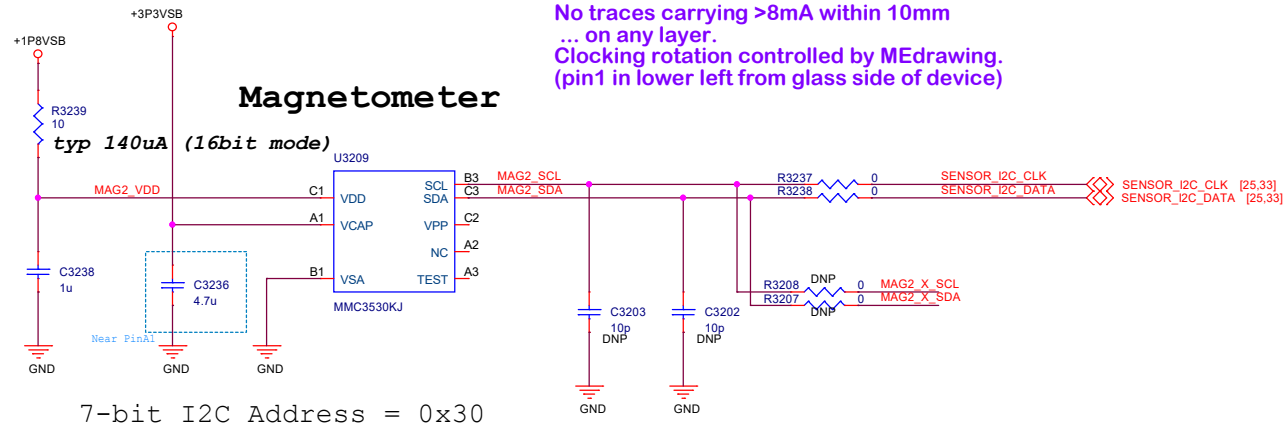
VOL_DOWN BUTTON



VOL_UP BUTTON



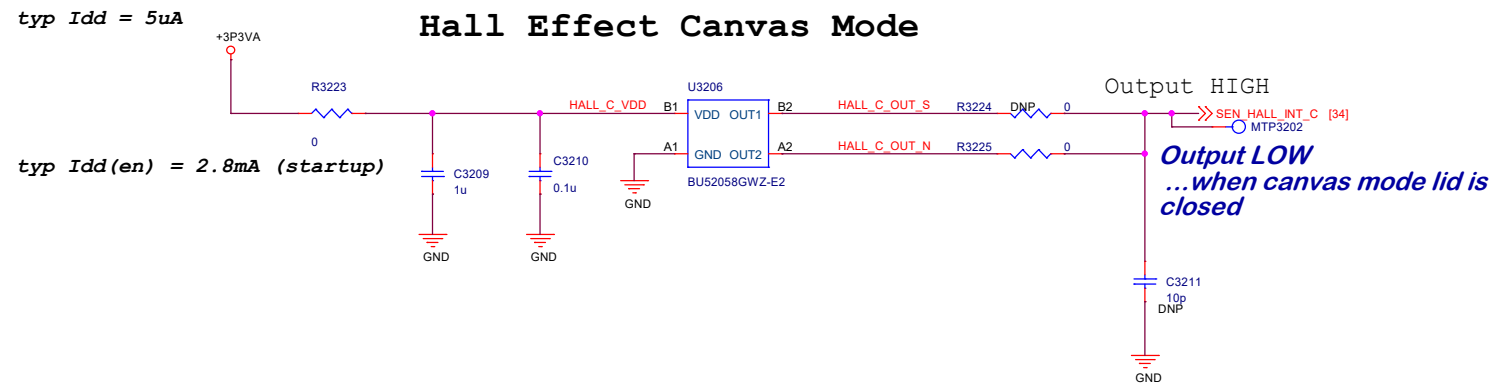
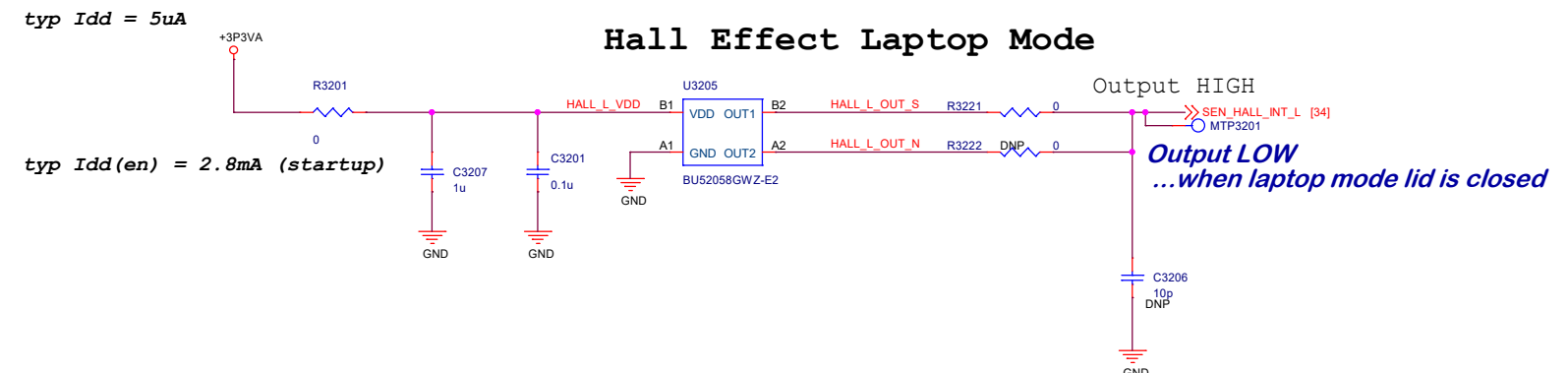




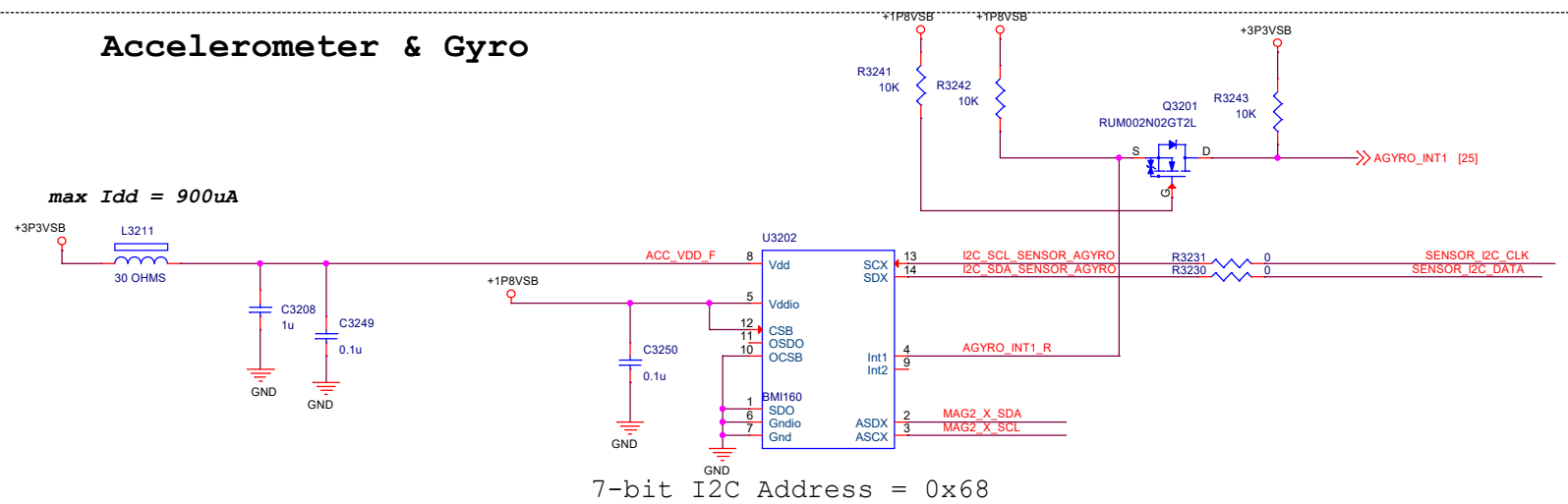
Critical Layout Note:
Extremely sensitive to ferrous materials:
Local ferrite bead to be >8mm remote
No traces carrying >8mA within 10mm
... on any layer.
Clocking rotation controlled by MEdrawing.
(pin1 in lower left from glass side of device)

Critical Layout Note for MemS devices:
- No traces under part,
- No vias in pads or directly under part,
- All traces entering pads to be same width,
- All traces to enter pads at zero angle.

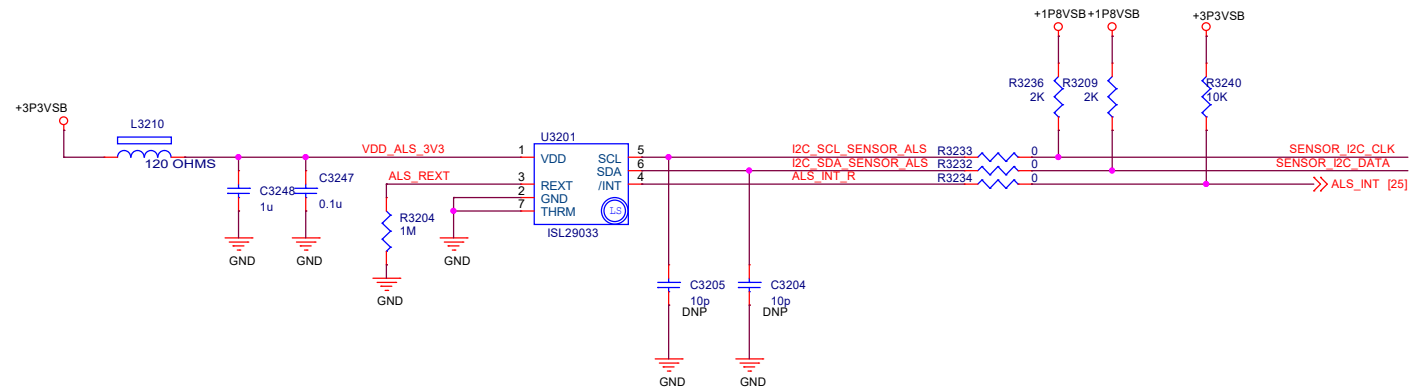
Clocking rotation controlled by MEdrawing.
(+X Device & +X Surface vectors must be parallel w/same direction
(i.e. if the part is located on the glass side of the PCB, the pin1 indicator dot should be in upper right corner)



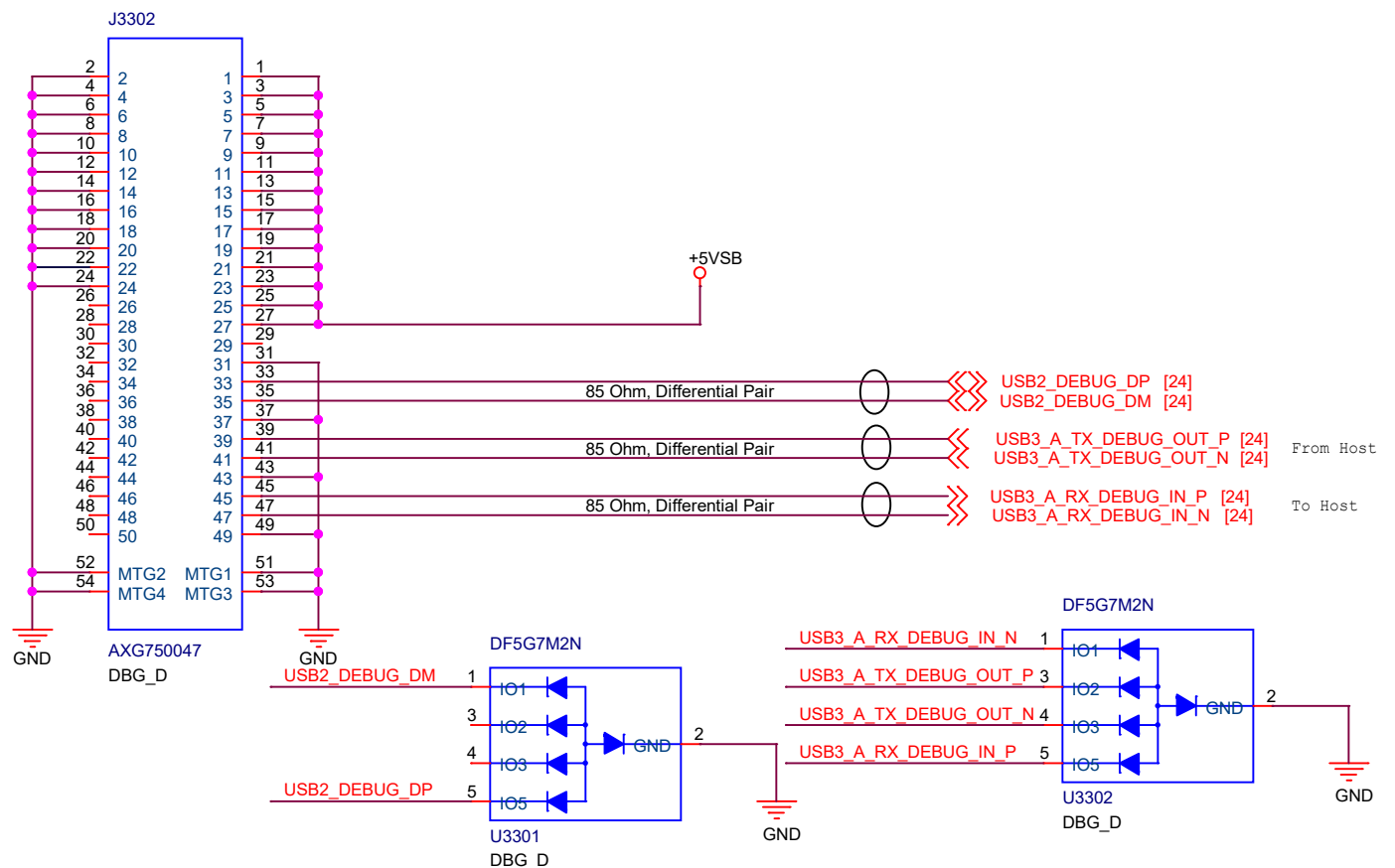
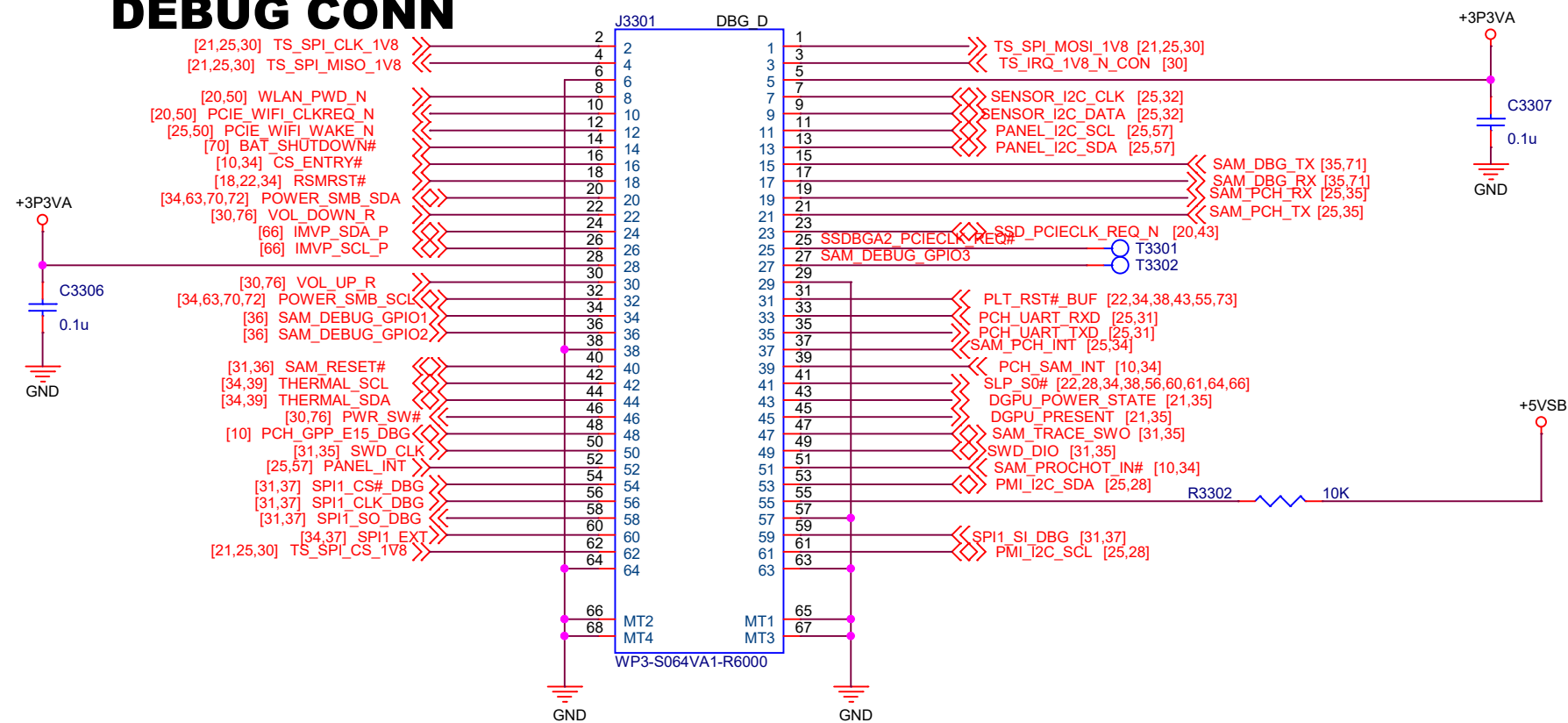
Accelerometer & Gyro



7-bit I2C Address = 0x44

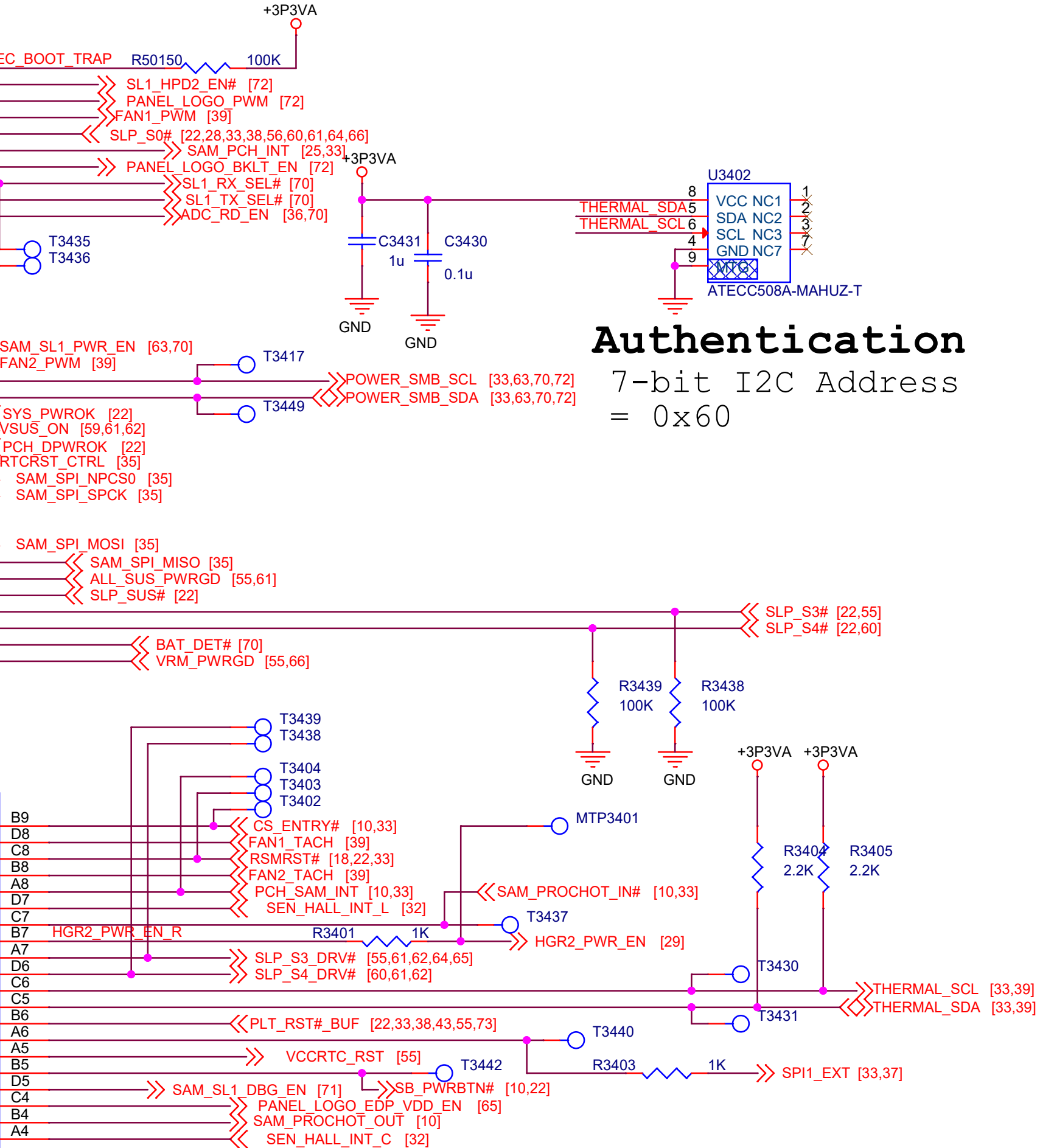
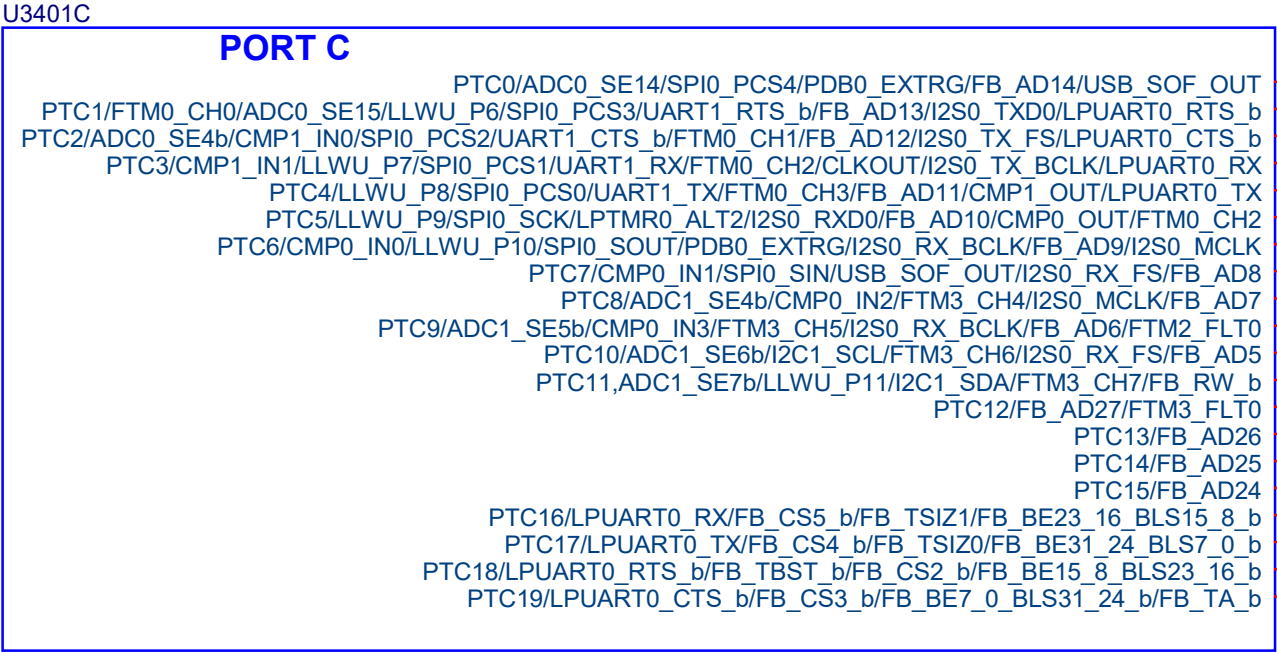
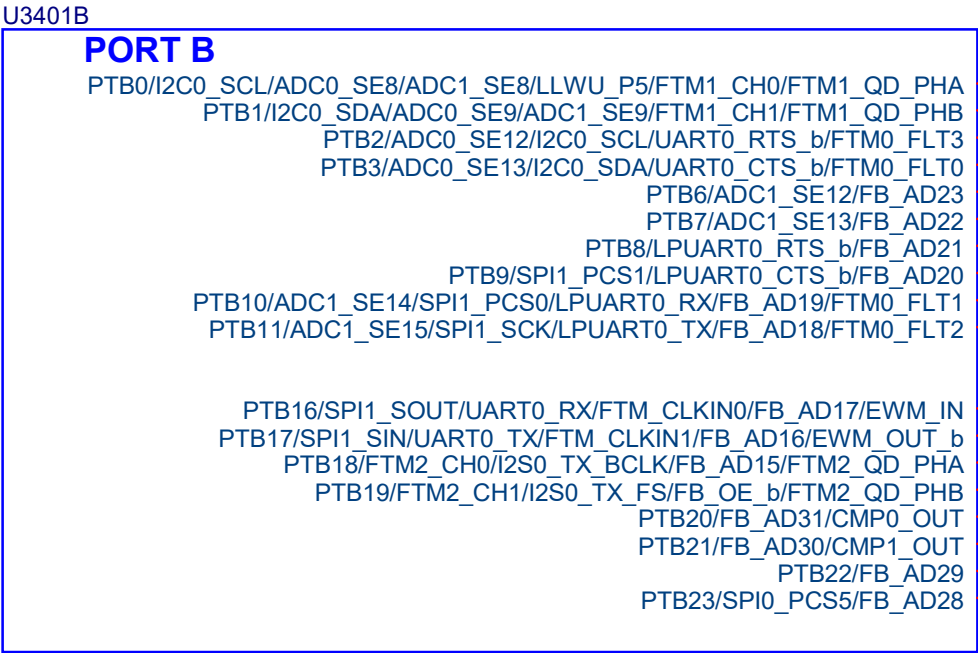
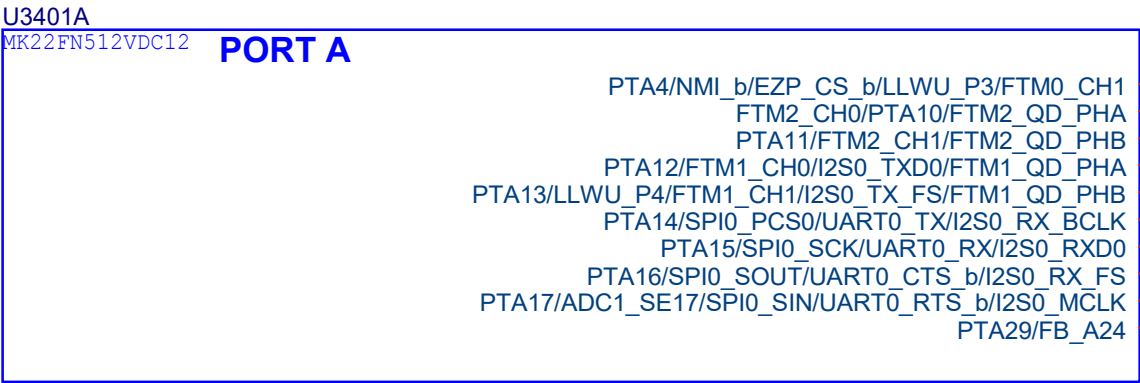


DEBUG CONN

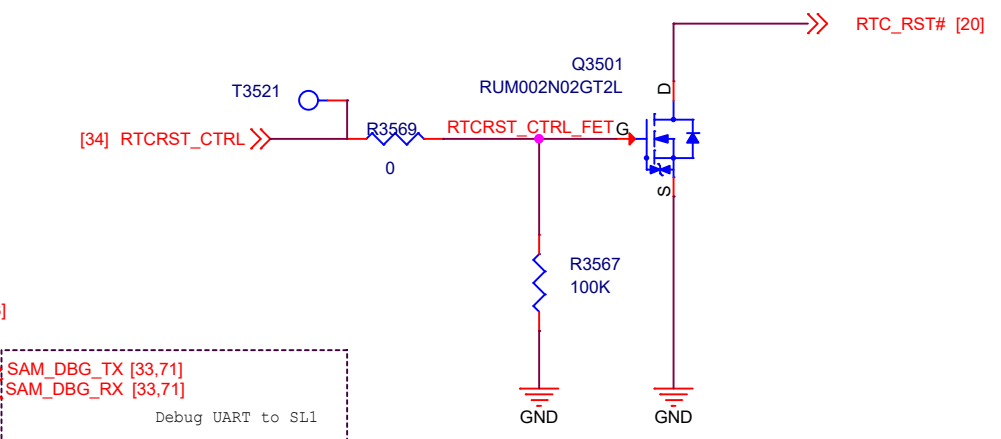
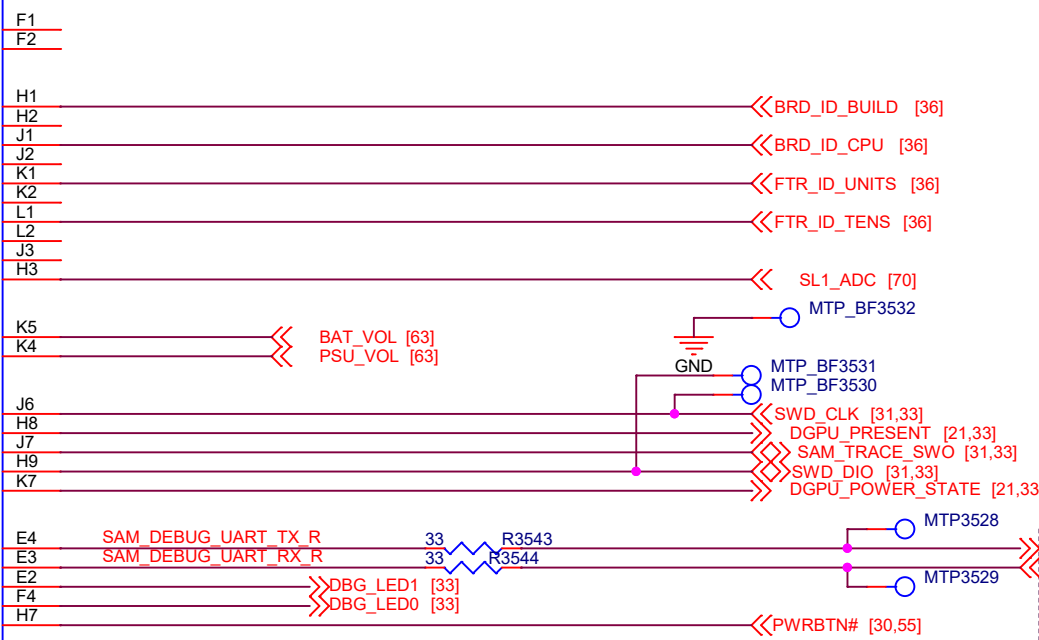
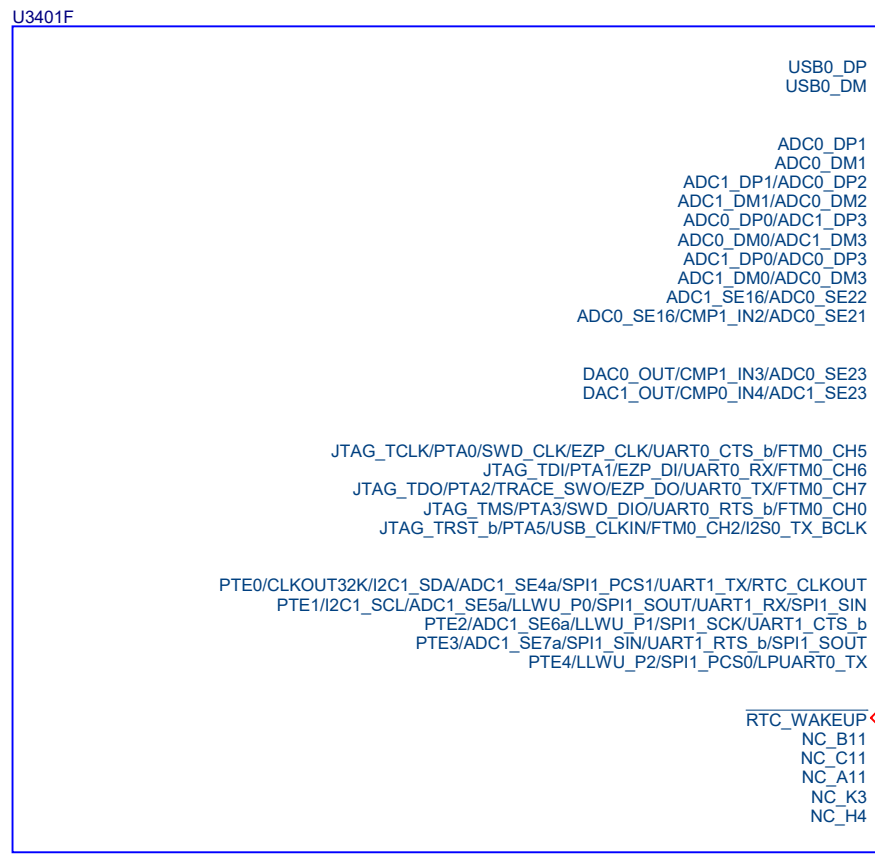
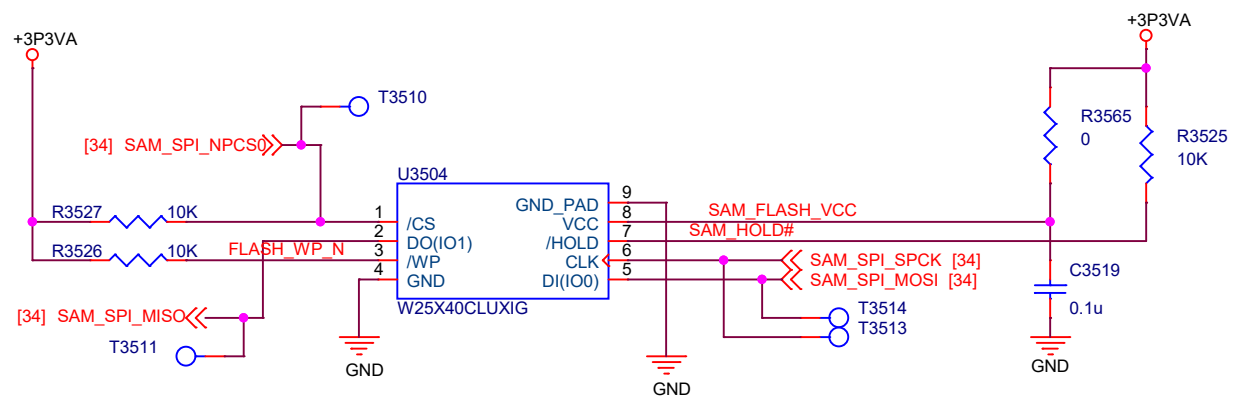
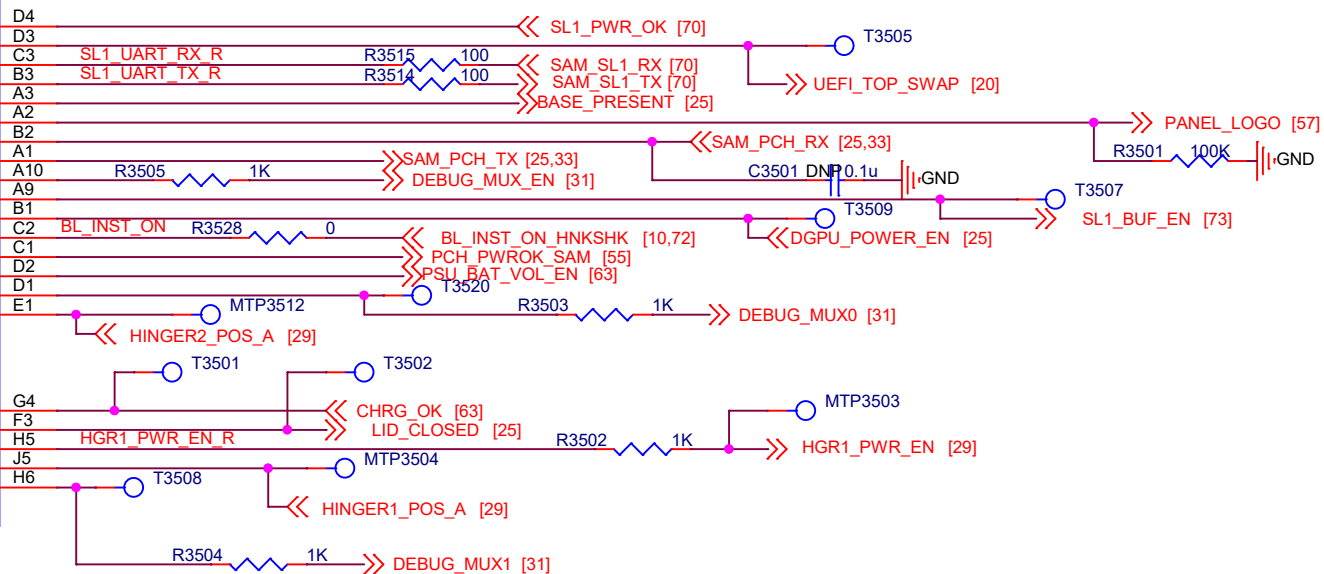
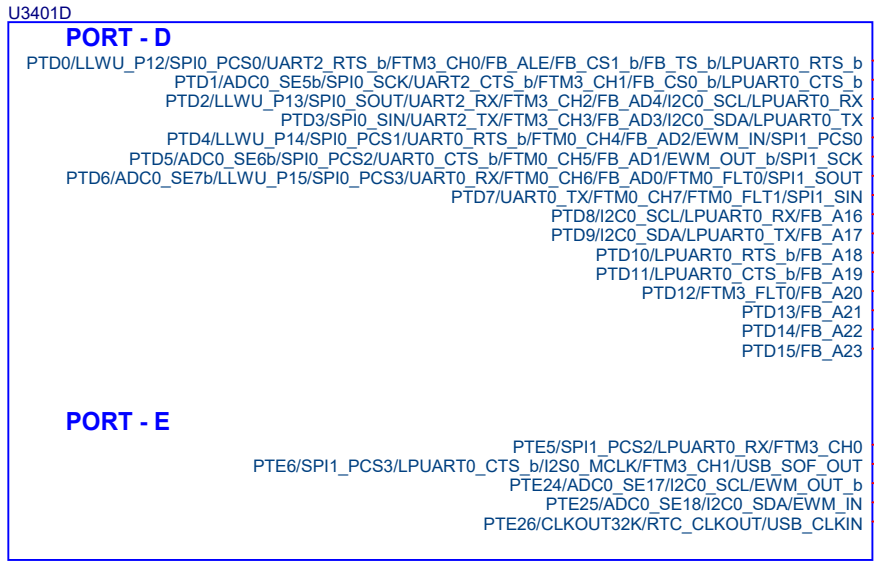


<Core Design>

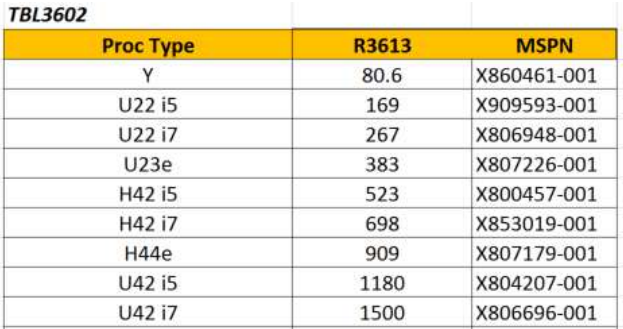
Title: Debug Conn / LPC		
Engineer: <OrgAddr1>		
Size: A3	Project Name: CHARIOT	Rev: 1.00
Date: Thursday, August 03, 2017	Sheet: 33	of 76



Title:		SAM_1	
Engineer:		<OrgAddr1>	
Size	Project Name	Rev	
A4	CHARIOT	1.00	
Date:	Thursday, August 03, 2017	Sheet	34 of 76



	HINGER1_POS_A_R	HINGER1_POS_B_R
Closed	High	Low
Transition	High	High
Open	Low	High
fault	Low	Low



Title:		SAM_3_PWR_IO_ID	
<OrgName>		<OrgAddr>	
Size	Project Name	Engineer:	Rev
A2	CHARIOT		1.00
Date:	Thursday, August 03, 2017	Sheet	36 of 76

D

D

C

C

B

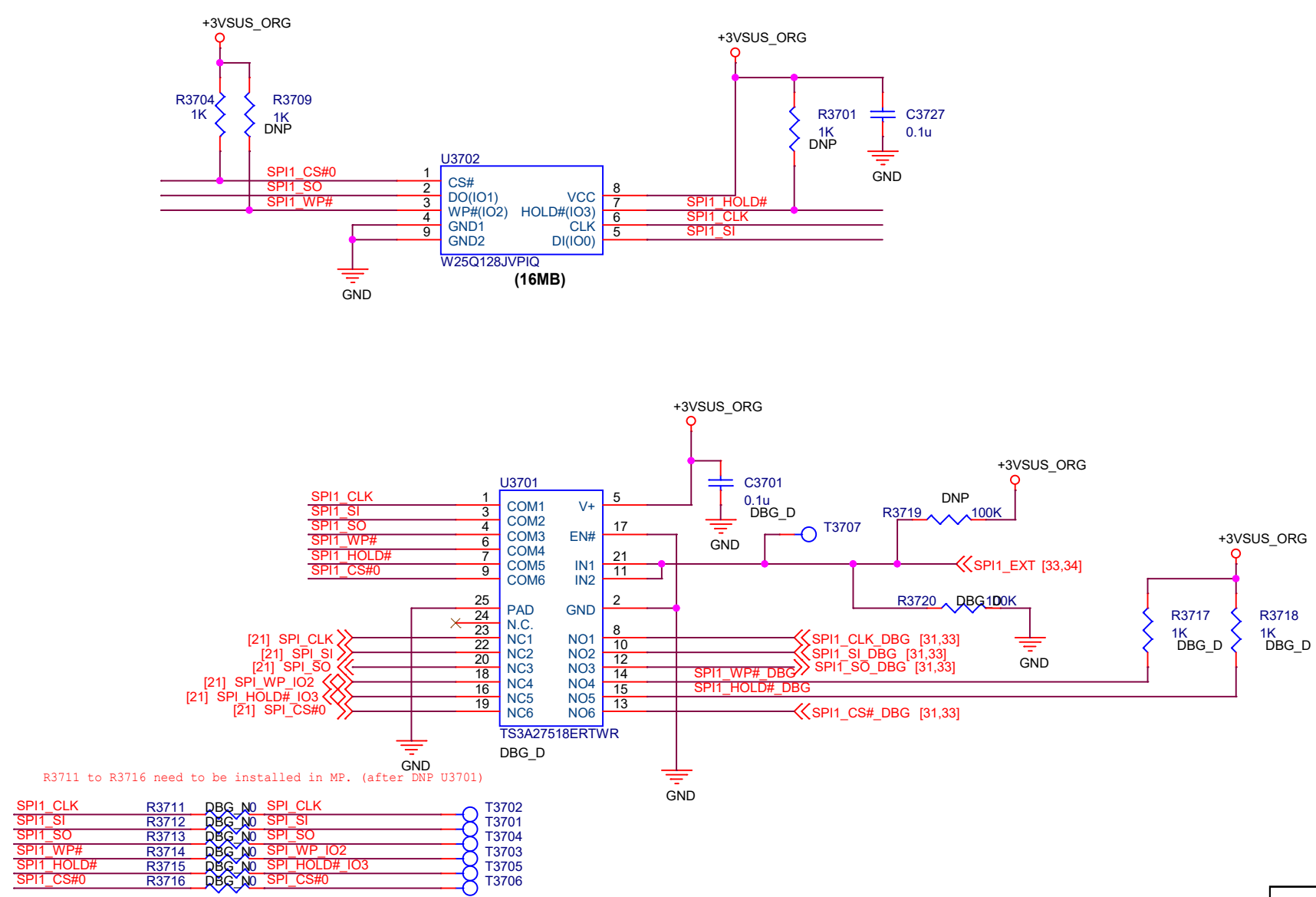
B

A

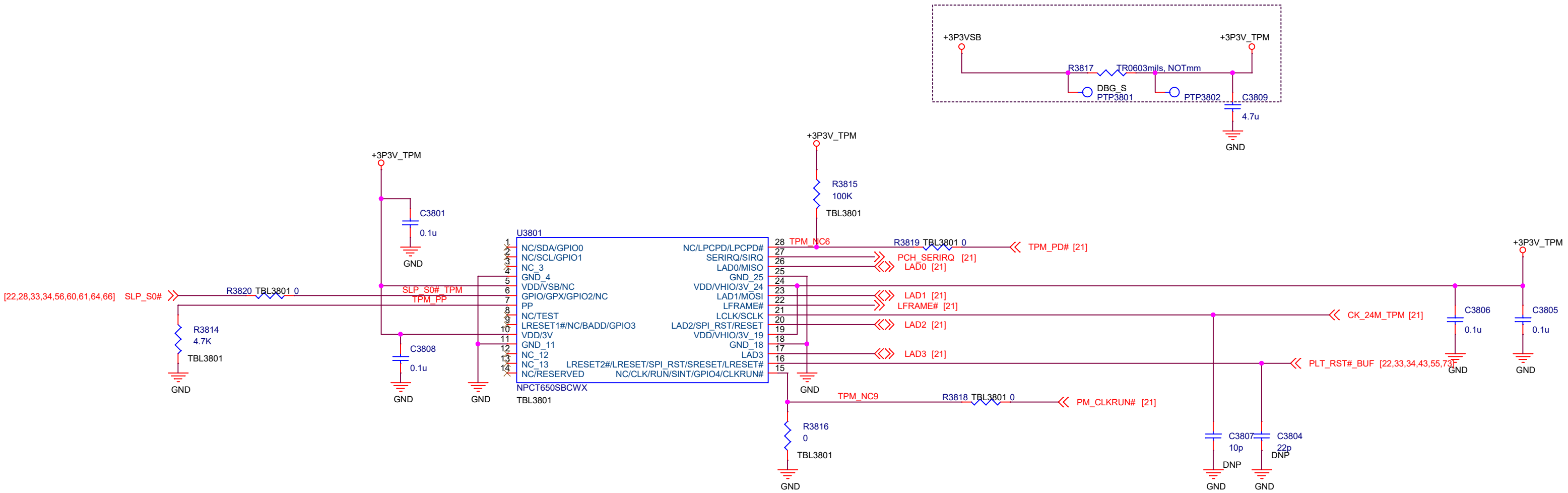
A

BW=200MHz

EN#	IN1/IN2	FUNCTION
L	L	COM to NC
L	H	COM to NO
H	X	Disconnect



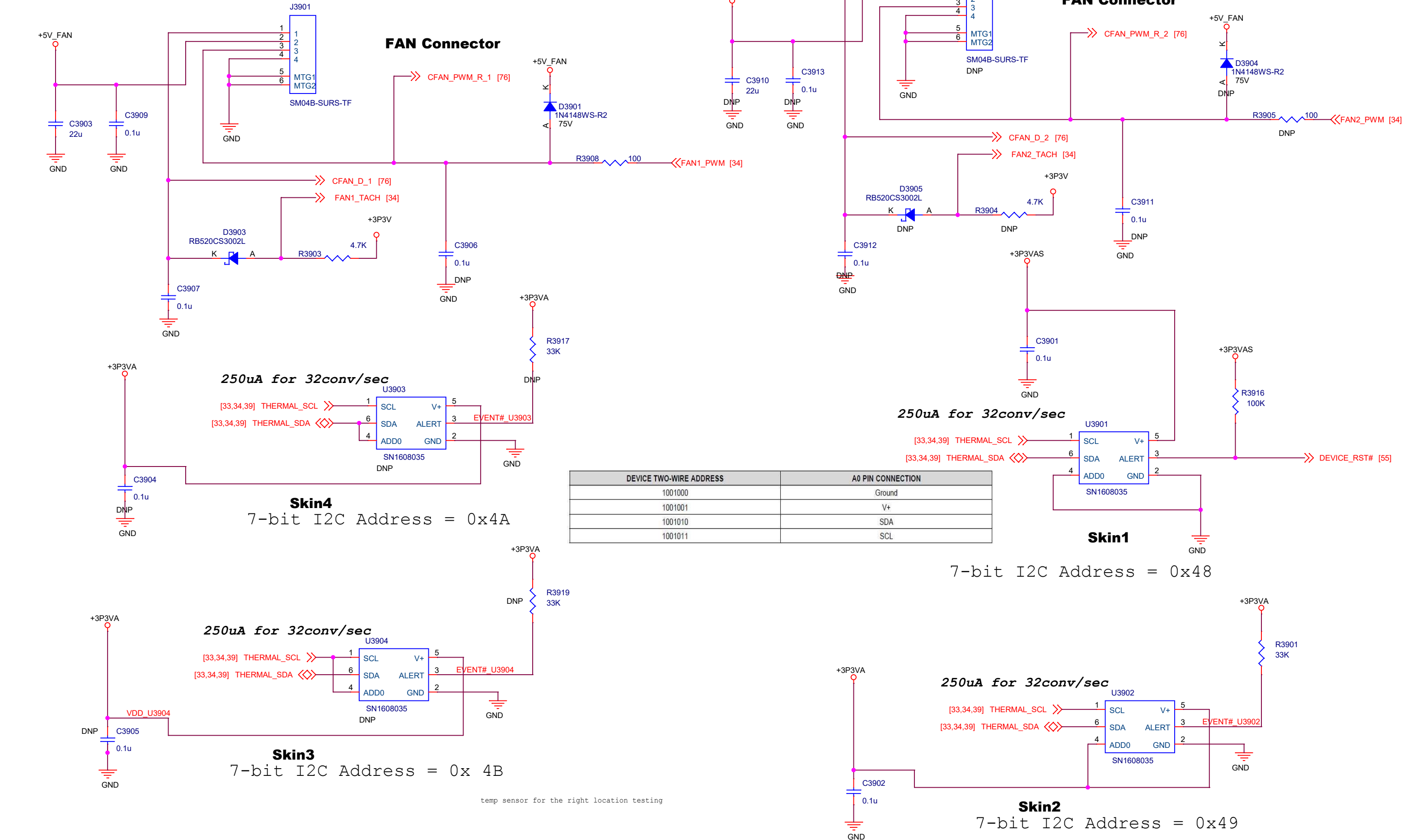
Trusted Platform Module

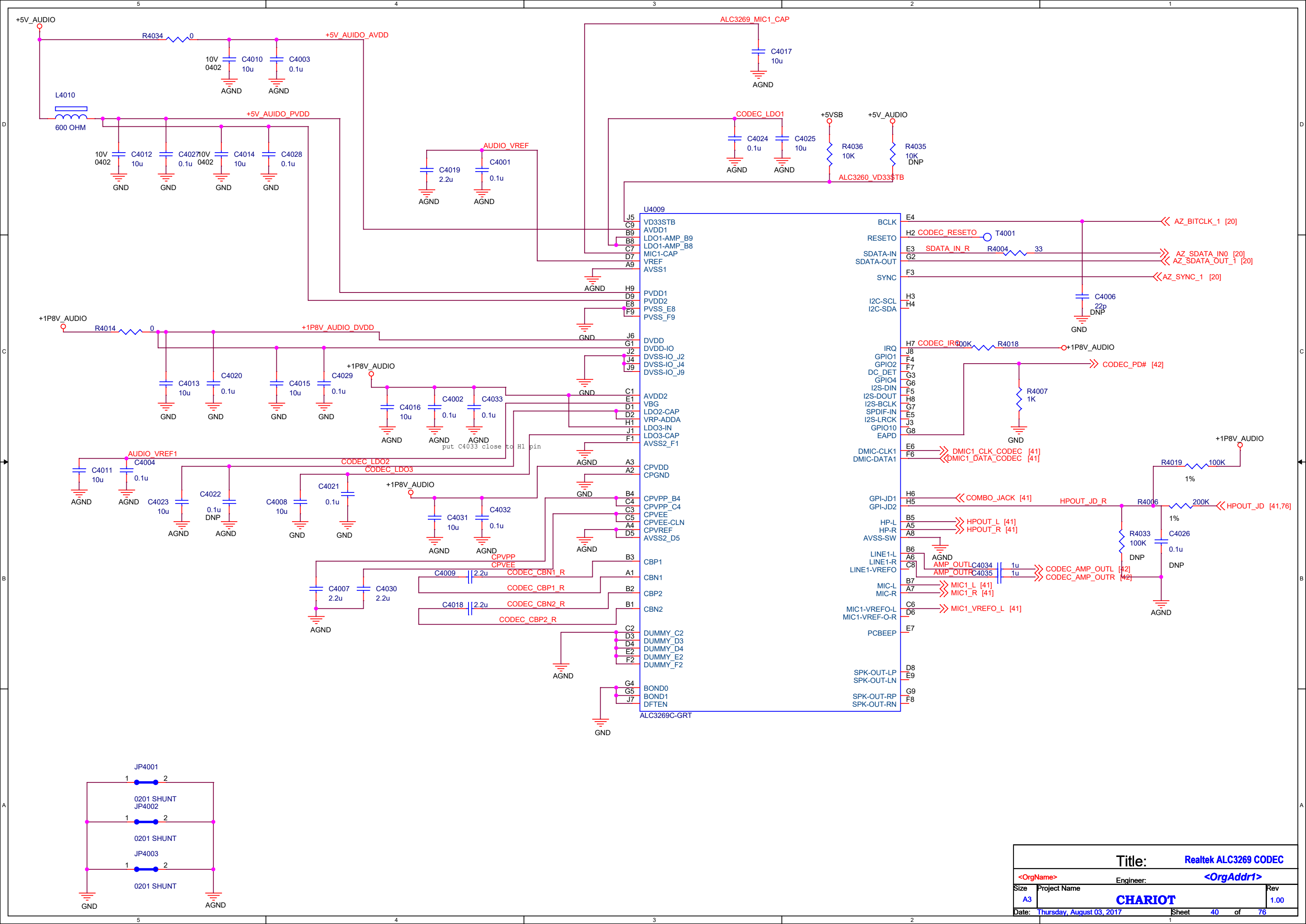


NationZ Z32H320TC do not support CLKRUN# and LPCPD# function
IFX don't have PP funcnction in TPM2.0

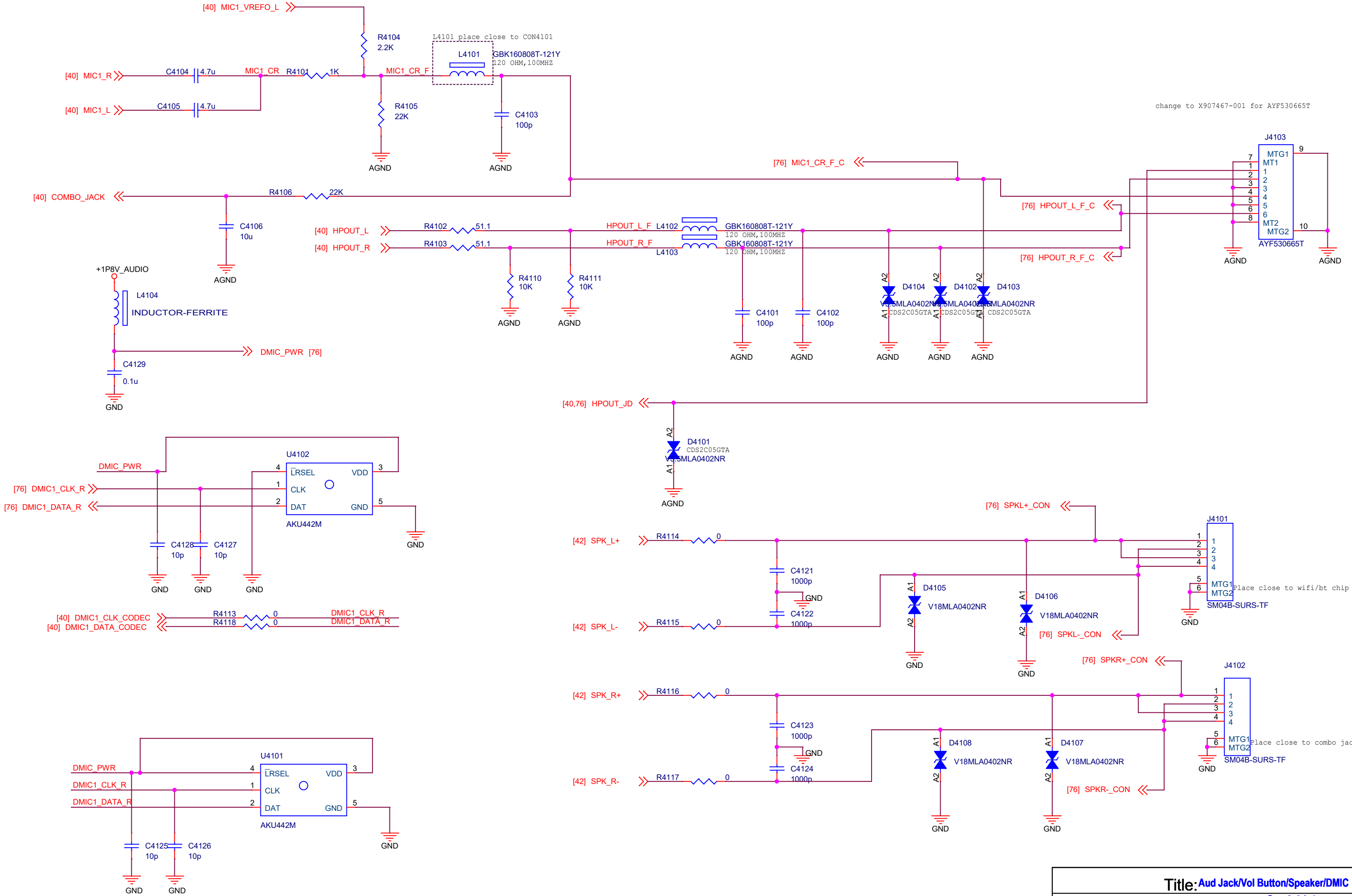
TBL3801			
Ref	Infineon	NationZ	Nuvoton
R2701	X811791-001	NO-STUFF	X811791-001
R2703	NO-STUFF	X811791-001	NO-STUFF
R3814	X852314-001	NO-STUFF	X852314-001
R3815	NO-STUFF	X813010-001	NO-STUFF
R3816	NO-STUFF	X811786-001	NO-STUFF
R3818	NO-STUFF	NO-STUFF	X811786-001
R3819	NO-STUFF	NO-STUFF	X811786-001
R3820	NO-STUFF	NO-STUFF	X811786-001
U3801	X912460-002	X930840-002	M1006791-003

+5V_FAN
Imax=0.7A
Trace Width>30mil





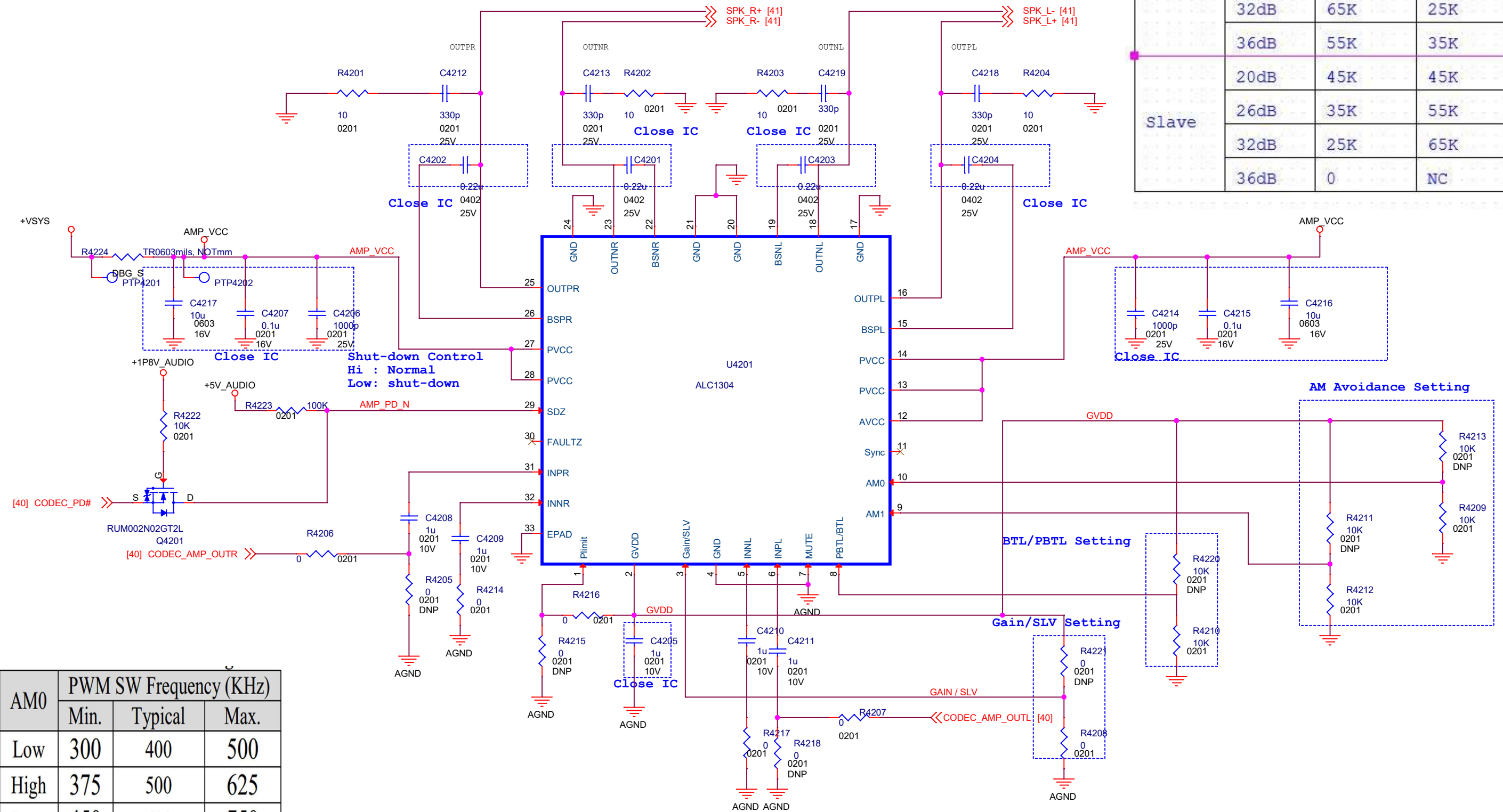
HP/MIC1 Combo Jack



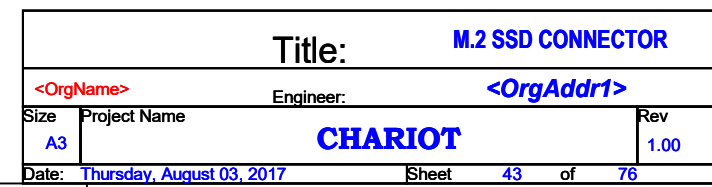
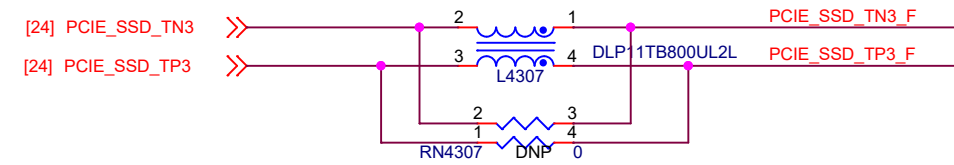
Stereo Input (S.E.) Stereo Output-BTL

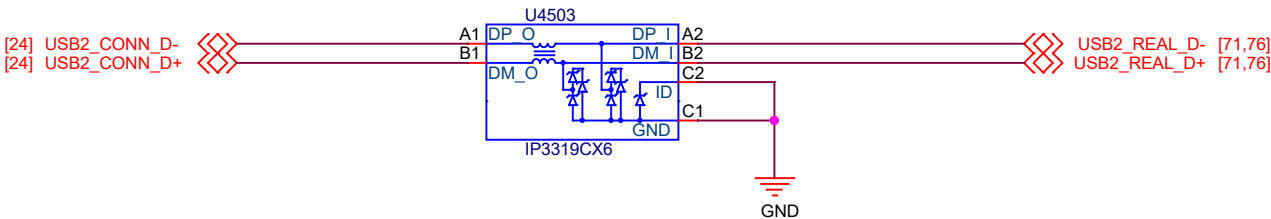
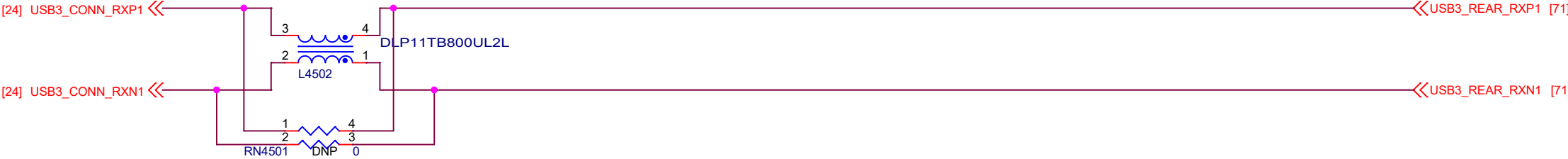
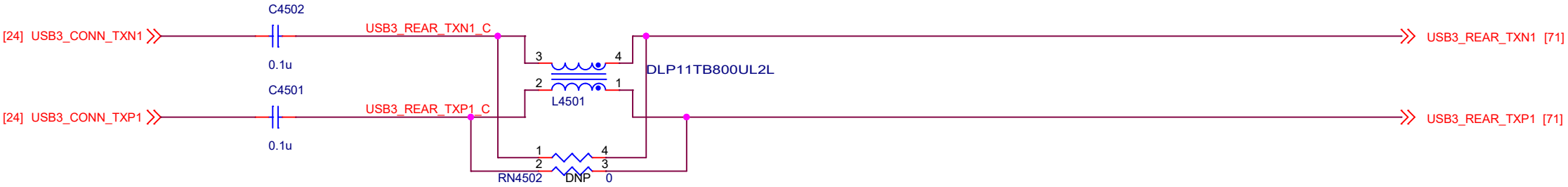
SPKR Trace Width
1. Maximum trace resistance for each channel less than 0.5 ohms.
2. Each of 4 traces, measured from CODEC to speaker connector, less than 0.25 ohms

		R4221	R4208
Mode	Gain	RX (ohm)	RY (ohm)
Master	20dB	NC	0
	26dB	75K	15K
	32dB	65K	25K
	36dB	55K	35K
Slave	20dB	45K	45K
	26dB	35K	55K
	32dB	25K	65K
	36dB	0	NC



AM1	AM0	PWM SW Frequency (KHz)		
		Min.	Typical	Max.
Low	Low	300	400	500
Low	High	375	500	625
High	Low	450	600	750
High	High	750	1000	1250





Note: IP3319CX6 D+ and D- is interchangeable as seen in data sheet. Flipped for layout convenience.

D

D

C

C

B

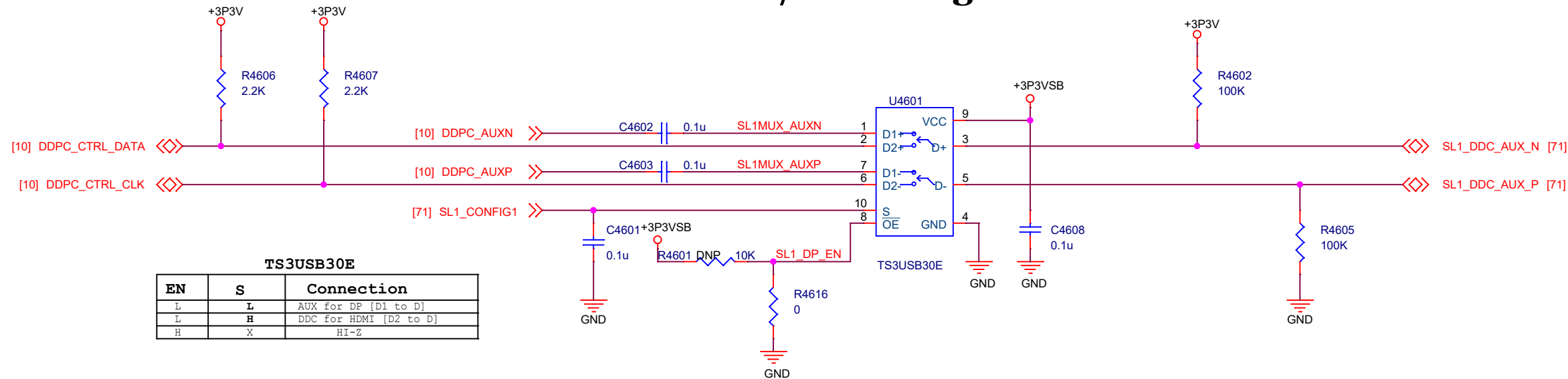
B

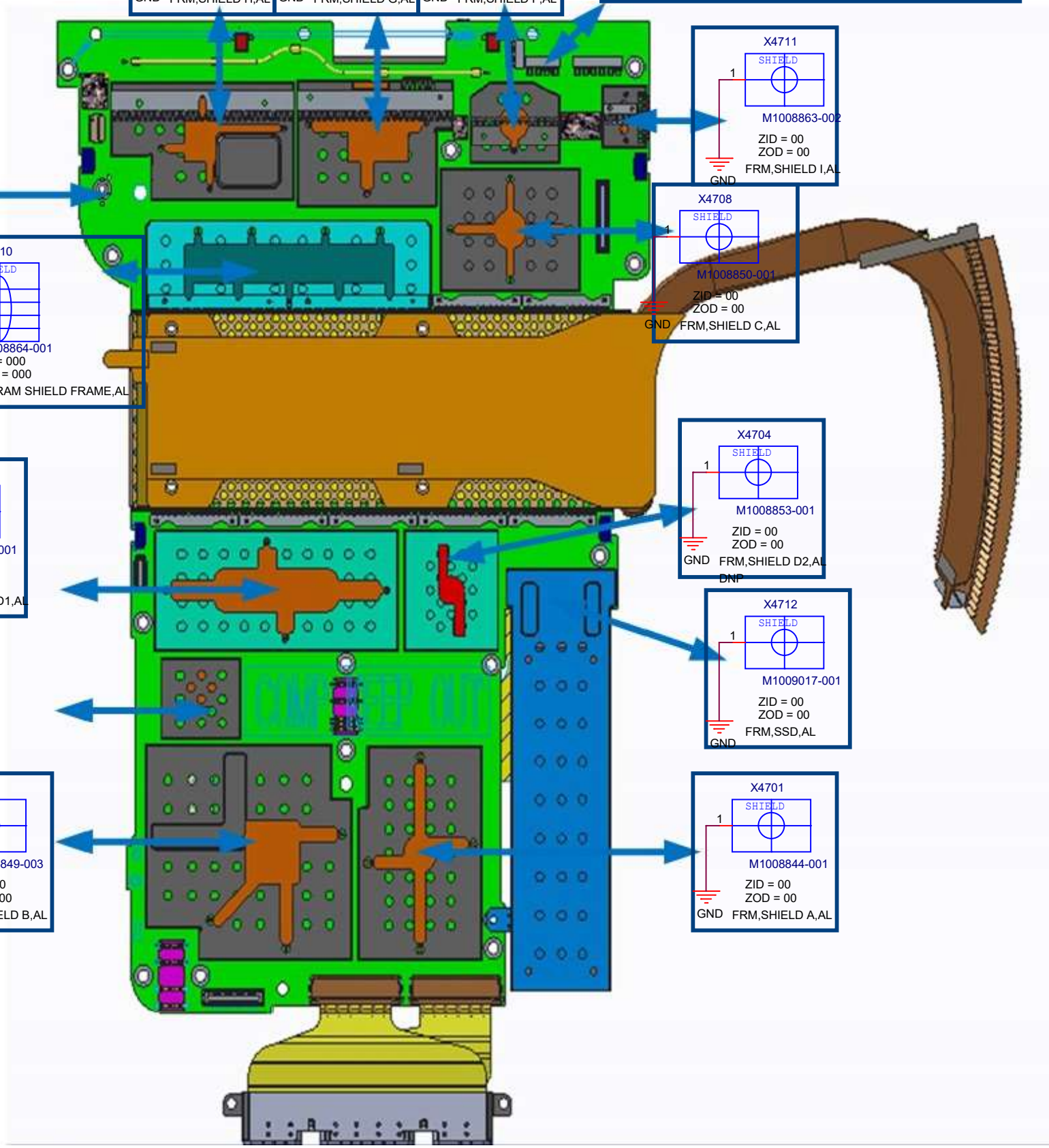
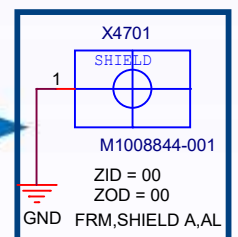
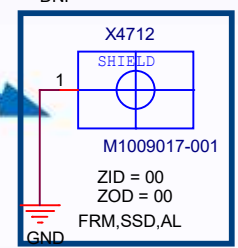
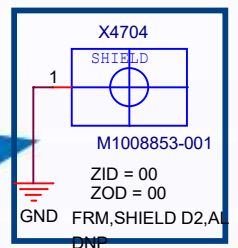
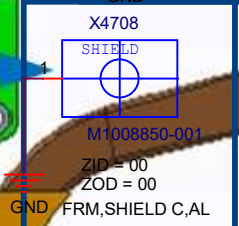
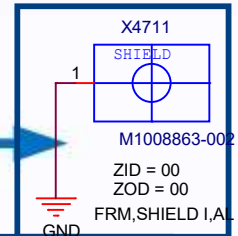
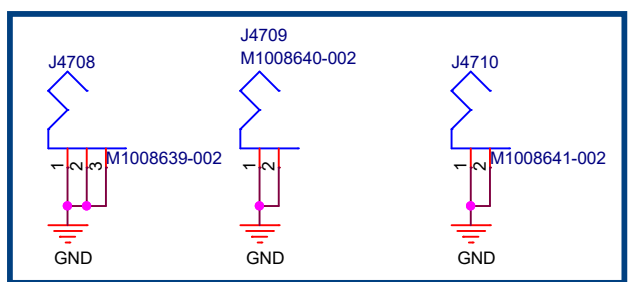
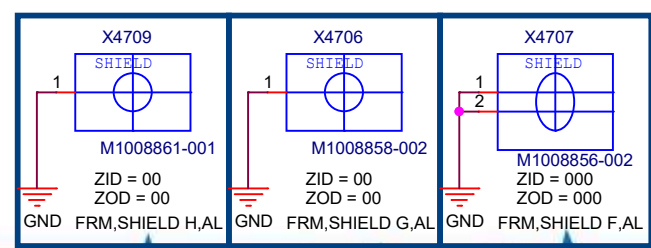
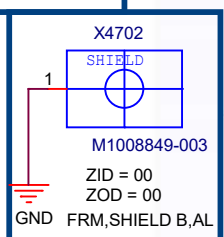
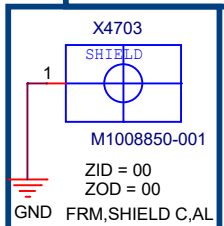
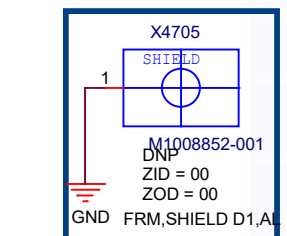
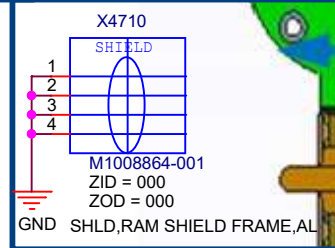
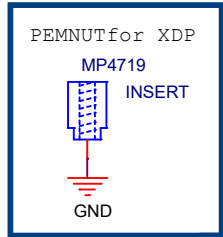
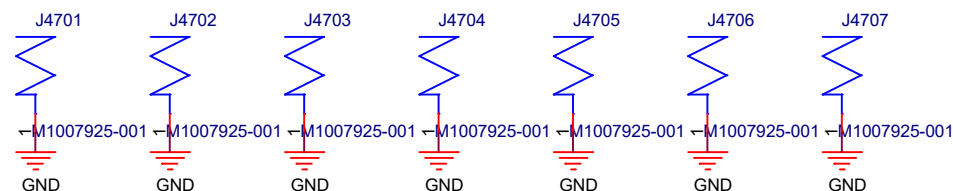
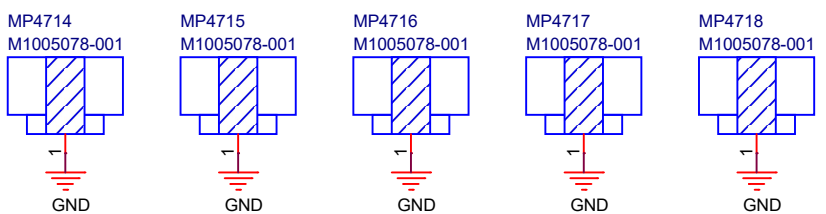
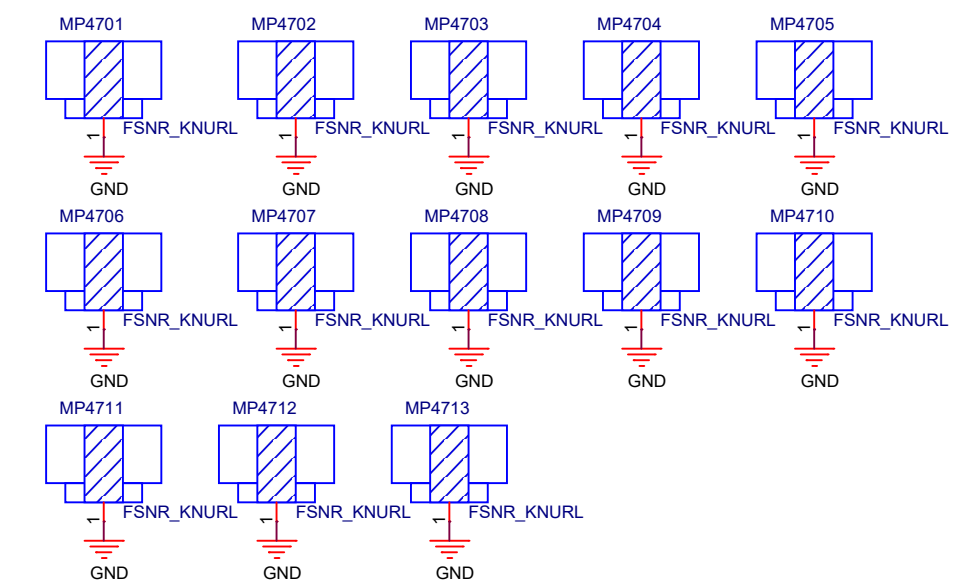
A

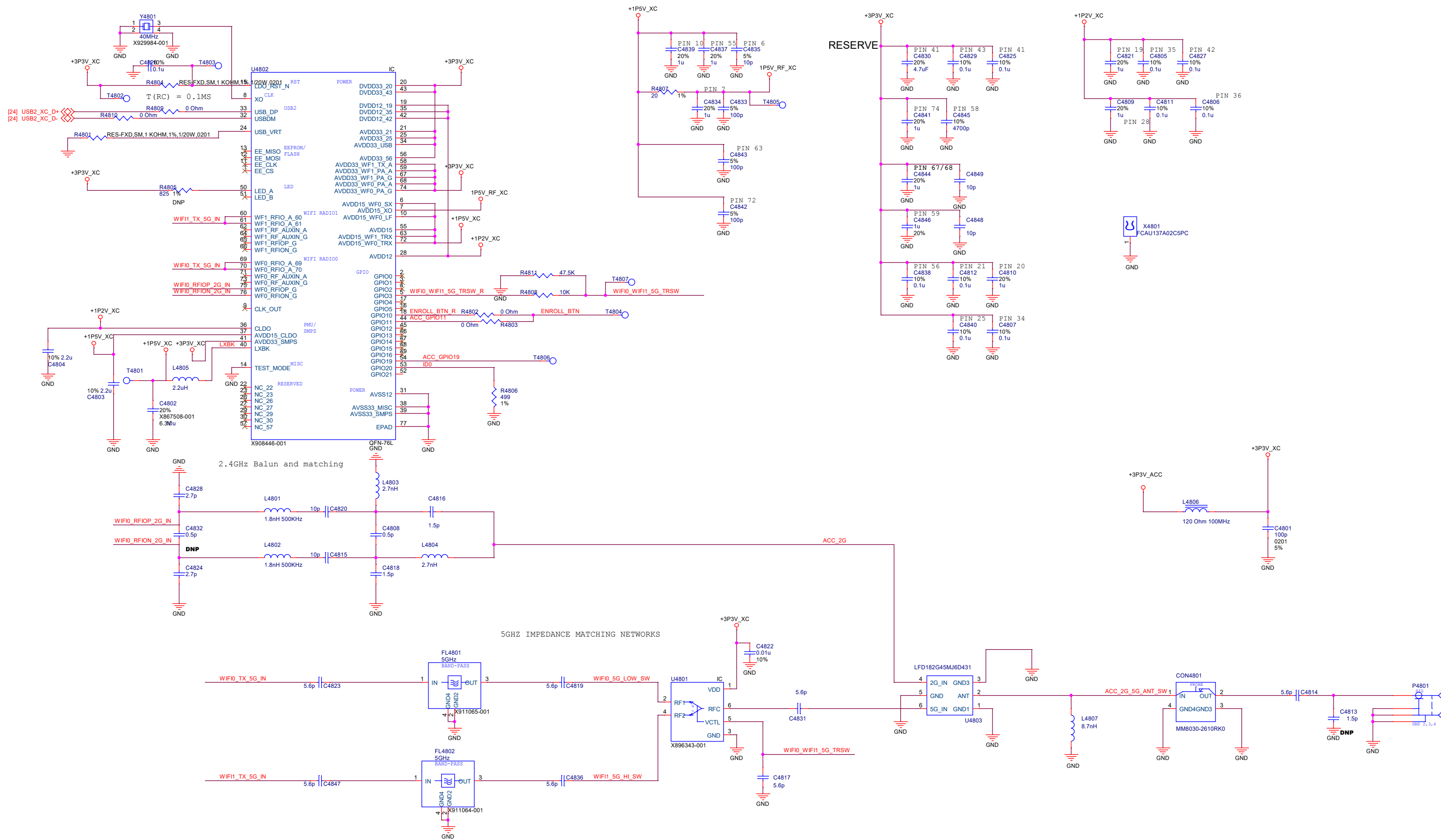
A

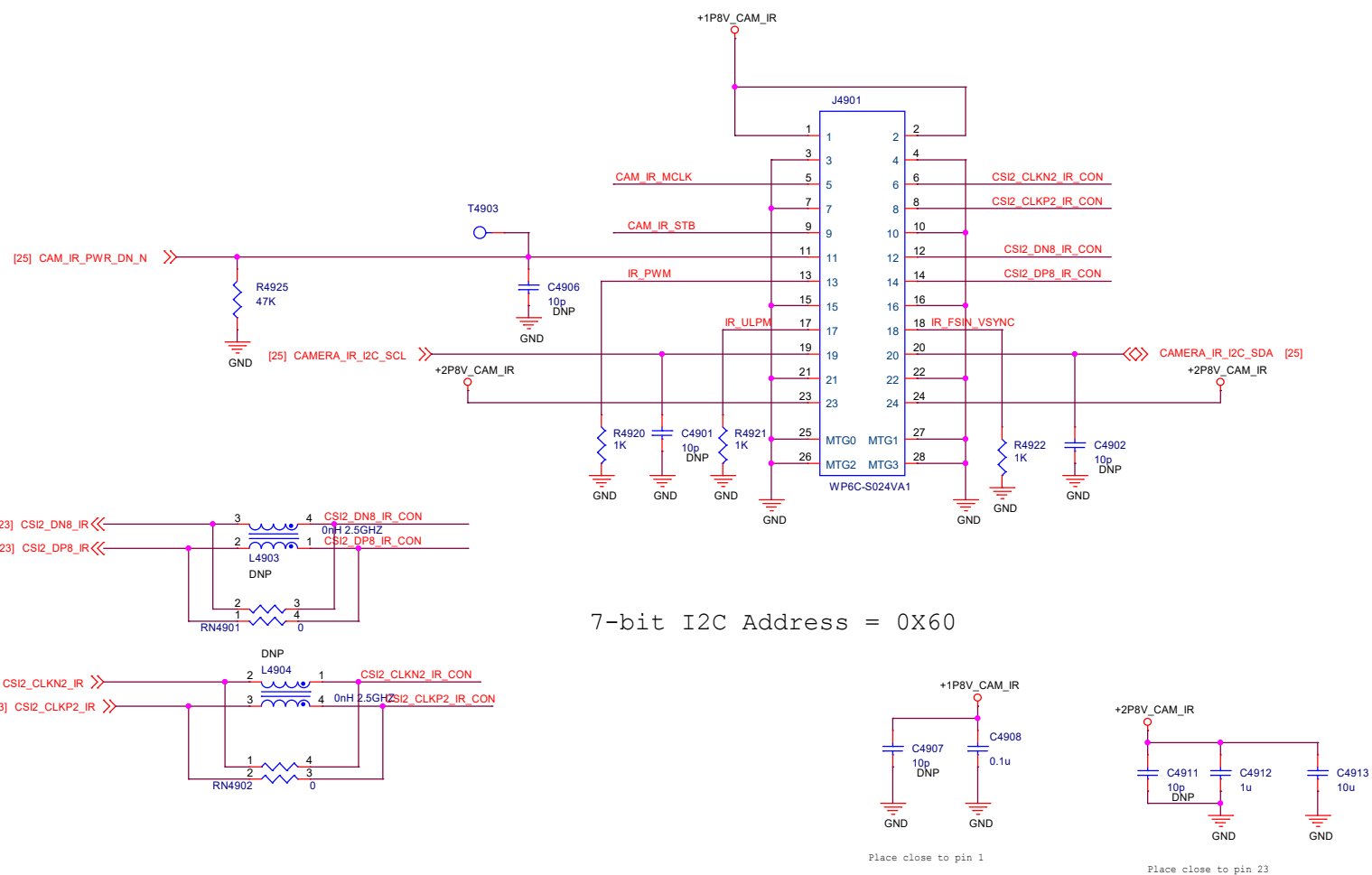
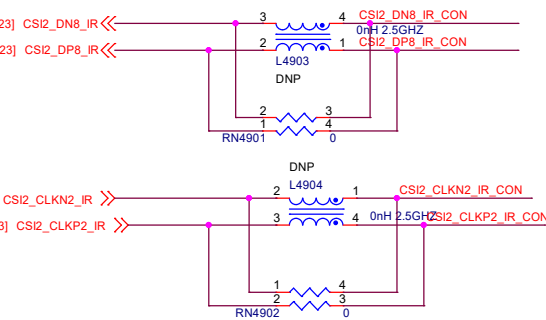
when you TI tsusb30e (X870617-001), NIR4613 and R4601 and install R4615 and R4616

SL1 DP mux to HDMI/DVI Dongle control









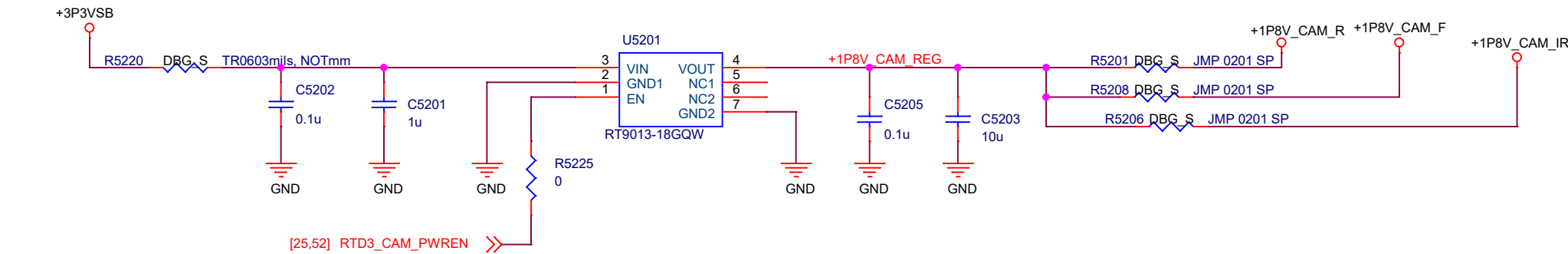
Place close to pin 1

Place close to pin 23



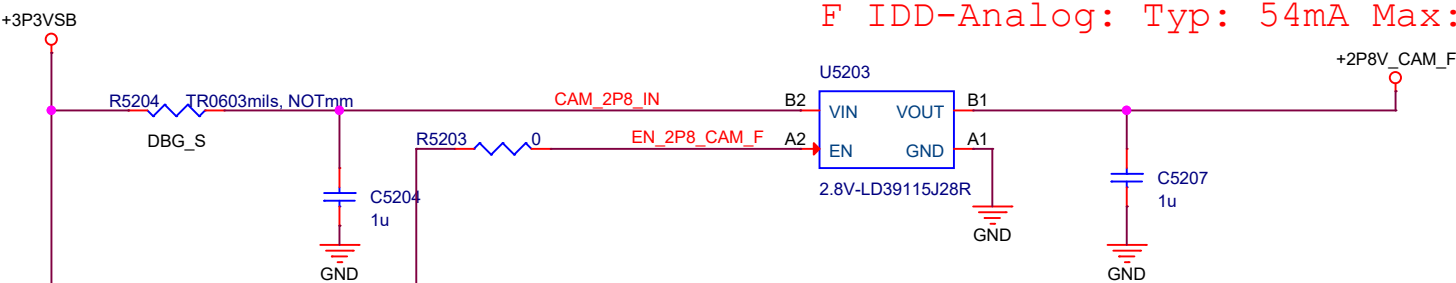
Title: X	
<OrgName>	Engineer: <OrgAddr1>
Size A2	Project Name CHARIOT
Date: Thursday, August 03, 2017	Rev 1.00
Sheet 51 of 76	

IR IDD-IO: Typ: 40mA Max: 55mA
Front IDD-IO+Core: Typ: 67.5mA Max: 93mA
Rear IDD-IO: Typ: 3.3mA Max: 4.5mA

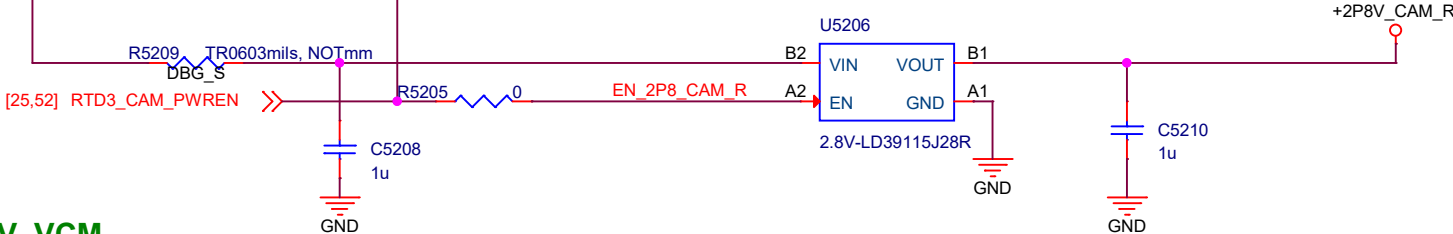


2V8_LDO_Voltage Regulator

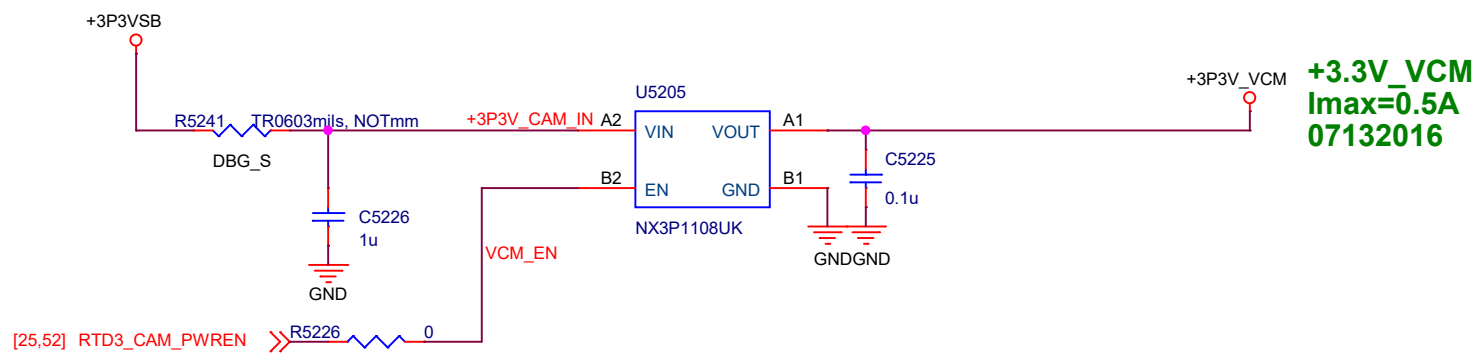
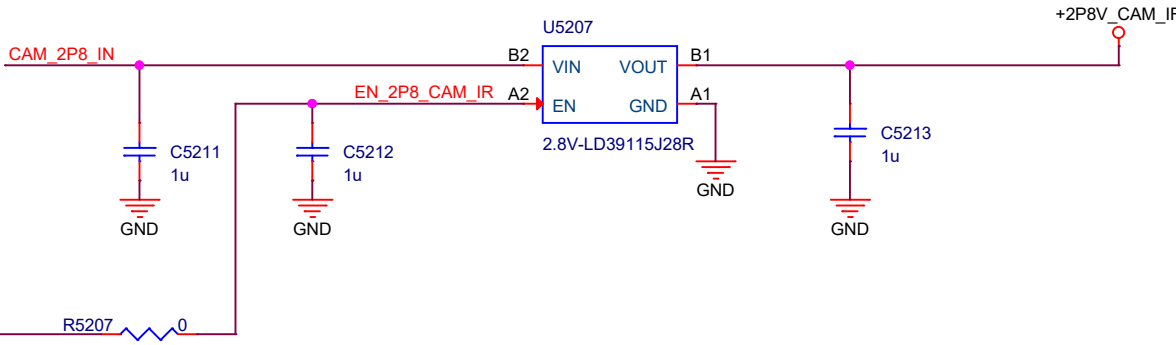
F IDD-Analog: Typ: 54mA Max: 70mA



R IDD-Analog: Typ: 23mA Max: 30mA

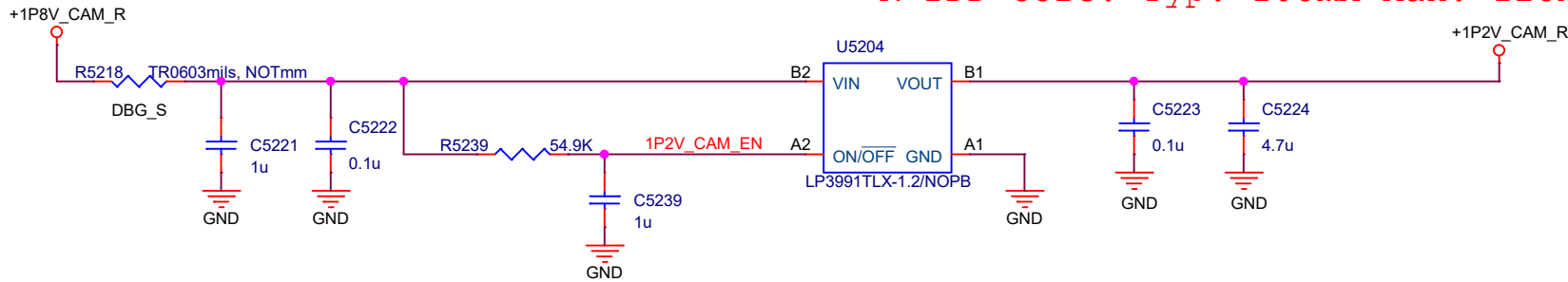


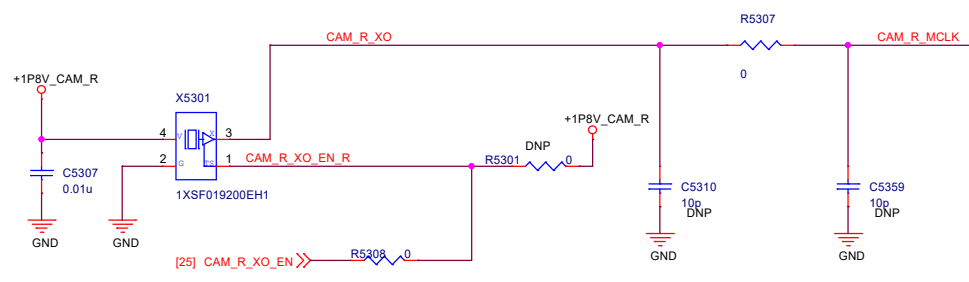
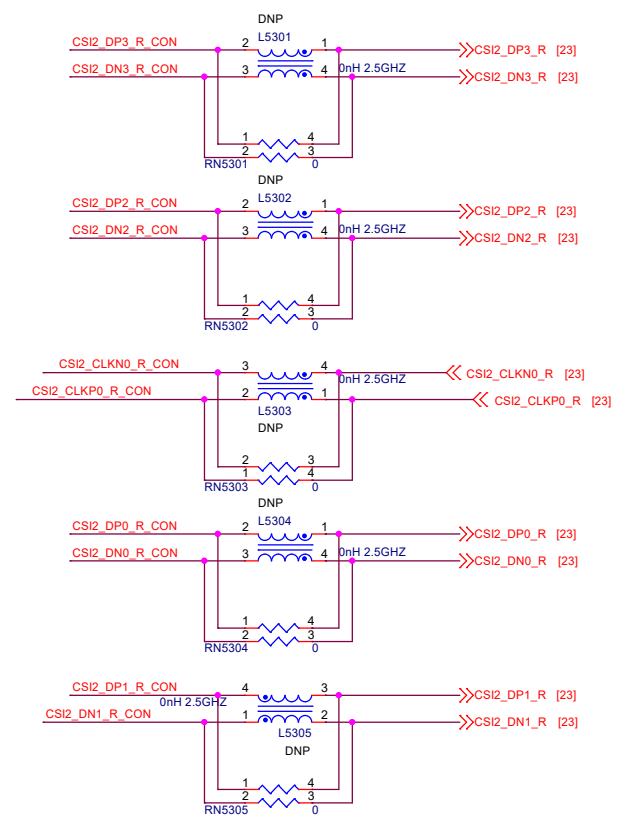
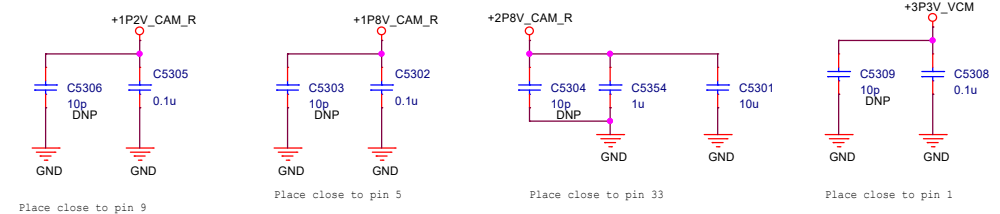
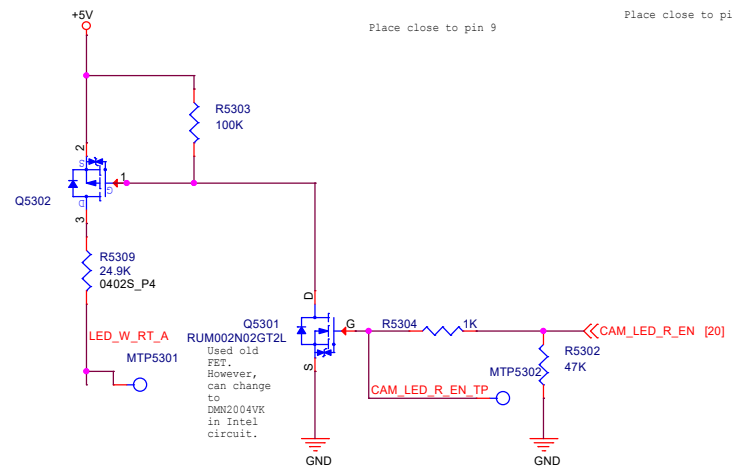
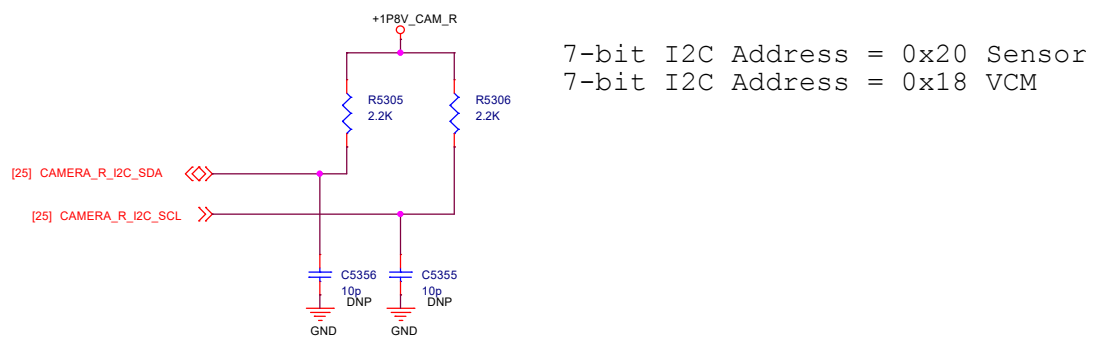
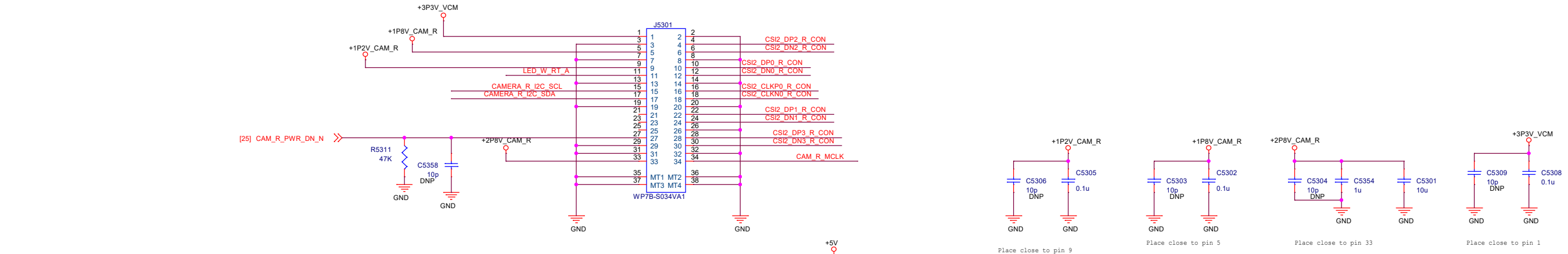
IR IDD-Analog: Typ: 16mA Max: 20mA



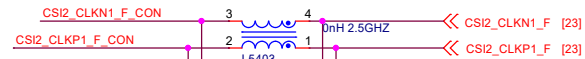
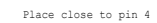
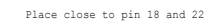
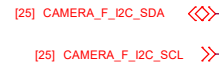
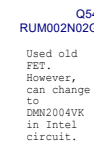
+3.3V_VCM
I_{max}=0.5A
07132016

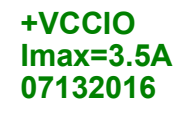
R IDD-Core: Typ: 105mA Max: 125mA





7-bit I2C Address = 0x10 Sensor
7-bit I2C Address = 0x0C VCM

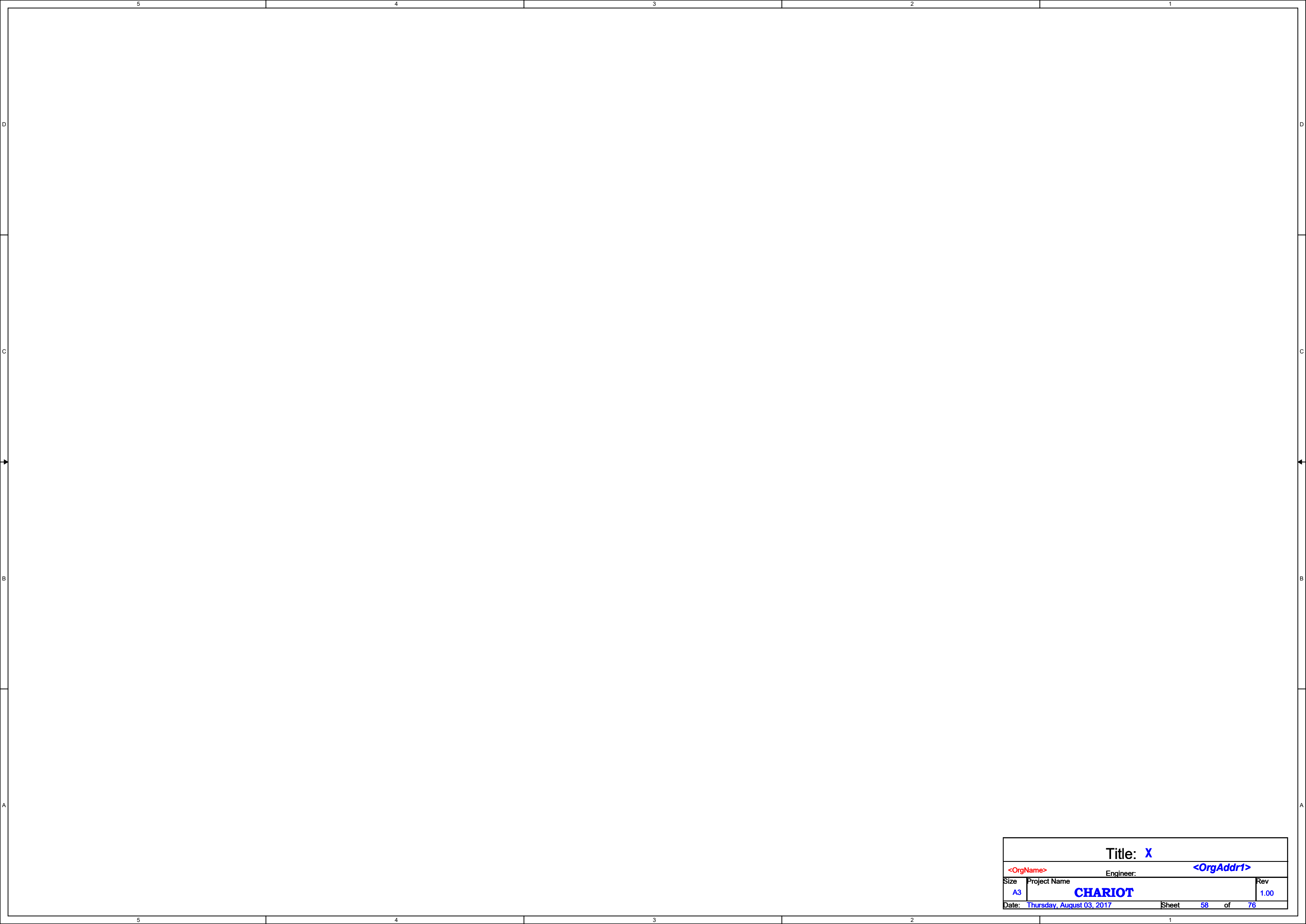


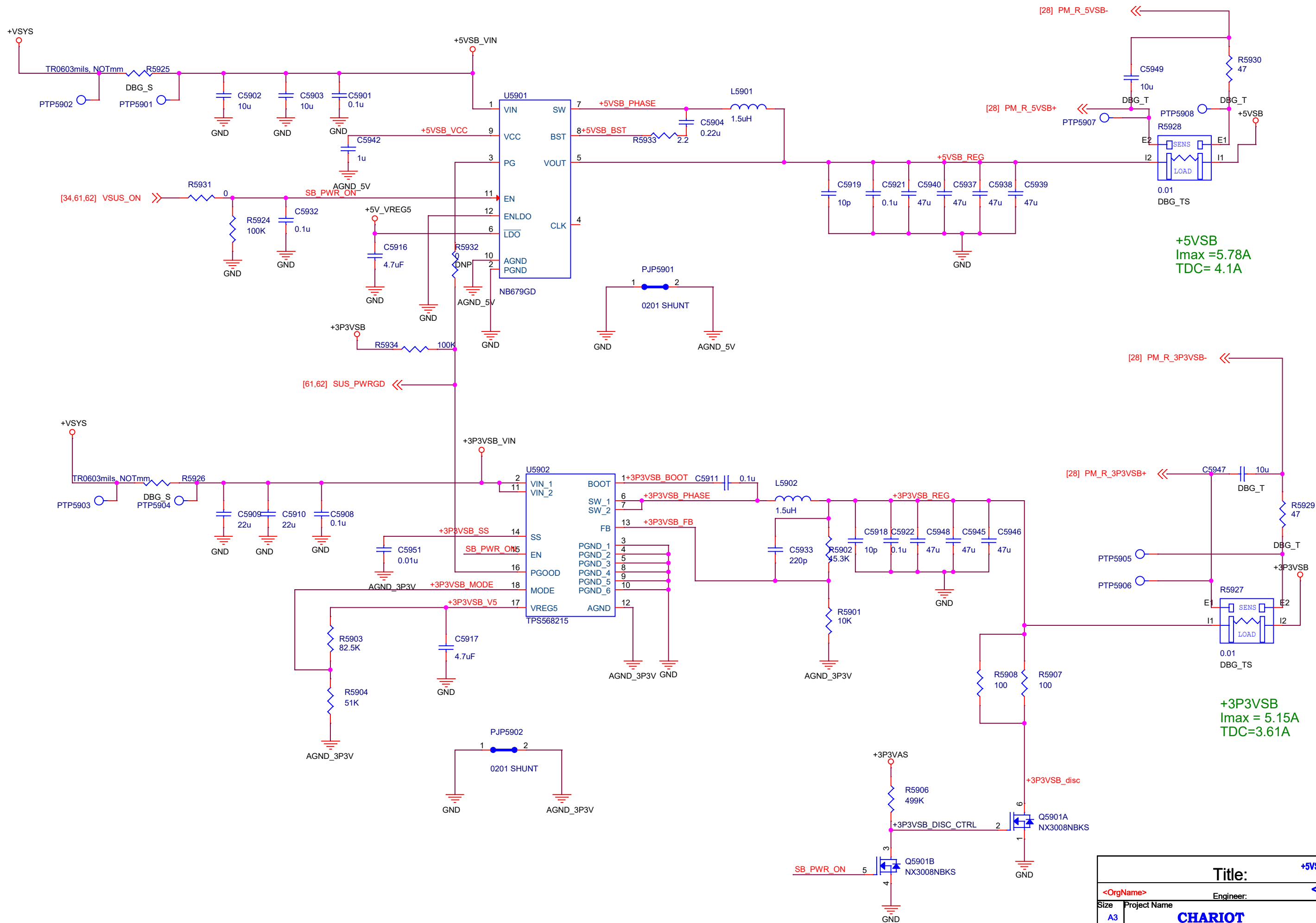


<div> <div>Title:</div> <div>+VCCIO</div> </div>			
<div> <div><OrgName></div> <div>Engineer:</div> </div>		<div> <div><OrgAddr1></div> </div>	
<div> <div>Size</div> <div>A3</div> </div>	<div> <div>Project Name</div> <div>CHARIOT</div> </div>		<div> <div>Rev</div> <div>1.00</div> </div>
<div> <div>Date:</div> <div>Thursday, August 03, 2017</div> </div>		<div> <div>Sheet</div> <div>56</div> <div>of</div> <div>76</div> </div>	

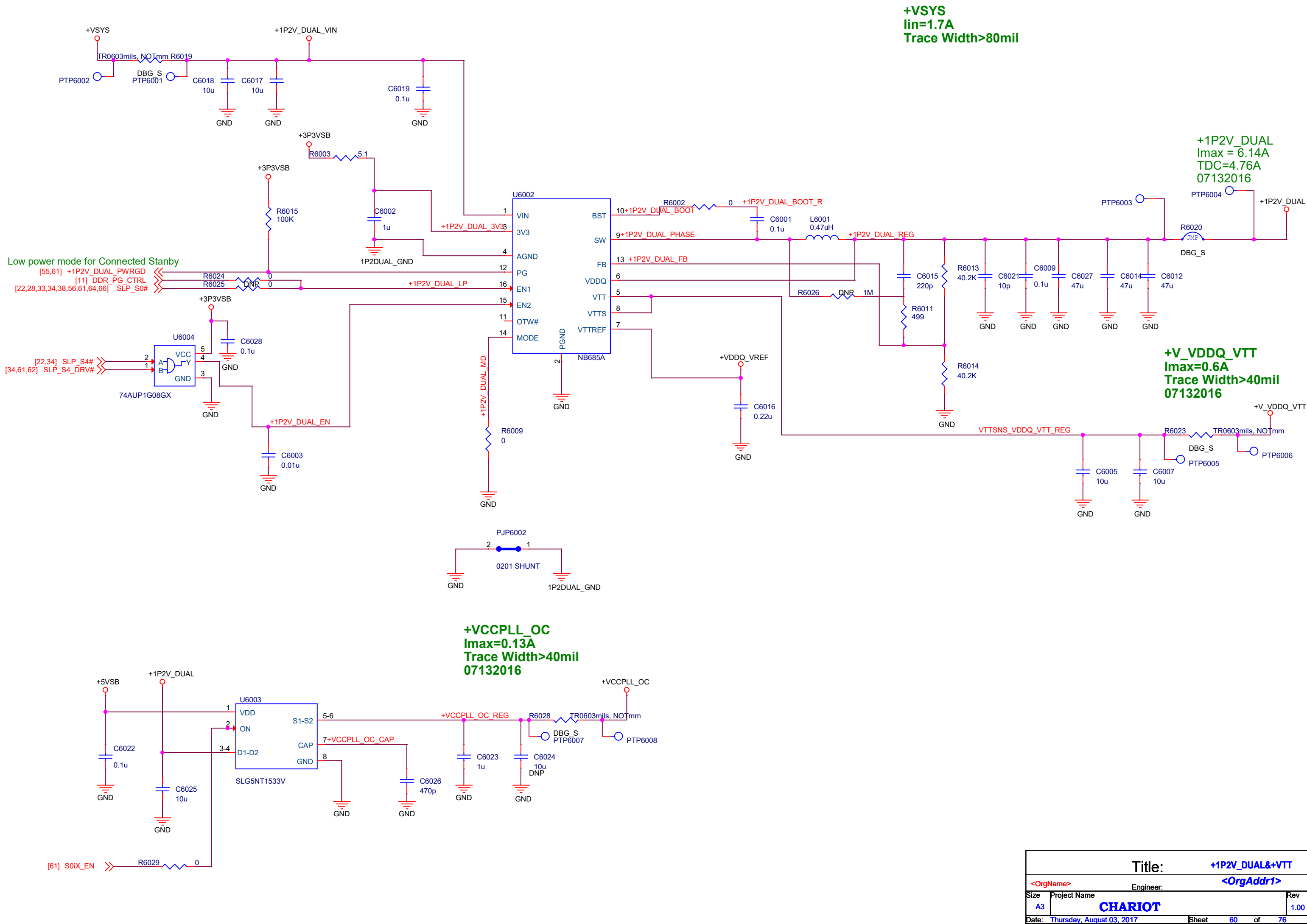


1

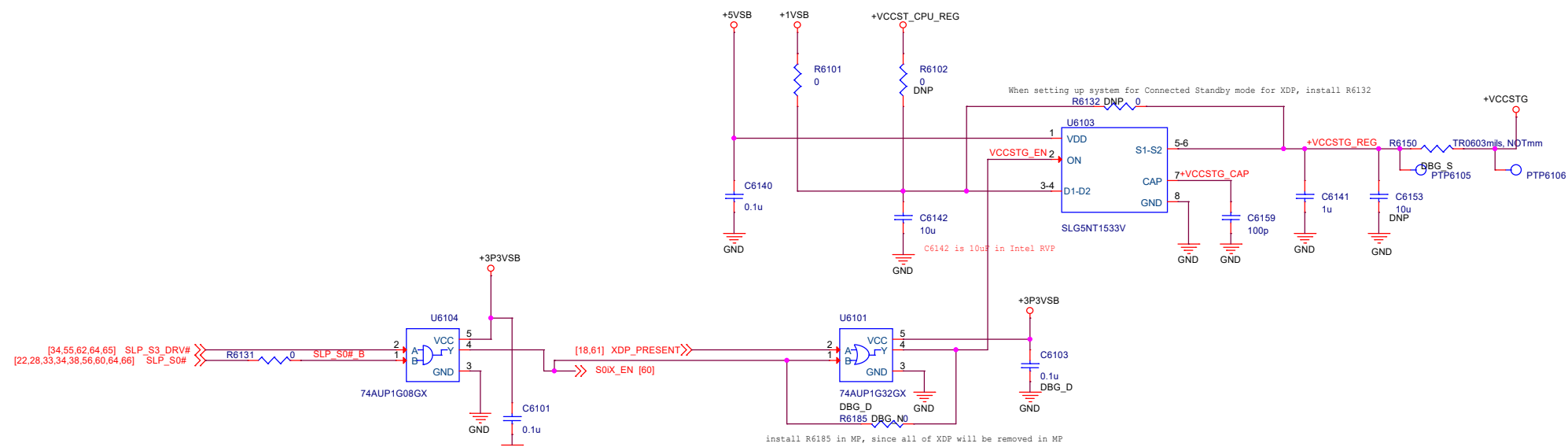
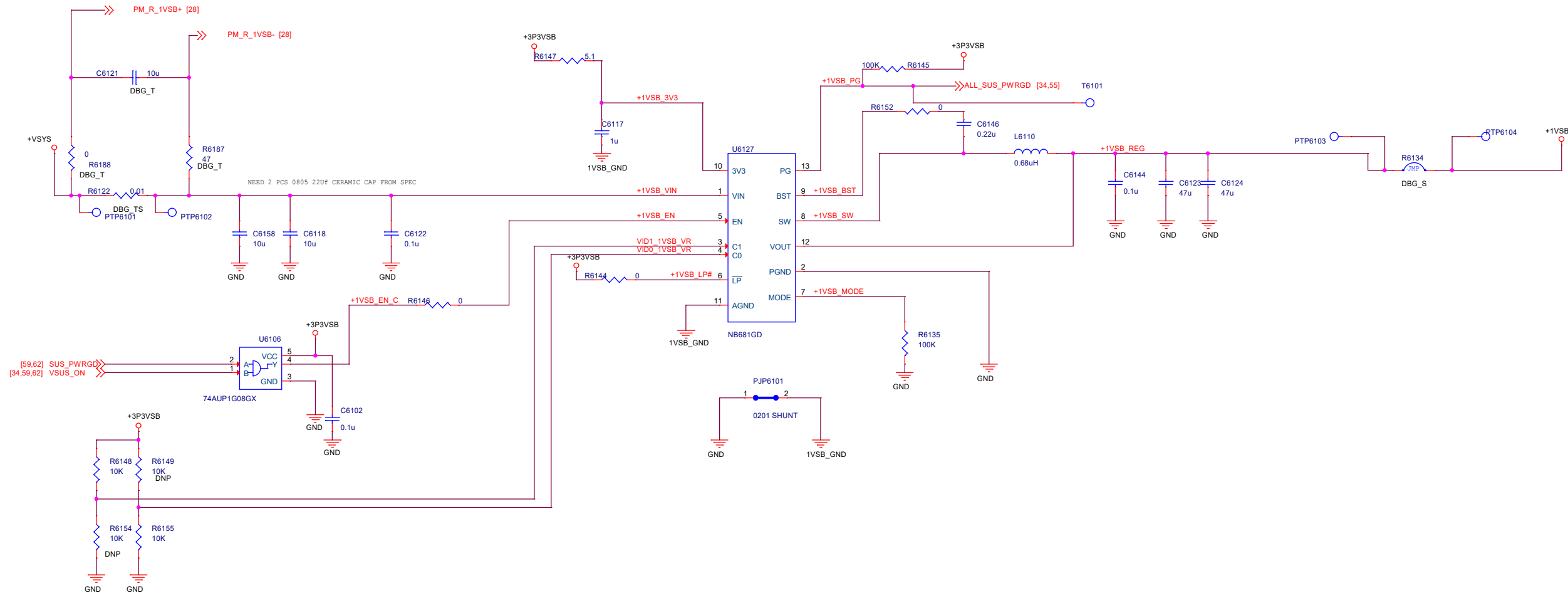




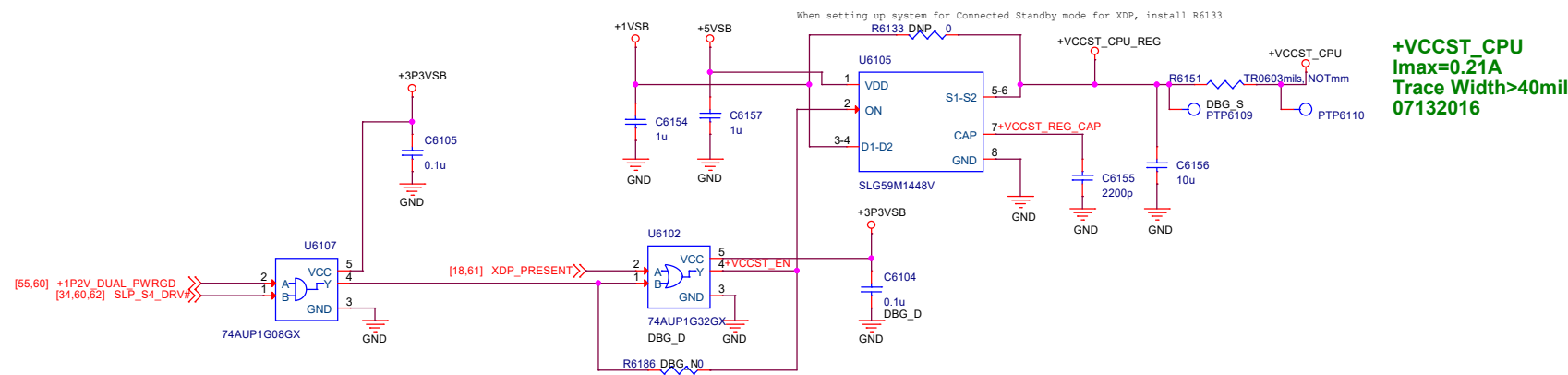
Title: +5VSB & +3P3VSB	
<OrgName>	Engineer: <OrgAddr1>
Size A3	Project Name CHARIOT
Date: Thursday, August 03, 2017	Rev 1.00
Sheet 59	of 76



Title:		+1P2V_DUAL+VTT	
<OrgName>		Engineer:	
Size	Project Name	Rev	
A3	CHARIOT	1.00	
Date:	Thursday, August 03, 2017	Sheet	60 of 76

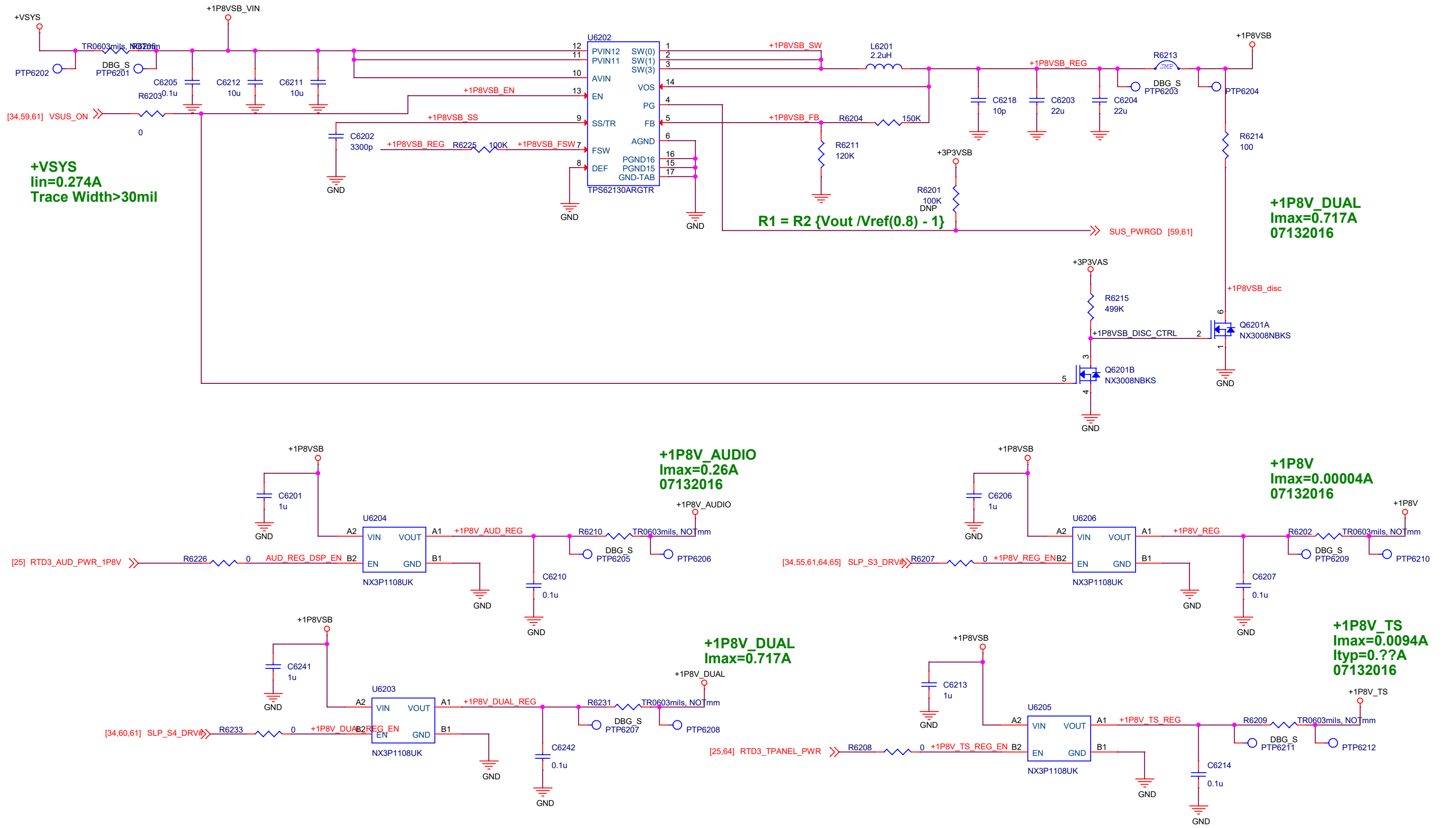


+VCCSTG
Imax=0.02A
Trace Width>40mil
07132016

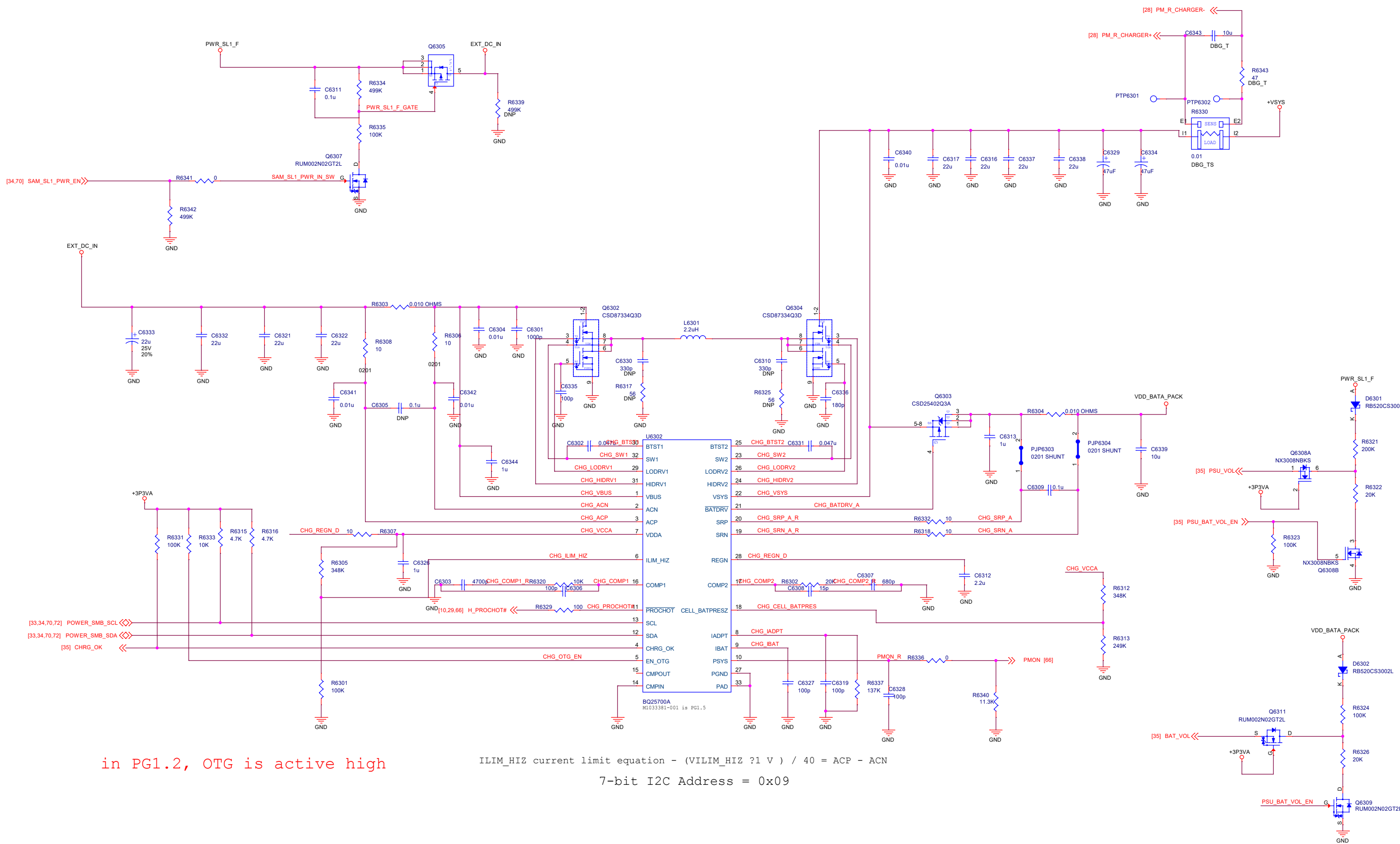


+VCCST CPU
Imax=0.21A
Trace Width>40mil
07132016

Title: +1VSB	
Engineer: <OrgAddrt>	
Project Name: CHARIOT	Rev: 1.00
Date: Thursday, August 03, 2017	Sheet: 61 of 76



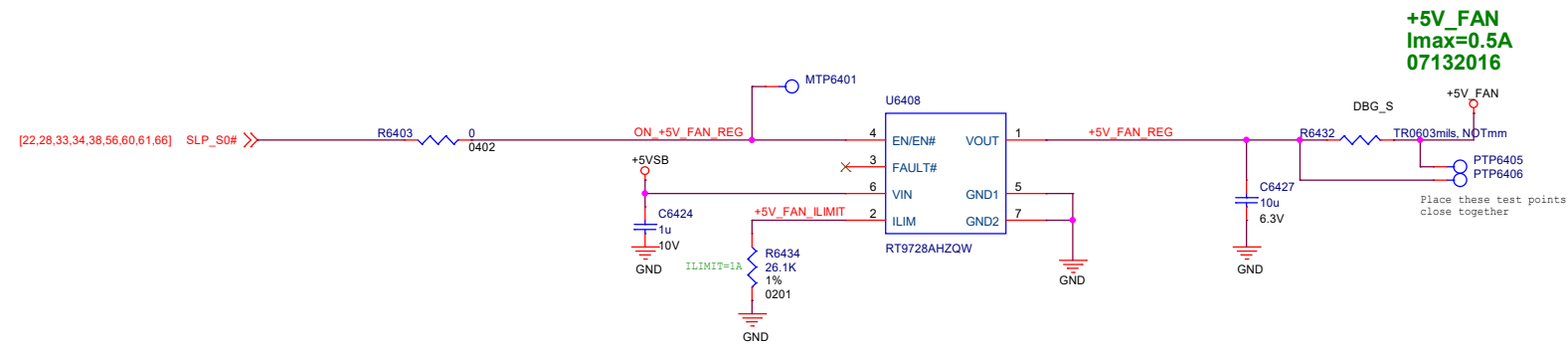
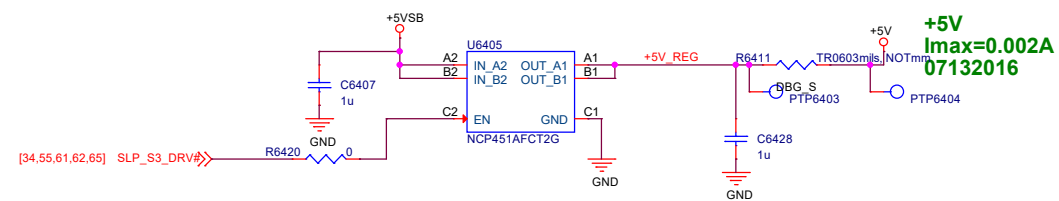
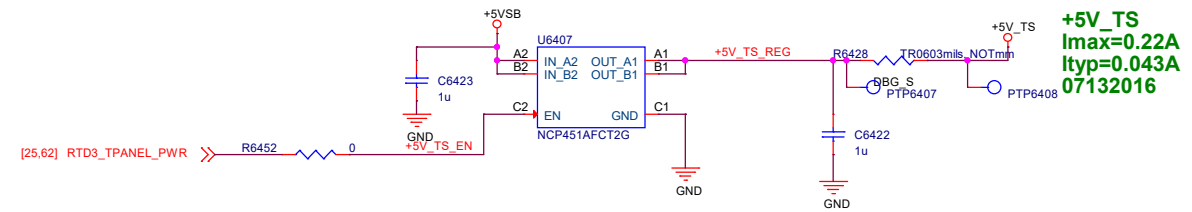
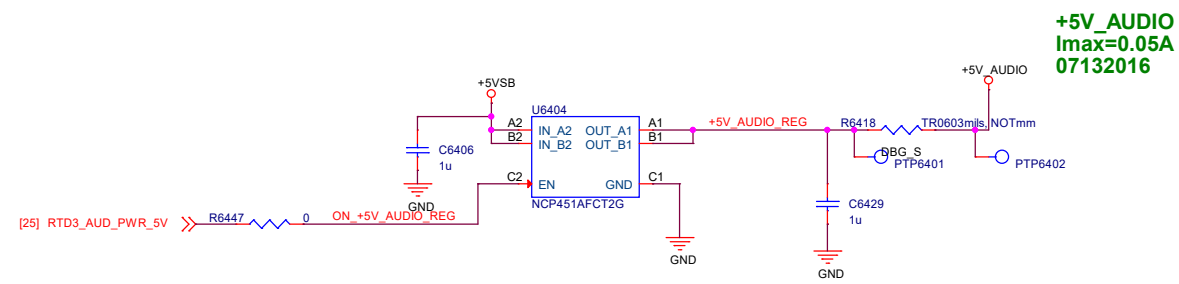
+VSY: 6V(TBD) to 8.75V

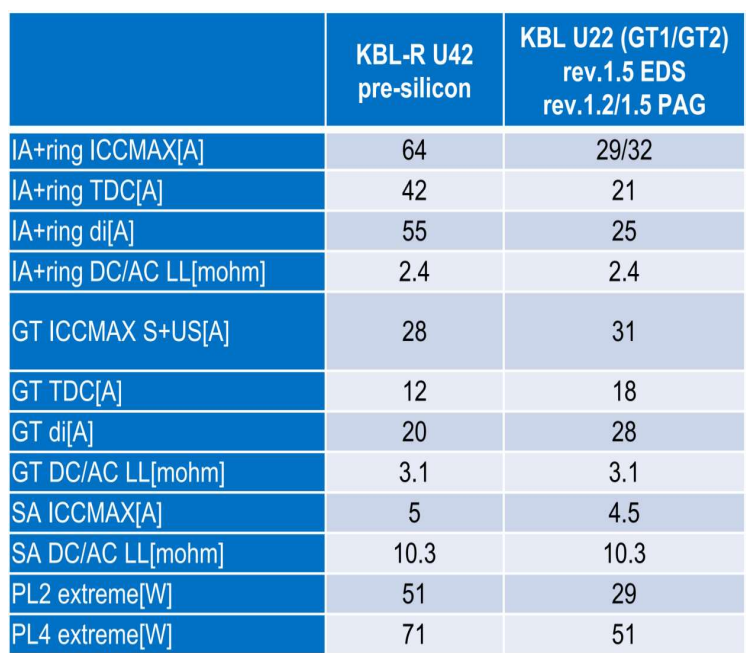


in PG1.2, OTG is active high

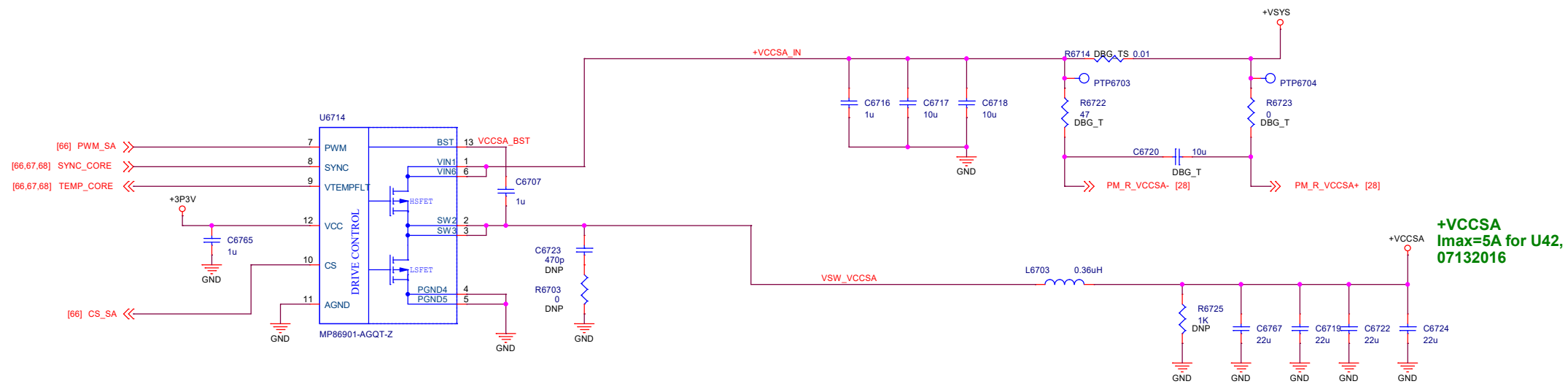
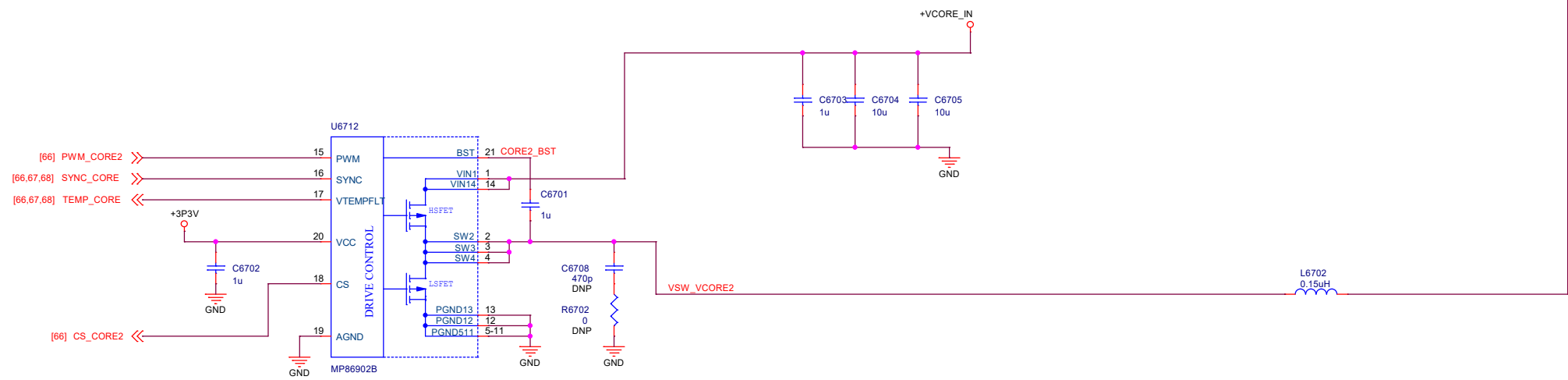
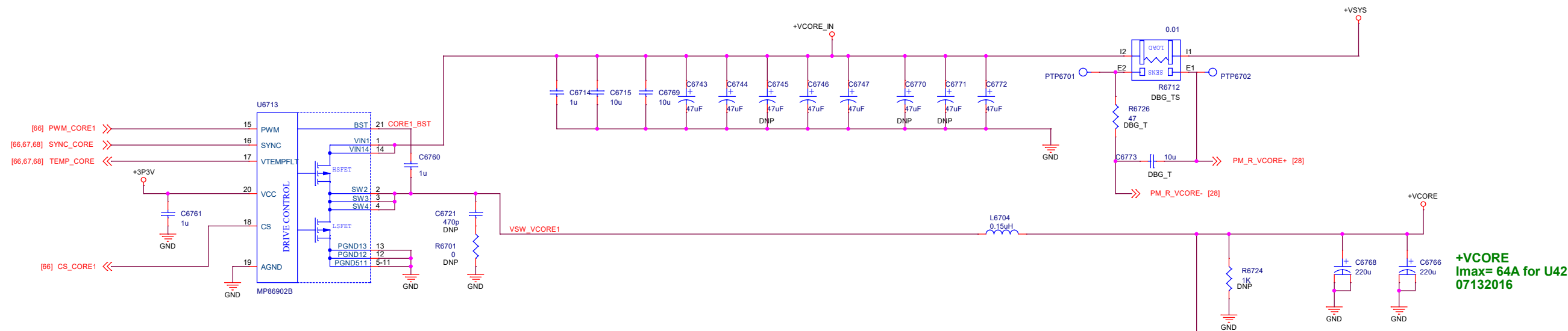
ILIM_HIZ current limit equation - (VILIM_HIZ ?1 V) / 40 = ACP - ACN
7-bit I2C Address = 0x09

Title: CHARGER	
Engineer: <OrgAddr1>	
Size A2	Project Name CHARIOT
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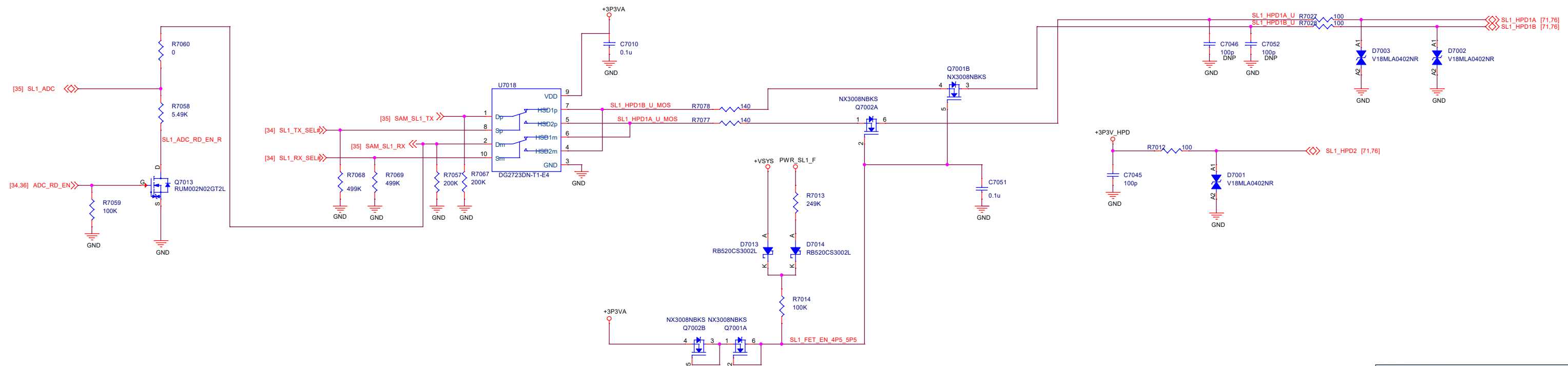




Title:		VCPU controller	
<OrgName>		<OrgAddr1>	
Size	Project Name	Engineer	Rev
A2	CHARIOT		1.00
Date:	Thursday, August 03, 2017	Sheet	66 of 76

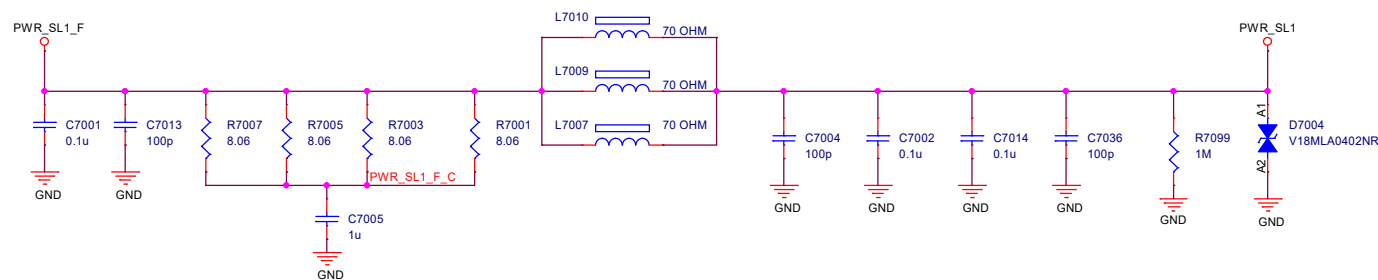
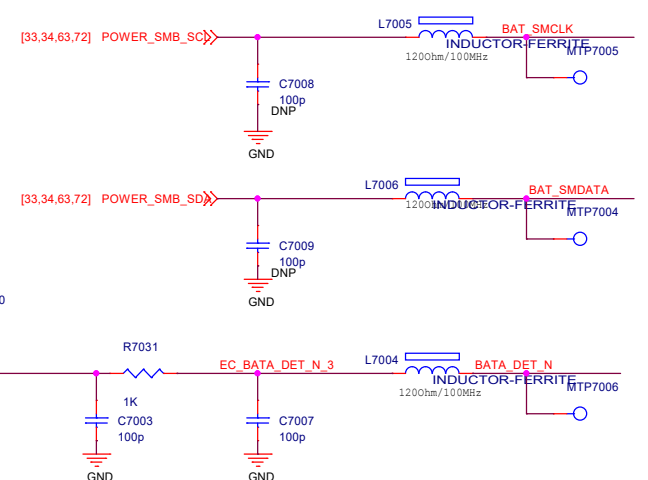


HPD FOR SL1 (ONE/TWO WIRE UART)

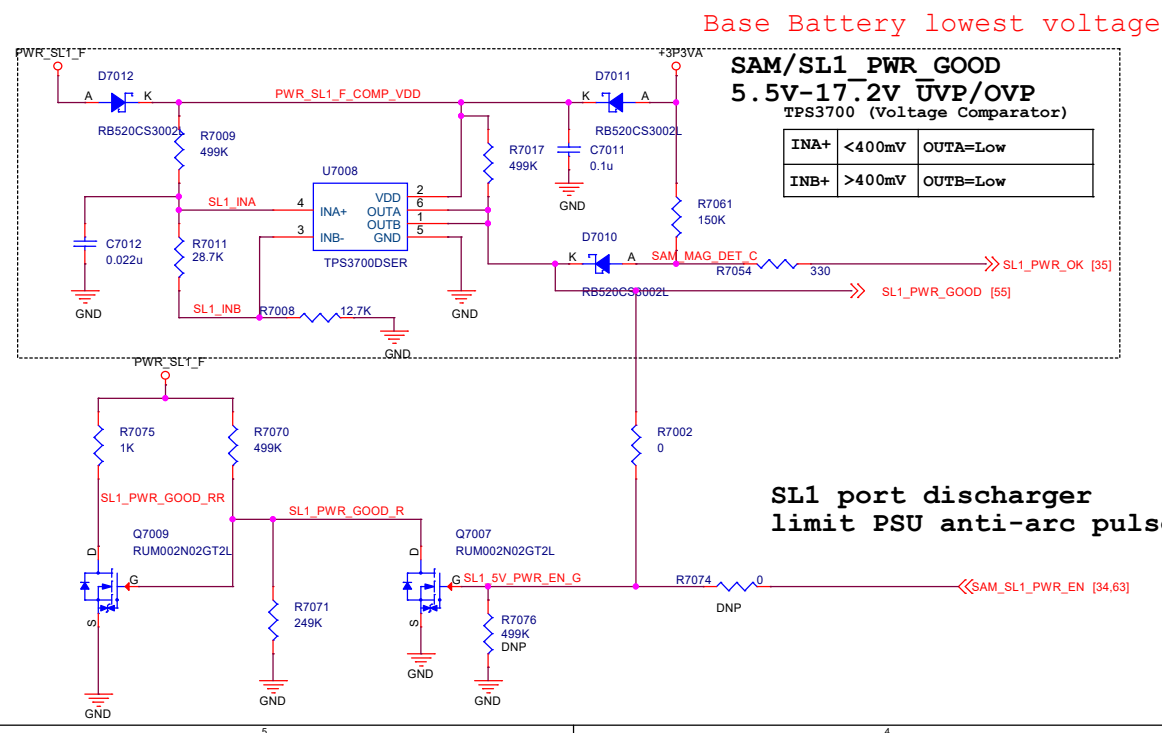


TRUTH TABLE		
S+ (PIN 8)	S- (PIN 10)	FUNCTION
X	0	D- = HSD1-
X	1	D- = HSD2-
0	X	D+ = HSD1+
1	X	D+ = HSD2+

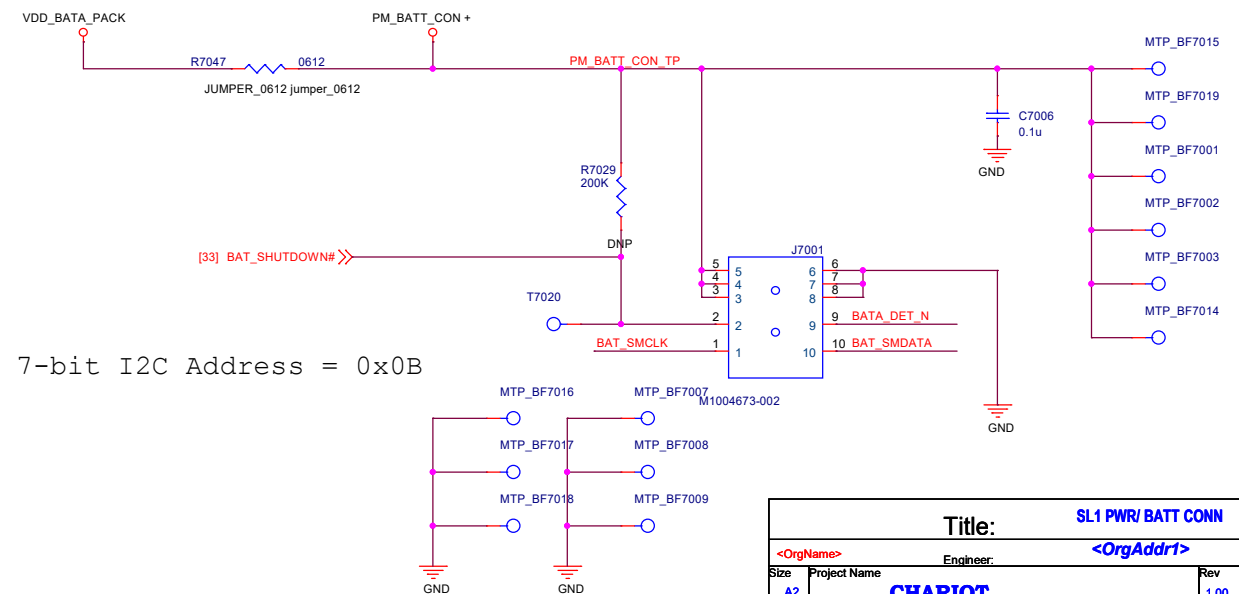
Present State			Trigger	Output		
SL1_UART_TX	SL1_UART_RX	1W/2W Detect	Initial A/D read	SL1_UART_TX_SEL_N	SL1_UART_RX_SEL_N	SL Polarity
Low	Low	Detach	n/a	Low	Low	Detach
Low	High	1W	n/a	High	Low	Straight up
High	Low	1W	n/a	Low	High	Reversed
High	High	2W	Valid	Low	Low	Straight up
High	High	2W	Invalid	High	High	Reversed



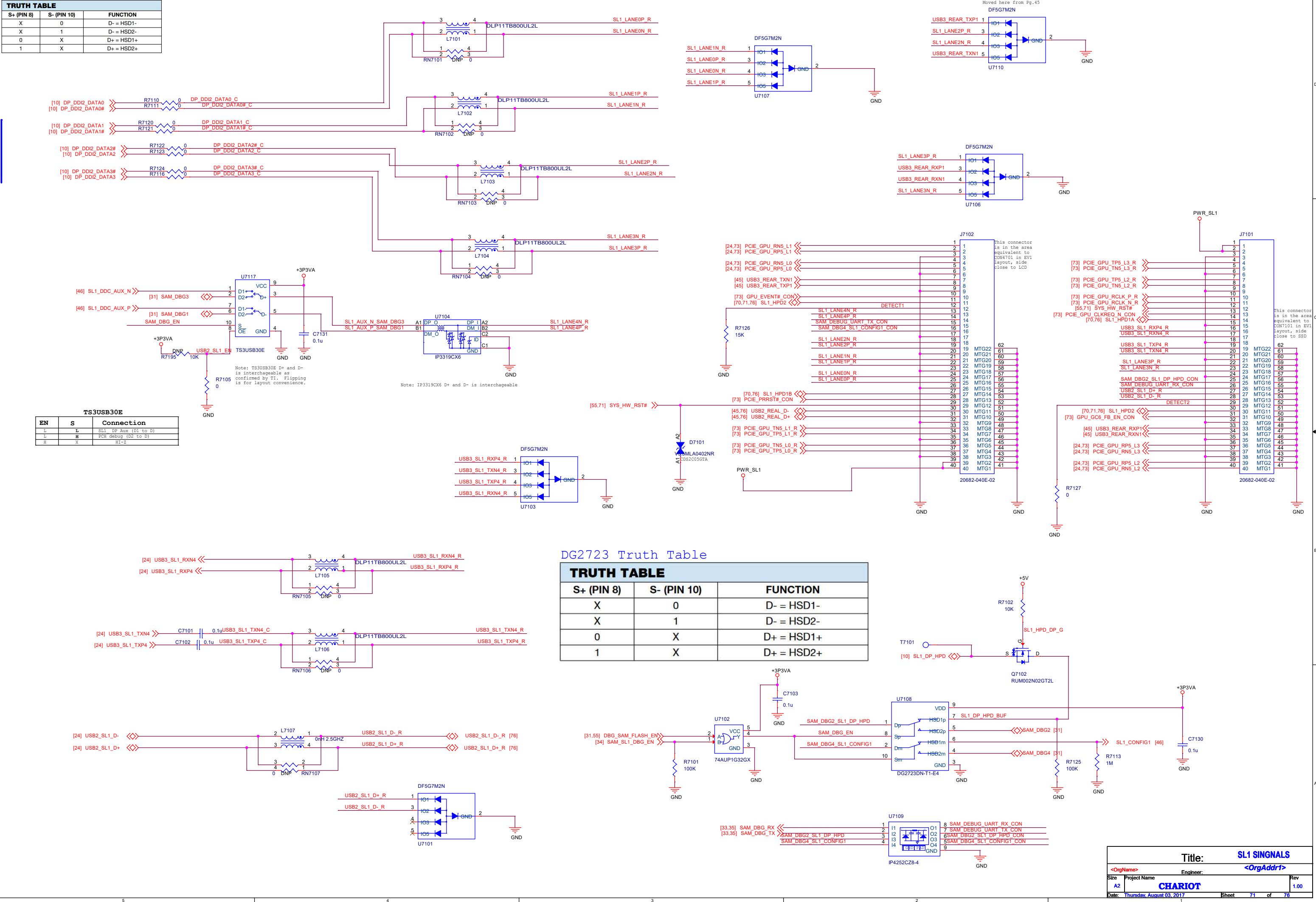
TPS3700 (Voltage Comparator)		
INA+	<400mV	OUTA=Low
INB+	>400mV	OUTB=Low



18W Battery Connector

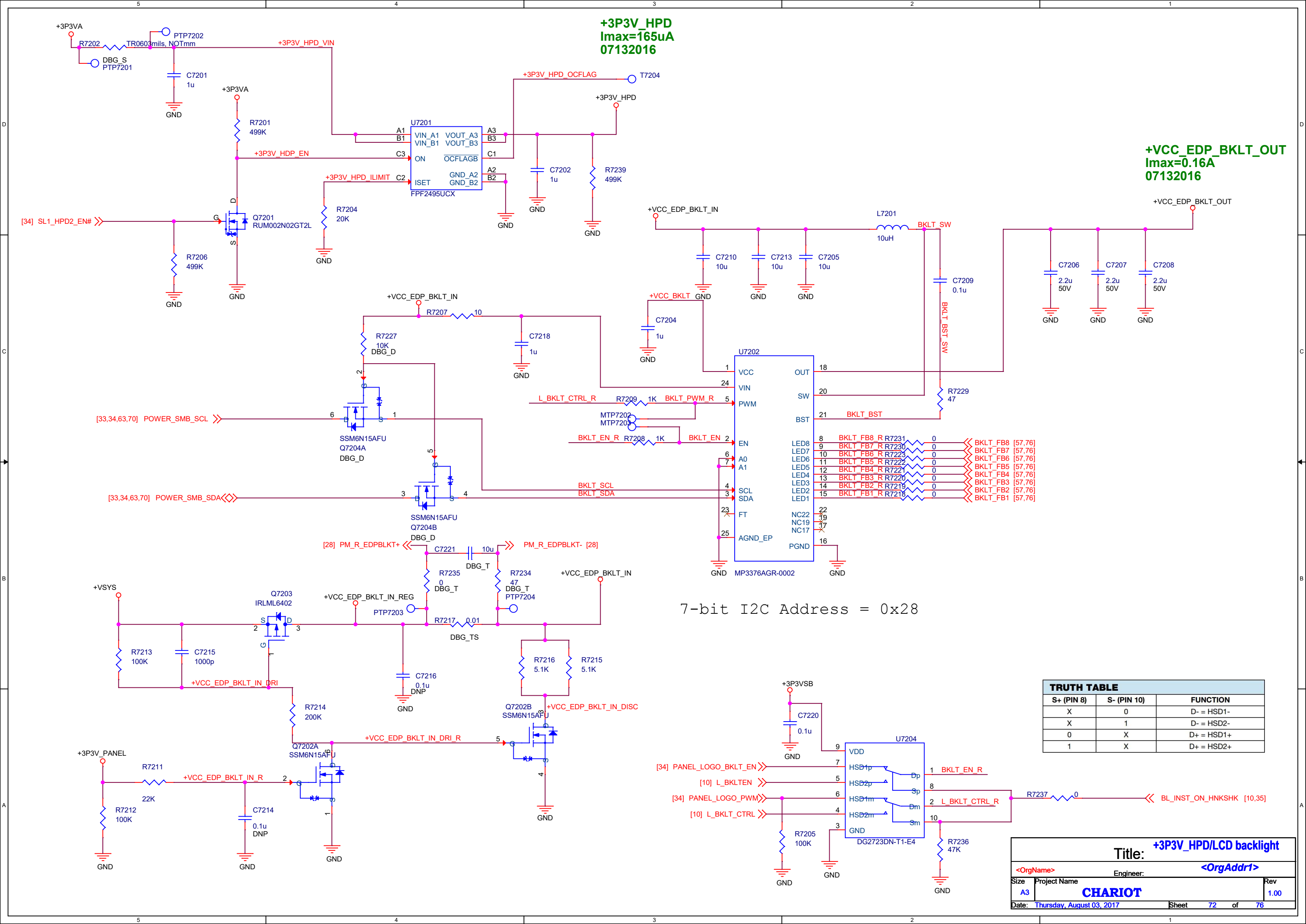


TRUTH TABLE		
S+ (PIN 8)	S- (PIN 10)	FUNCTION
X	0	D- = HSD1-
X	1	D- = HSD2-
0	X	D+ = HSD1+
1	X	D+ = HSD2+



DG2723 Truth Table

TRUTH TABLE		
S+ (PIN 8)	S- (PIN 10)	FUNCTION
X	0	D- = HSD1-
X	1	D- = HSD2-
0	X	D+ = HSD1+
1	X	D+ = HSD2+

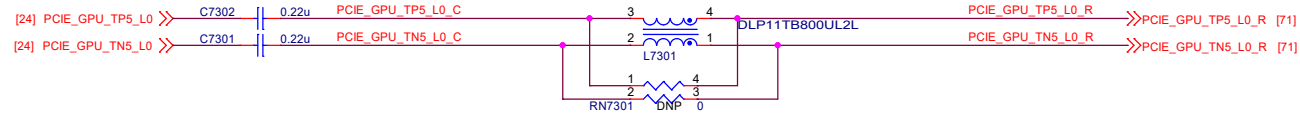


+3P3V_HPDP
I_{max}=165uA
07132016

+VCC_EDP_BKLT_OUT
I_{max}=0.16A
07132016

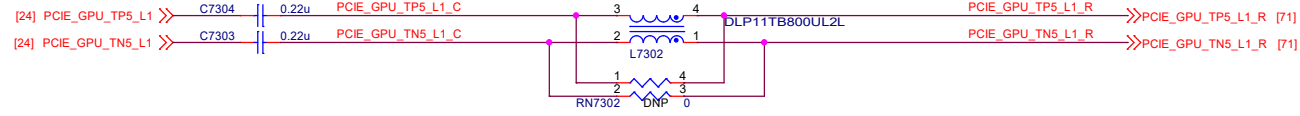
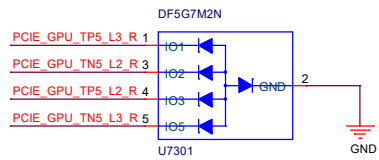
7-bit I2C Address = 0x28

TRUTH TABLE		
S+ (PIN 8)	S- (PIN 10)	FUNCTION
X	0	D- = HSD1-
X	1	D- = HSD2-
0	X	D+ = HSD1+
1	X	D+ = HSD2+



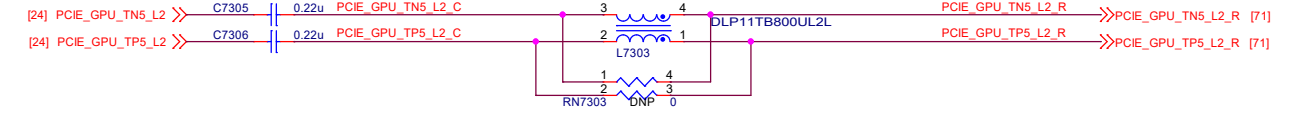
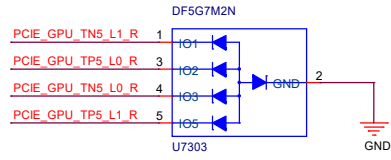
[24,71] PCIE_GPU_RN5_L0 <<

[24,71] PCIE_GPU_RP5_L0 <<



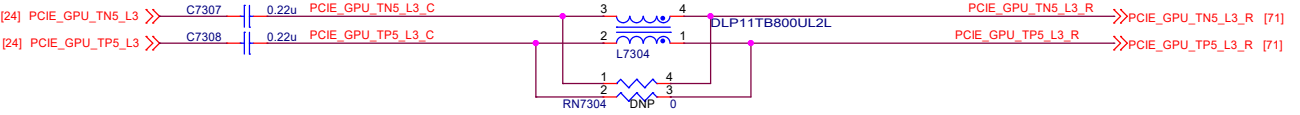
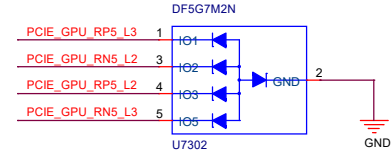
[24,71] PCIE_GPU_RN5_L1 <<

[24,71] PCIE_GPU_RP5_L1 <<



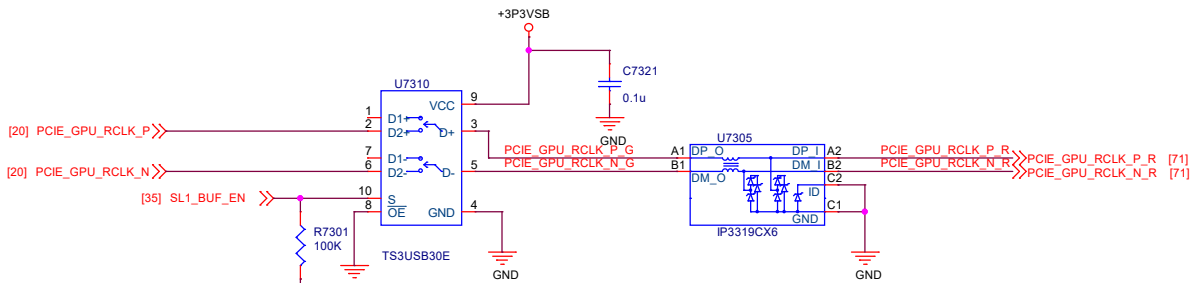
[24,71] PCIE_GPU_RN5_L2 <<

[24,71] PCIE_GPU_RP5_L2 <<

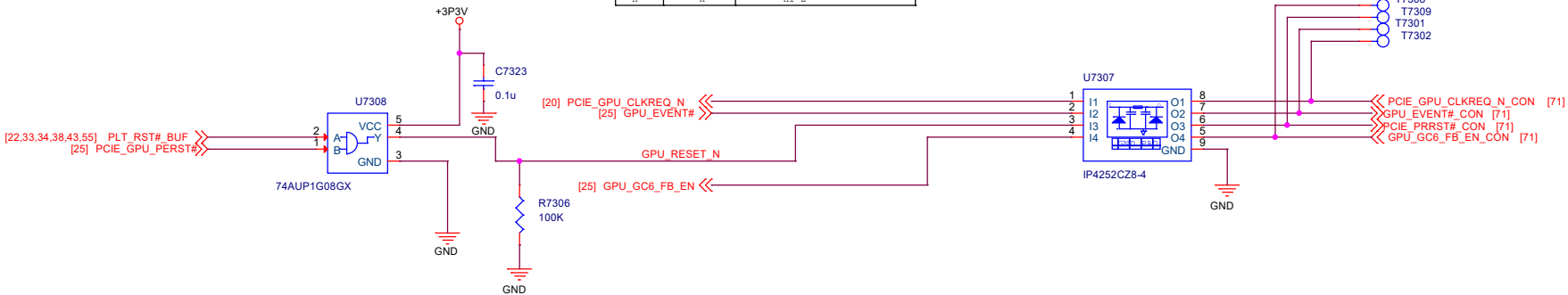


[24,71] PCIE_GPU_RP5_L3 <<

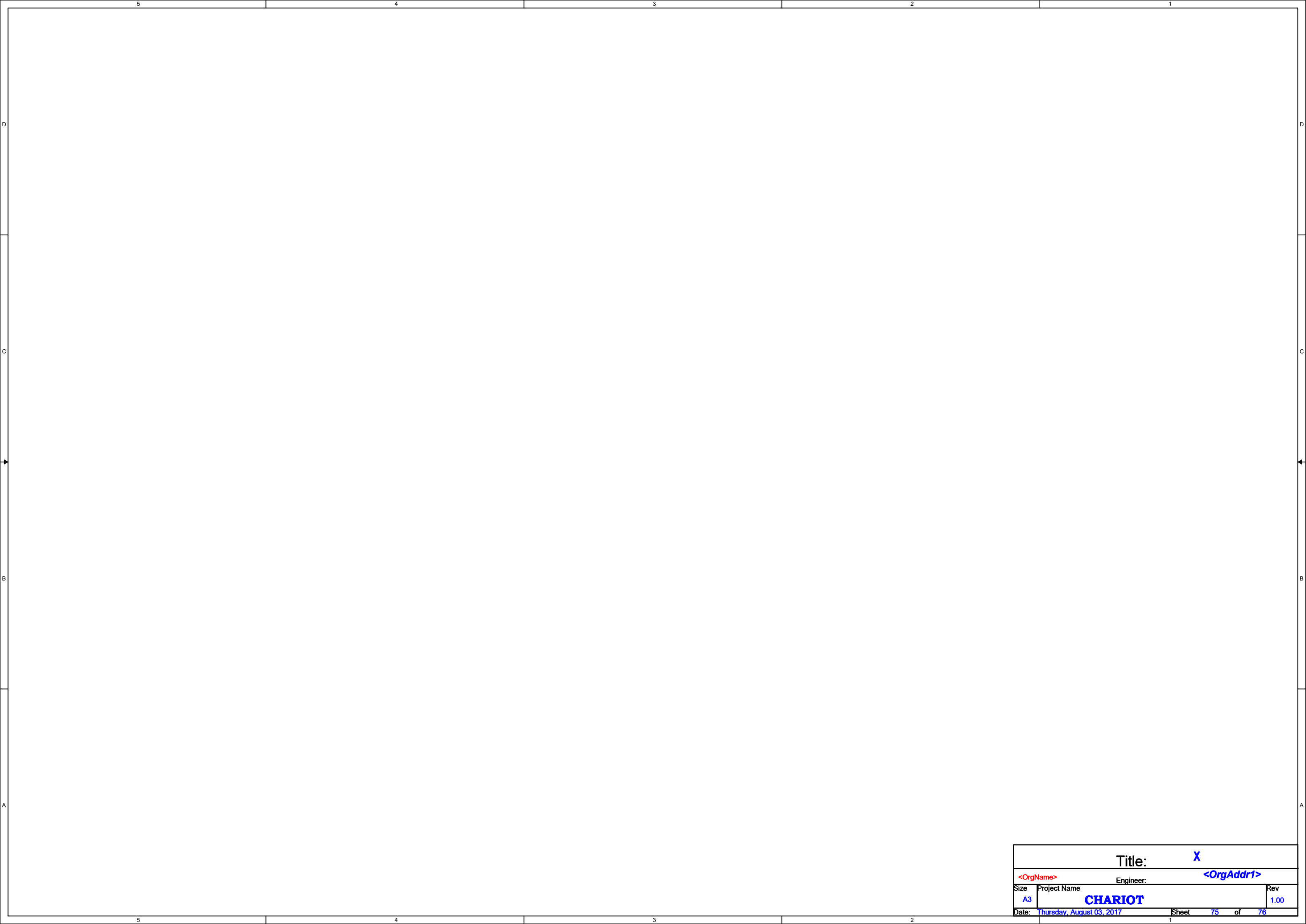
[24,71] PCIE_GPU_RN5_L3 <<



TS3USB30E		
EN	S	Connection
L	L	(D1 to D)
L	H	(D0 to D)
R	X	R1-2



Title: X			
<OrgName>		Engineer: <OrgAddr1>	
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Title: X	
<OrgName> Engineer: <OrgAddr1>	
Size A3	Project Name CHARIOT
Date: Thursday, August 03, 2017	Rev 1.00
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